TI Designs: TIDA-01604

98.6% Efficiency, 6.6-kW Totem-Pole PFC Reference Design for HEV/EV Onboard Charger

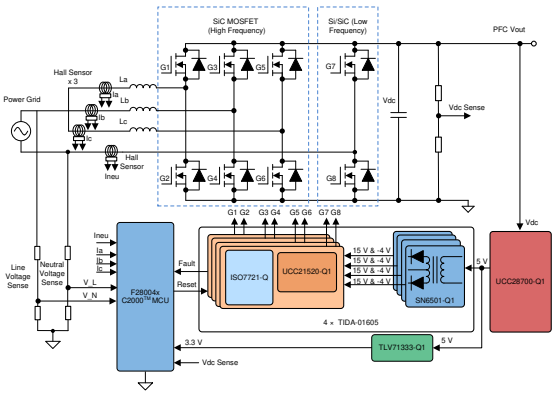
Description

This reference design presents a 6.6-kW totem-pole (TTPL) bridgeless power factor correction (PFC) solution for Onboard Charger. The power stage implements silicon carbide (SiC) MOSFETs driven by a C2000™ microcontroller (MCU) with SiC-isolated gate drivers. The design implements three-phase interleaving and operates in continuous conduction mode (CCM) to achieve a 98.60% efficiency at a 240-V input voltage and 6.6-kW full power. The C2000 controller enables phase shedding and adaptive dead-time control to improve the power factor at light load. The gate driver board (see TIDA-01605) implements reinforced isolation and can withstand more than 100-V/ns common-mode transient immunity (CMTI). The gate driver board also contains the two-level turnoff circuit, which protects the MOSFET from voltage overshoot during the short-circuit scenario.

Resources

TIDA-01604	Design Folder
UCC21520-Q1	Product Folder
TMS320F280049	Product Folder
UCC28700-Q1	Product Folder
TL1963A-Q1	Product Folder
ISO7731-Q1	Product Folder
C2000WARE-DIGITALPOWER-SDK	Tool Folder

ASK Our E2E™ Experts

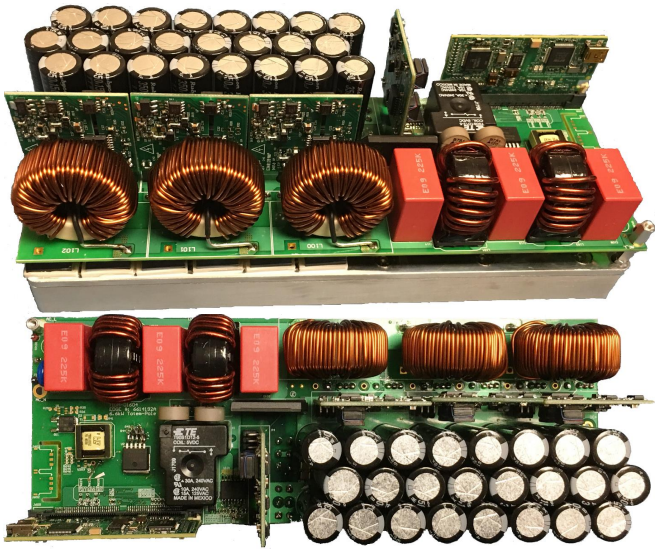


Features

- High-power-density, high-efficiency PFC design to power systems up to 6.6 kW
- SiC MOSFETs with TI drivers offers higher integration for customers
- Half-bridge- and compact isolated gate driver with reinforced isolation and two-level turnoff protection
- Full digital control with high-performance C2000™ controller to enable advanced control scheme
- 98.86% peak efficiency, greater than 0.99 power factor and less than 2% total harmonic distortion (THD)
- Three-phase interleaved operation with phase shedding control
- Programmable output voltage of 400 V to 600 V

Applications

- HEV/EV Traction Inverter
- HEV/EV Onboard Charger
- Electronic Control Units
- HEV/EV DC/DC Converters



1 System Description

WARNING

Do not leave the device powered when unattended.

High voltage! There are accessible high voltages present on the board. Electric shock is possible. The board operates at voltages and currents that may cause shock, fire, or injury if not properly handled. Use the equipment with necessary caution and appropriate safeguards to avoid injury or damage to property. For safety, use of isolated equipment with overvoltage and overcurrent is highly recommended. TI considers it the user's responsibility to confirm that the voltages and isolation requirements are identified and understood before energizing the board or simulation. When energized, do not touch the design or components connected to the design.

Hot surface! Contact may cause burns. Do not touch! Some components may reach high temperatures > 55°C when the board is powered on. The user must not touch the board at any point during operation or immediately after operating, as high temperatures may be present.

1.1 Benefits of Totem-Pole Bridgeless PFC

All plug-in hybrid electric vehicles (PHEVs) require an onboard charger (OBC) between the power grid and the high-voltage battery pack located inside the vehicle. Implementing a power factor correction (PFC) converter is mandatory to connect directly to the power grid for AC/DC power conversion and maximize the real power that flows to the downstream DC/DC converters.

Conventional PFC converters implement a passive diode bridge for rectification, which is now known as a passive PFC technique. The advantages of such a scheme are: simple design, reliability, slow-system control loop, and low cost. However, the disadvantages are also very obvious: the passive components are heavy with a low-power factor and generate significant power losses, which results in bulky heat sinks and a lot of heat dissipation. Further investigation into the matter shows that an input bridge consumes approximately 2% of the input power at the low line of a wide mains application. If the designer can suppress one of the series diodes, then they can save 1% of the input power, which allows the efficiency to rise from 94% to 95% (Turchi; Dalal; Wang; Lenck 2014). Due to previously-mentioned drawbacks, the power rating of bridged traditional PFCs is limited under hundreds of watts, especially in a hybrid-electric vehicle (HEV) or electric vehicle (EV) where reduced space and weight are the key design parameters.

As a result, the trend continues to move toward a bridgeless architecture with the elimination of the traditional diode bridge. The OBC is based on a silicon power device and has limitations such as low efficiency, low power density, and high weight. With the advantages of the SiC MOSFET, the designer can greatly improve these limitations by utilizing the superior performance of fast switching, low reverse recovery charge, and a low $R_{DS(ON)}$.

Figure 1 shows the basic structure of the totem-pole bridgeless PFC boost rectifier. The component consists of a boost inductor, two high-frequency boost SiC switches (SiC_1 and SiC_2), and two components for conducting current at the line frequency. The line frequency components can be two slow diodes, as Figure 1 shows. Side (A) shows two silicon MOSFETs (Si_1 and Si_2). Side (B) shows that the use of Si_1 and Si_2 further increases the efficiency.

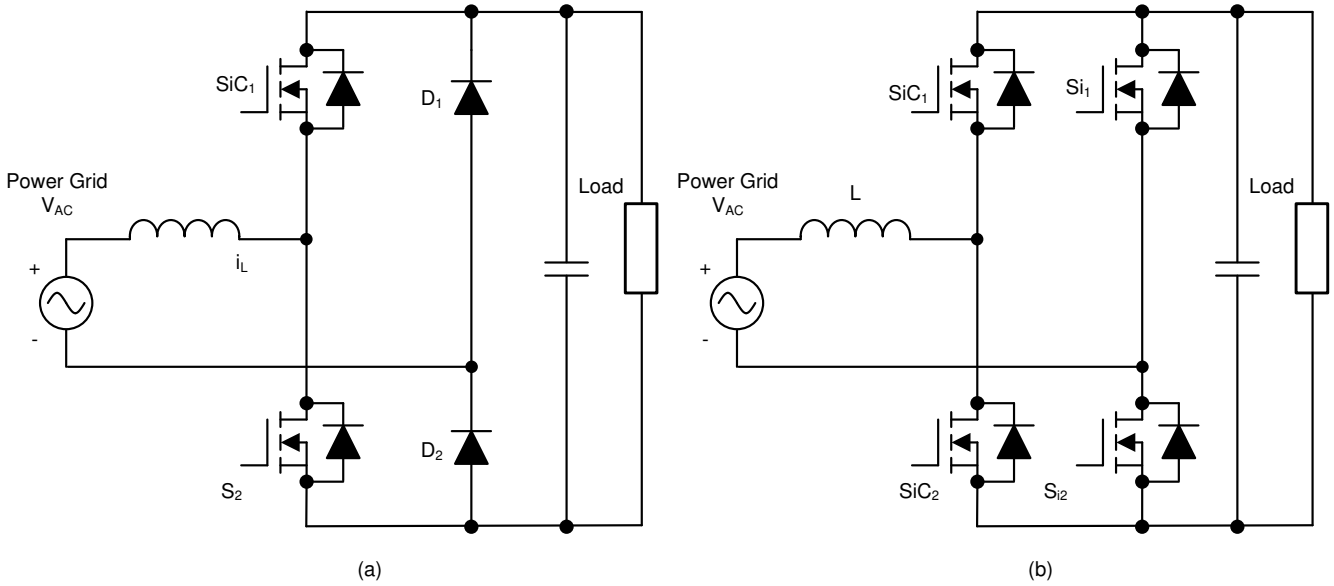


Figure 1. Totem-Pole Bridgeless PFC Boost Converter Topology: (A) Diode for Line Rectification (B) MOSFET for Line Rectification

The inherent issue in the totem-pole PFC is the operation mode transition at the AC voltage zero-crossing. When the AC input changes from the positive half line to the negative half line at the zero-crossing, the duty ratio of the low-side high-frequency switch SiC_2 changes from 100% to 0%, and the duty cycle of SiC_1 changes from 0% to 100%. Because of the slow reverse recovery of the high-side diode (or body diode of the MOSFET), the voltage at the cathode of D_2 cannot jump from ground to DC+ voltage instantly (this causes a large current spike). Because of this issue, the designer cannot use an Si MOSFET in a continuous-conduction mode (CCM) totem-pole PFC. Therefore SiC_1 and SiC_2 must be either SiC MOSFET or gallium nitride (GaN) field-effect transistors (FETs), which have a low reverse recovery.

The biggest advantage of the totem-pole PFC is the reduced power losses in the conduction path. Table 1 shows the device comparison between a conventional PFC and a totem-pole PFC.

Table 1. Device Comparison of Conventional Bridged PFC and Totem-Pole Bridgeless PFC

PARAMETER	LOW-FREQUENCY DIODES	HIGH-FREQUENCY DIODES	HIGH-FREQUENCY SWITCHES	CONDUCTION PATHS
Conventional bridged PFC	Four	One	One	Two low-speed diodes + one switch or (two low-speed diodes + one high-speed diode)
Totem-pole bridgeless PFC	Two	Zero	Two	One high-speed SiC switch + one low-speed Si (or SiC) MOSFET

The following list summarizes the benefits of the totem-pole PFC:

- Although the conventional PFC boost converter is the most popular topology, its efficiency suffers from the conduction losses of the front-end diode bridge rectifier and it is not bidirectional. A totem-pole PFC is inherently capable of bidirectional operation.
- Bridgeless PFC boost converters greatly reduce the number of diodes, increase the power density, and increase the efficiency.
- This PFC is superior in terms of: high efficiency, small common mode noise, small AC current ripple, small reverse recovery current, and fewer components.
- The low reverse recovery charge of the SiC body diode and the low turnon resistance of the SiC MOSFET make the converter an efficient and cost-effective solution for bidirectional onboard chargers.

1.2 Totem-Pole Bridgeless PFC Operation

The totem-pole PFC operates in the positive and negative cycles of the AC mains input, respectively, and determines the current flow depending on how the high frequency SiC MOSFETs are switched (see Figure 2 and Figure 3, respectively).

The high-frequency SiC MOSFETs together with the inductor create a synchronous mode boost converter. During the positive half cycle, S_2 is the boost switch which is driven with duty cycle D and S_1 is driven with a complementary pulse-width modulation (PWM) signal (1-D). Figure 2 (A) shows the direction in which the current flows. Similarly, during the period when S_2 is switched with 1-D, S_1 is switched with D; Figure 2 (B) shows the direction in which the current flows. Note that, during this cycle, S_{D2} conducts continuously.

During the negative half cycle, the operation is similar except that the role of the high-side- and low-side, high-frequency switches are swapped. Figure 3 shows the direction in which the current flows. Note that, during this cycle, S_{D1} conducts continuously.

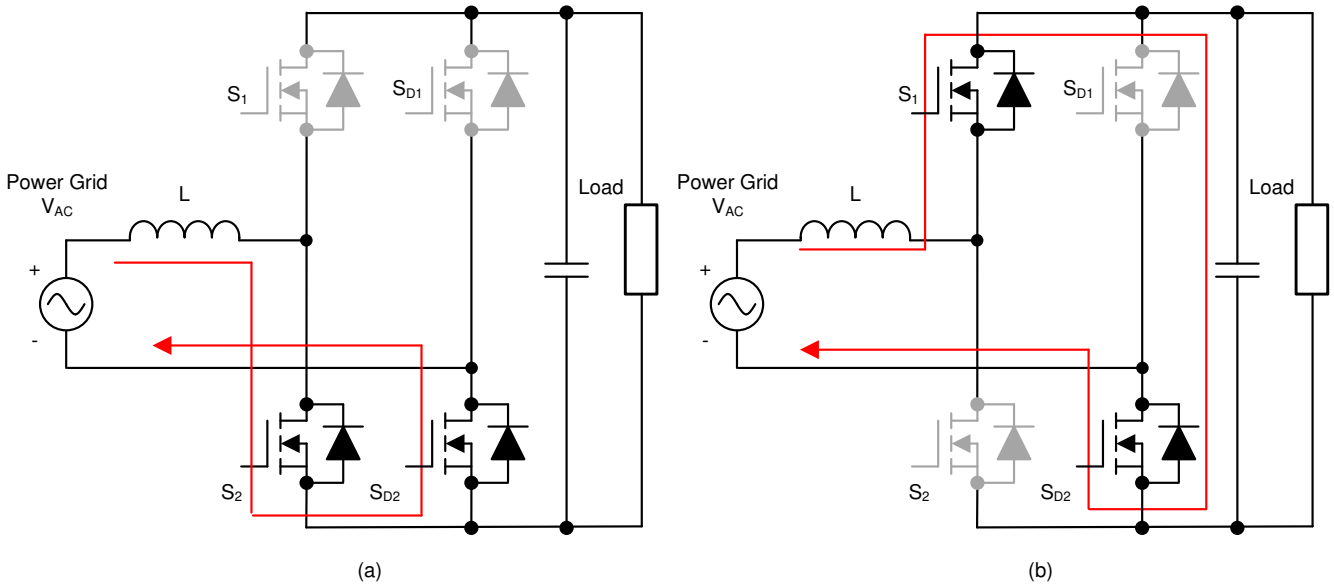


Figure 2. Totem-Pole Bridgeless PFC Operation During Positive Half Cycle: (A) While S_2 is Switched ON (B) While S_2 is Switched OFF

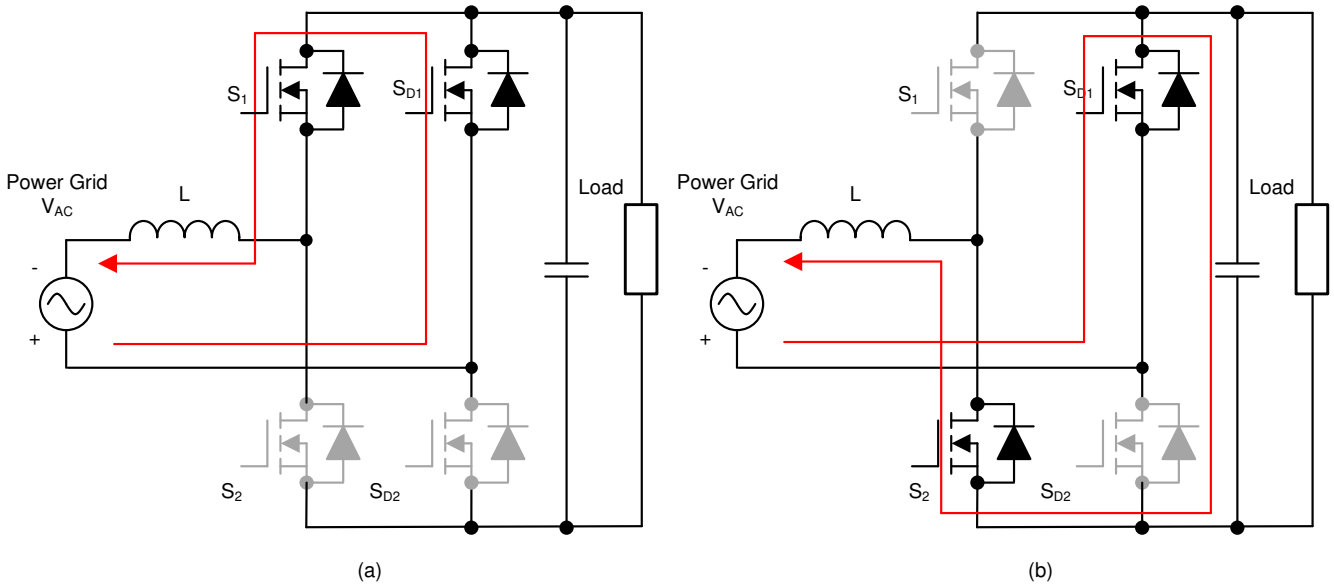


Figure 3. Totem-Pole Bridgeless PFC Operation During Negative Half Cycle: (A) While S_1 is Switched ON (B) While S_1 is Switched OFF

This reference design uses an SiC MOSFET (C3M0065100K from Wolfspeed) and TI's C2000™ Piccolo™ (TMS320F280049) high-performance MCU. The high-frequency SiC MOSFETs operate at a 100-kHz switching frequency and the pair of Si MOSFETs operate at the line frequency (approximately 45 Hz to 60 Hz). Thus the conduction path includes one SiC switch and one low-frequency Si switch with significantly-reduced conduction losses. Use three-channel interleaving to reduce conduction loss and input current ripple. Test results demonstrate a high efficiency above 98.86% and confirm that the advanced features of the controller function, such as phase shedding and adaptive dead-time control.

1.3 Key System Specifications

Table 2 lists the key system specifications of this design.

Table 2. TIDA-01604 Key System Specifications

PARAMETER	SPECIFICATIONS
Input	• Single phase • Voltage: ≈ 85-V AC_{RMS} to 265-V AC_{RMS} • AC line frequency range: 47 Hz to 63 Hz • Input current: 32 A_{RMS_MAX} at 240 V, 32 A_{RMS_MAX} at 120 V • Power factor: ≥ 0.99 • Power line harmonics: < 2% at 240-V AC, full load
Output	• PFC output: ≈ 400 V to 600 V (adjustable) • Output power: 6.6 kW at ≈ 400 V to 600 V • Output capacitance: 900 µF • Output ripple: < 65 V • Peak efficiency: 98.86%
Performance	• PFC stage for high-voltage li-ion battery OBC • Switching frequency: 100 kHz • Isolation: Reinforced • Input AC sensing • PFC output voltage sensing
Protection	• Overtemperature: > 75℃, stop work, and restores to work when < 75℃ • Short-circuit protection • Overcurrent protection • Undervoltage protection at 80-V AC • Overvoltage protection at 265-V AC
Working environment	• Ambient temperature: ≈ –40℃ to +85℃

2 System Overview

2.1 Block Diagram

Figure 4 shows the system block diagram of the TIDA-01604 reference design, which includes the following elements.

- Power switches G1-G6 are high-frequency SiC MOSFETs, for which there is a 120° phase shift between each two half bridge legs. G7 and G8 forms a low-frequency (45- to 60-Hz) synchronous rectifier bridge which virtually has no switching loss; a low conduction loss feature is desirable for these two devices.
- TMS320F280049M C2000 Piccolo controller functions as the controller, which has all the voltage and current sensor inputs and generates the correct PWM signals for G1-G8. The controller also reads any fault signal from the gate driver boards and shuts down the system if a fault occurs. The reset function is used during start-up or when a fault clears.
- TIDA-01605 daughterboards are used to drive SiC switches G1-G8. The driver board is based on isolated, dual-channel gate driver devices, features reinforced isolation, and provides more than 100 V/ns CMTI. The driver board provides the two-level turnoff protection during the short-circuit scenario.
- Hall sensors are used to sense the total input current and current for each channel. Voltage dividers are used to sense the input line and neutral voltages as well as output DC bus voltages.
- The SN6501-Q1-based push-pull isolated converter provides +15 V/–4 V for each gate driver. The TLV71333-Q1 low-dropout (LDO) linear regulator provides accurate reference for the sensing circuits connected to the controller.

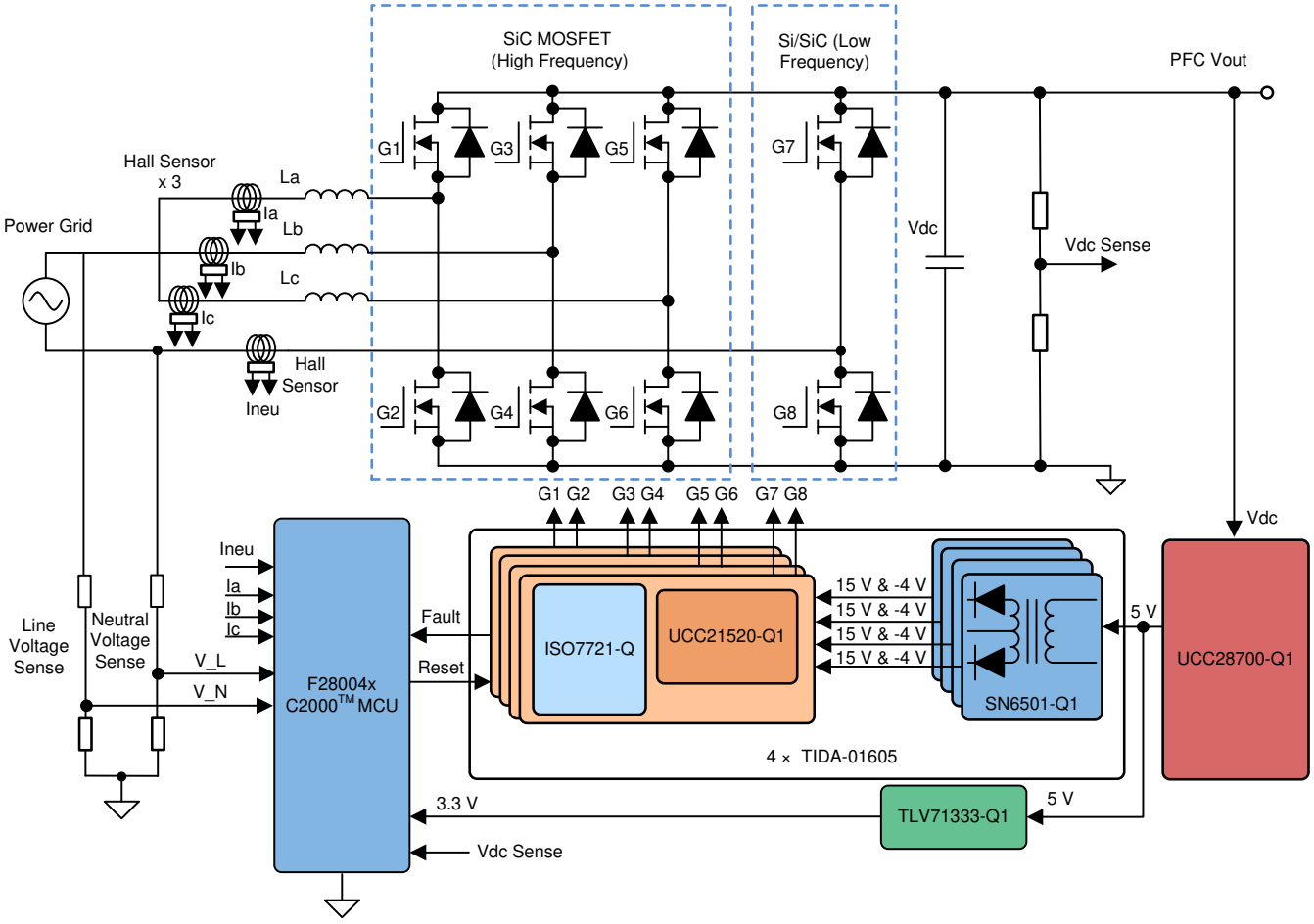


Figure 4. TIDA-01604 Block Diagram

2.2 Highlighted Products

2.2.1 UCC21520-Q1

The UCC221520-Q1 is an automotive-grade, isolated dual-channel gate driver with 4-A source and 6-A sink peak current capability. It is designed to drive power MOSFETs, insulated-gate bipolar transistors (IGBTs), and SiC MOSFETs. Its input side is isolated from the two output drivers by a 5.7-kV_{RMS} and 8-kV peak-reinforced isolated barrier, with a minimum of 100 V/ns CMTI. The internal functional isolation between the two secondary side drivers allows a working voltage of up to 1.5-kV DC. The gate driver also certified according to VDE, CSA, UL, and CQC various isolation standards. Each driver accepts VDD supply voltages up to 25 V and a wide input VCCI range from 3 V to 18 V. The UCC21520-Q1 also has programmable dead-time (DT) control. A disable pin shuts down both outputs simultaneously when it is set high.

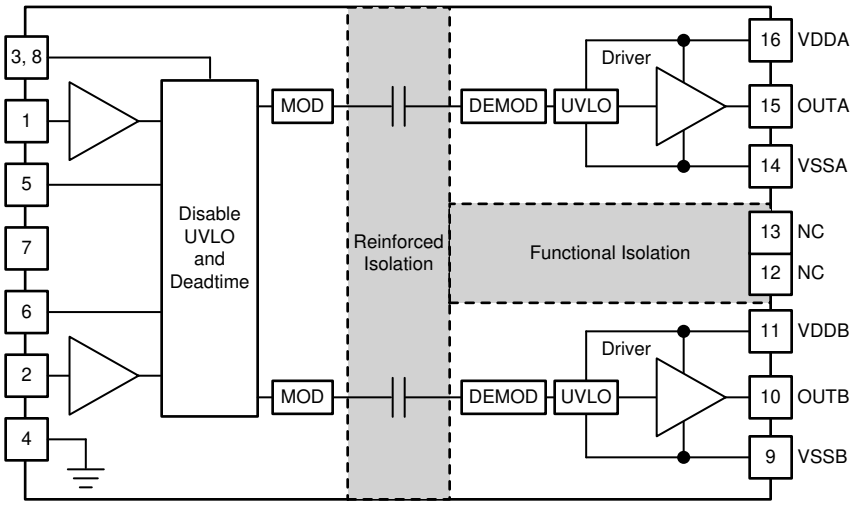


Figure 5. Functional Block Diagram of UCC21520-Q1

2.2.2 UCC28700-Q1

The UCC28700-Q1 of flyback power supply controllers provides constant-voltage (CV) and constant-current (CC) output regulation without the use of an optical coupler. The devices process information from the primary power switch and an auxiliary flyback winding for precise control of output voltage and current. Low start-up current, dynamically controlled operating states, and a tailored modulation profile support very low standby power without sacrificing start-up time or output transient response.

2.2.3 SN6501-Q1

The SN6501-Q1 is a monolithic push-pull transformer driver specifically designed for small factor, isolated power supplies. The device drives a low profile, center-tapped transformer from a 3.3-V or 5-V DC power supply. The SN6501-Q1 consists of an oscillator followed by a gate drive circuit that provides the complementary output signals with a 50% duty cycle to drive the ground referenced N-channel power switches. The device includes two 500-mA peak MOSFET switches at 5-V input voltage to ensure proper start-up under heavy loads.

2.2.4 ISO7731-Q1

The ISO7731-Q1 is a triple-channel digital isolator with 5kV RMS isolation voltage. The device implements reinforced isolation which is certified according to VDE, CSA, UL and CQC standards. The ISO7221-Q1 has an ON-OFF keying modulation scheme to transmit the digital data across a silicon-dioxide-based isolation barrier. The device has a low propagation delay of 11ns typical, and a high CMTI of 100 V/ns. The transmitter sends a high frequency carrier across the barrier to represent one digital state and sends no signal to represent the other digital state.

2.2.5 LMV762Q-Q1

The LMV762Q-Q1 is a precision comparator intended for applications requiring low noise and low input offset voltage. The device includes dual comparators in one package and features a CMOS input and push-pull output stage. The LMV762Q-Q1 is designed to meet the demands of small-size, low-power, and high-performance applications. The input offset voltage has a typical value of 200 µV at room temperature and a 1mV limit over temperature.

2.2.6 TPS7B6950-Q1

The TPS7B6950-Q1 is a low dropout linear regulator designed for up to 40-V operations. It has typical 15 µA quiescent current at light load. The device is suitable for standby micro control-unit systems especially in automotive applications. TPS7B6950-Q1 features a thermal shutdown and an integrated short-circuit and overcurrent protection. The device has an output current capability of 150 mA and offers fixed output voltage options.

2.2.7 TL431-Q1

The TL431-Q1 is a three-pin adjustable shunt regulator with specified thermal stability over applicable automotive temperature ranges. The TL431-Q1 can be used as a single-voltage reference, error amplifier, voltage clamp, or comparator with integrated reference. The TL431-Q1 consists of an internal reference and amplifier that outputs a sink current based on the difference between the reference pin and the virtual internal pin. The sink current is produced by the internal Darlington pair, which allows this device to sink a maximum current of 100 mA.

2.2.8 TLV71333-Q1

The TLV71333-Q1 is a low quiescent current LDO with excellent line and load transient performance and is designed for power-sensitive applications. The TLV71333-Q1 is designed to be stable without an output capacitor, which allows for small solution size. The device also provides inrush current control during device power up and enabling. The TLV71333-Q1 limits the input current to the defined current limit to avoid large currents flowing from the input power source.

2.2.9 OPA2376-Q1

The OPA2376-Q1 is a low noise operational amplifier with e-trim offering outstanding dc precision and ac performance. The device has rail-to-rail output, low offset (25µV maximum), low noise, a maximum quiescent current of 950 µA and a 5.5MHz bandwidth. OPA2376-Q1 is very attractive for a variety of precision and portable applications. All versions are specified for operation from –40°C to +125°C.

2.2.10 C2000™ MCU F28004x

C2000 MCUs are part of an optimized MCU family for real-time control application. A fast and high-quality analog-to-digital controller (ADC) enables accurate measurement of the current and voltage signals, and an integrated comparator subsystem (CMPSS) provides protection for overcurrent and overvoltage without use of any external devices. The optimized central processing unit (CPU) core enables fast execution of control loop. Trigonometric operations are accelerated using the on-chip trigonometric math unit (TMU).

This reference design implements TI's latest TMS320F280049 32-bit Piccolo MCU with 100 MHz of signal processing performance.

2.3 System Design Theory

2.3.1 PWM

Figure 6 shows a simplified diagram of a single phase of the interleaved TTPL PFC topology. To control this rectifier, the duty cycle is controlled to regulate the voltage directly. This regulation is possible if the software variable Duty, or D, is set so that when it is equal to 1, Q3 is always ON, and the setting makes the voltage V_{xiN} equal to the V_{bus} voltage. When Duty is set to 0, Q3 never turns on, and Q4 is always connected to DC bus negative, which makes the voltage go to 0.

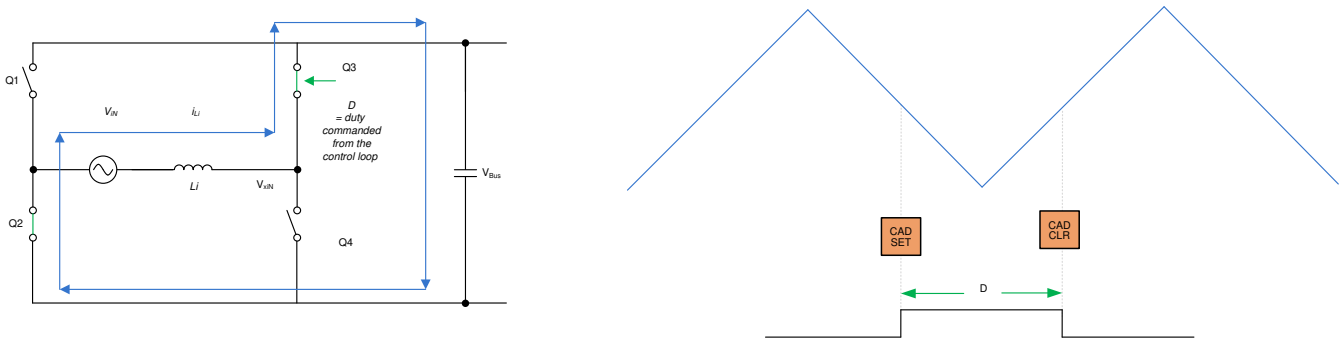


Figure 6. Single-Phase Diagram of TTPL PFC

2.3.2 Current Loop Model

To understand the current loop model, first look at the inductor current closely. In Figure 6, the duty cycle (D) is provided to the PWM modulator, which is connected to the switch Q3 and Q4. From here, Equation 1 is written as:

$$V_{xiN} = D \times V_{bus} \tag{1}$$

NOTE: When D is set to 1, Q3 is on all of the time, and when D is 0, Q3 is off all of the time.

To modulate the current through the inductor, the voltage V_{xiN} is regulated using the duty cycle control of Q3 and Q4 switches. It is assumed that the direction of current is positive in the direction from the AC line into the rectifier and that the grid is fairly stiff when using the DC bus feedforward and the AC voltage feedforward. Figure 7 shows the simplified current loop, and the current loop plant model is written as Equation 2.

$$H_{p\_i} = \frac{i_{Li}^{*}}{D} = \frac{1}{K_{v\_gain}} \times K_{i\_gain} \times G_d \times \frac{1}{Z_i}$$

where,

- K_{v_gain} is the inverse of maximum bus voltage sensed, $\frac{1}{V_{busMaxSense}}$
- K_{i_gain} is the inverse of maximum AC current sensed, $\frac{1}{I_{AC\_MaxSense}}$
- K_{i_fltr} is the response of the RC filter connected from the current sensor to the ADC pin
- G_d is the digital delay associated with the PWM update and digital control is the current command
- i_{Li}^{*} is the current command

(2)

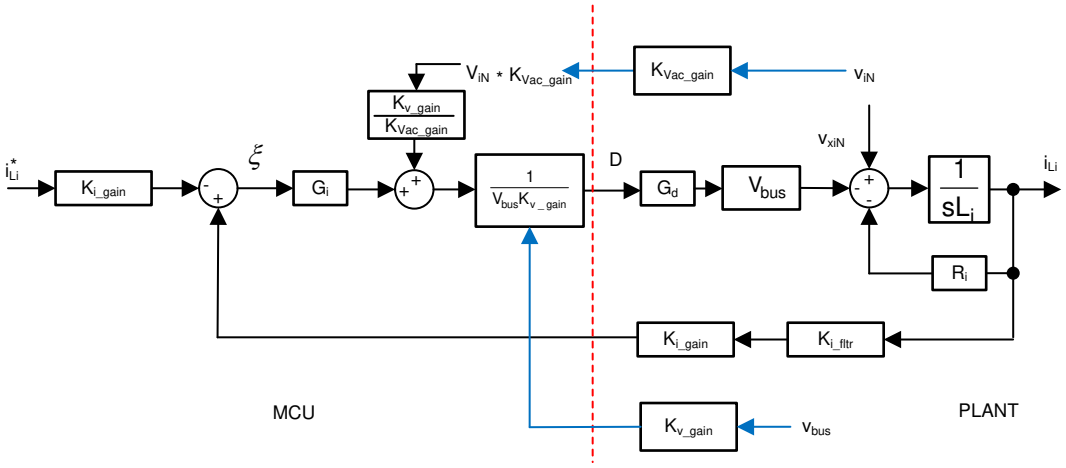


Figure 7. Current Loop Control Model

NOTE: The negative sign on the reference is used because the current loop is thought to be regulating the voltage, V_{xiN}. To increase the current, V_{xiN} must be reduced—hence, the opposite sign for reference and feedback in Figure 7.

This current loop model is then used to design the current compensator. A simple proportional integral controller is used for the current loop.

In the case of three interleaved phases, the current is simply three times more as the same duty cycle is provided to each leg. Hence, the plant model is given as Equation 3.

$$H_{p\_i} = \frac{i^*_{Li}}{D} = 3 \times \frac{1}{K_{v\_gain}} \times K_{i\_gain} \times K_{i\_fltr} \times G_d \times \frac{1}{Z_i} \tag{3}$$

2.3.3 DC Bus Regulation Loop

The DC bus regulation loop is assumed to provide the power reference. The power reference is then divided by the square of the line voltage's RMS to provide the conductance, which is further multiplied by the line voltage giving the instantaneous current command.

Small signal model of the DC bus regulation loop is developed by linearizing Equation 4 around the operating point.

$$i_{DC} v_{bus} = \eta V_{Nrms} i_{Nrms} \rightarrow \hat{i}_{DC} = \eta \frac{\overline{V}_{Nrms}}{\overline{V}_{bus}} i_{Li} \tag{4}$$

For a resistive load, the bus voltage and current are related as shown in Equation 5:

$$\hat{V}_{bus} = \frac{R_L}{1 + sR_L C_o} \hat{i}_{DC} \tag{5}$$

The DC voltage regulation loop control model can be drawn as shown in Figure 8. An additional V_{bus} feedforward is applied to make the control loop independent of the bus voltage. Therefore, the plant model for the bus control can be written as in Equation 6:

$$H_{p\_bus} = H_{load} * \eta * \frac{1}{K_{i\_gain}} * K_{v\_gain} * K_{v\_fltr} * \left(\frac{K_{v\_gain}}{K_{vac\_gain}} \right) \tag{6}$$

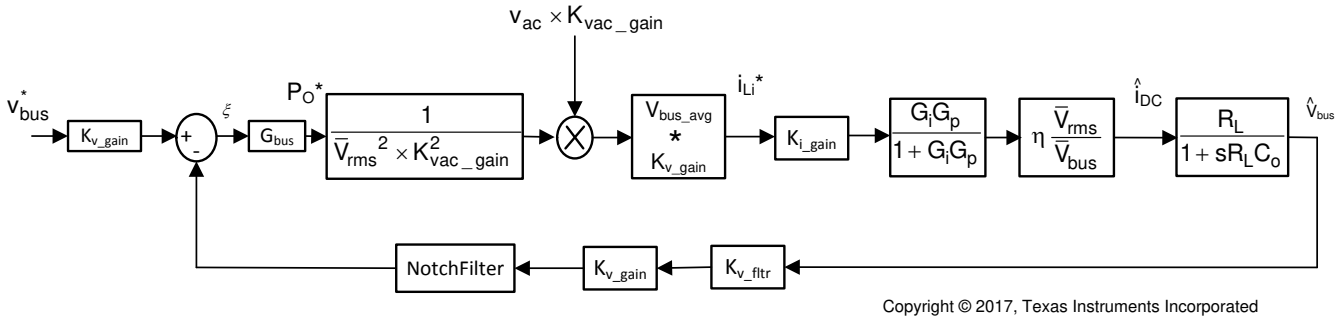


Figure 8. DC Voltage Loop Control Model

Using Figure 8, a proportional integrator (PI) compensator is designed for the voltage loop. The bandwidth of this loop is kept low as it is in conflict with the THD under steady state.

2.3.4 Soft Start Around Zero-Crossing for Eliminating or Reducing Current Spike

Zero-crossing current spikes present a challenging issue for TTPL PFC topologies. This issue is solved by implementing a soft-start scheme with a state machine to turn on and off switches in a particular sequence.

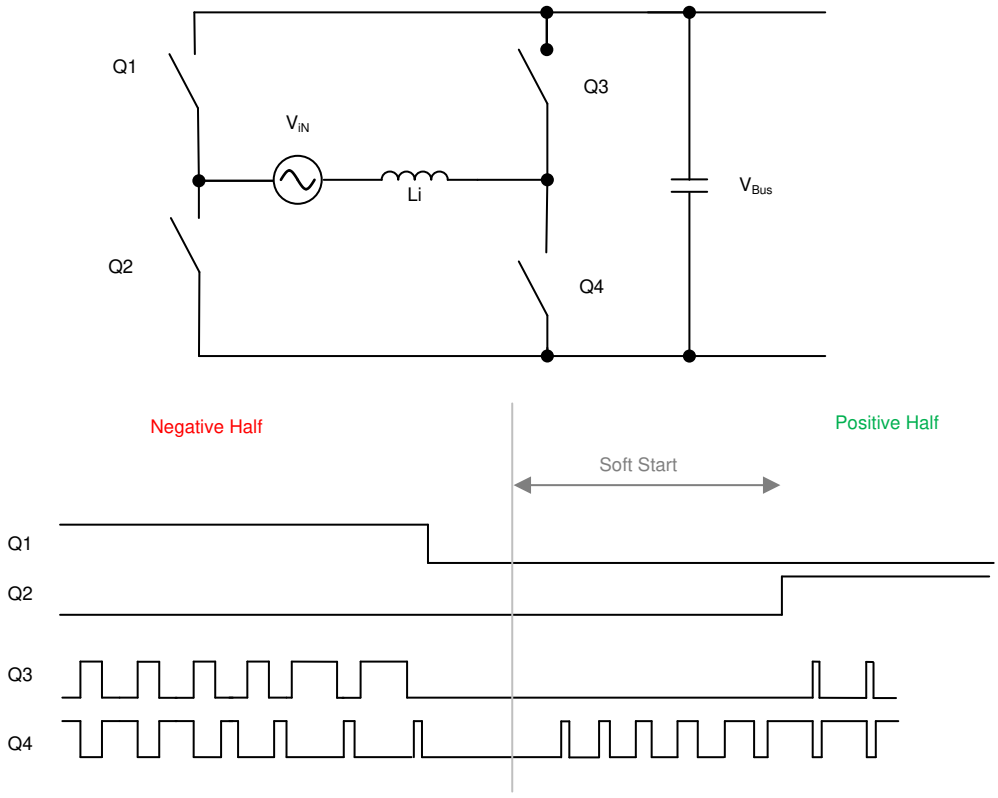


Figure 9. PWM Sequence With Soft Starting to Reduce Current Spike at Zero-Crossing

Figure 9 shows the switching sequence when the AC wave goes from negative to positive. During the negative half, Q1 is ON, Q3 is the active FET, and Q4 is the sync FET. During this time, the voltage across Q2 is the DC bus voltage. When the AC cycle changes, Q2 must be on 100% or close to 100%. If Q2 is turned ON immediately, a substantial positive spike results. Therefore, a soft-start sequence is used to turn Q4 ON as shown in Figure 9. The tuning of this soft start depends on the inductance value and other power stage parameters such as device C_{oss}.

Another reason for a negative current spike around zero-crossing is the relatively low AC voltage around the zero-crossing. When Q3 is turned ON, though the duty cycle is low, a high-voltage difference is applied and can result in a high negative current spike. Therefore, a sufficient delay is applied before Q3 starts switching back again.

Similarly, Q2 is turned on after some delay after the soft start has started.

2.3.5 Current Calculation

Select the input fuse, filter current ratings based on the max input current, which Equation 7 calculates as:

$$I_{inrms} = \frac{P_{out\_max}}{\eta \cdot V_{inrms} \cdot PF} = 28.2\ A \tag{7}$$

where,

- P_{OUT_MAX} is the maximum output power 6.6 kW
- η is the efficiency (assumed as 98.6%)
- V_{IN_RMS} is the input voltage RMS value (240 V)
- PF is the power factor (assumed as 0.99)

2.3.6 Inductor Calculation

The inductor plays important role in affecting system efficiency, current ripple, and overall size. It is always a balance between the efficiency and the power density. The inductance value is calculated based on the input voltage, output voltage, and worst case ripple.

The duty cycle is calculated as:

$$D = 1 - \frac{V_{in}}{V_{out}} \tag{8}$$

Calculation of the current ripple into inductor can be distinguished into three periods:

$$I_{ripple} = \left(\frac{V_{in}}{L} - 2 \times \frac{V_{out} - V_{in}}{L}\right) \times D \times T_s \leftarrow For D \le 1/3 \tag{9}$$

$$I_{ripple} = \left(\frac{2 \times V_{in}}{L} - \frac{V_{out} - V_{in}}{L}\right) \times \left(D - \frac{1}{3}\right) \times T_s \leftarrow For 1/3 < D < 2/3 \tag{10}$$

$$I_{ripple} = \left(\frac{3 \times V_{in}}{L}\right) \times \left(D - \frac{2}{3}\right) \times T_s \leftarrow For D \ge 2/3 \tag{11}$$

In the worst cases, the equation becomes:

$$I_{ripple} = \frac{V_{out} \times T_s}{12 \times L} \tag{12}$$

This design targets at achieving 10% current ripple at maximum input power and maximum AC current:

$$I_{ripple} < 10\% \times \frac{\sqrt{2} \times P_{out\_max}}{V_{in\_max} \times \eta}$$

where,

- Pout_max is the maximum output power
- η is the efficiency
- V_{in_max} is the maximum input voltage (13)

As a result, the inductance is calculated as 126 µH at 12 A RMS current.

2.3.7 Output Capacitor Calculation

Due to the input double-line frequency ripple on the DC link capacitor, its capacitance is mainly determined by the output voltage ripple, as calculated in Equation 14:

$$C_{out(\min)} \ge \frac{P_{out} / V_{out}}{4 \cdot \pi \cdot f_{line\_min} \cdot V_{ripple\_max}} = 860 \mu F \tag{14}$$

where,

- P_{OUT} is the output power
- V_{OUT} is the output voltage

- f_{LINE_MIN} is the minimum line frequency
- V_{RIPPLE} is the output ripple

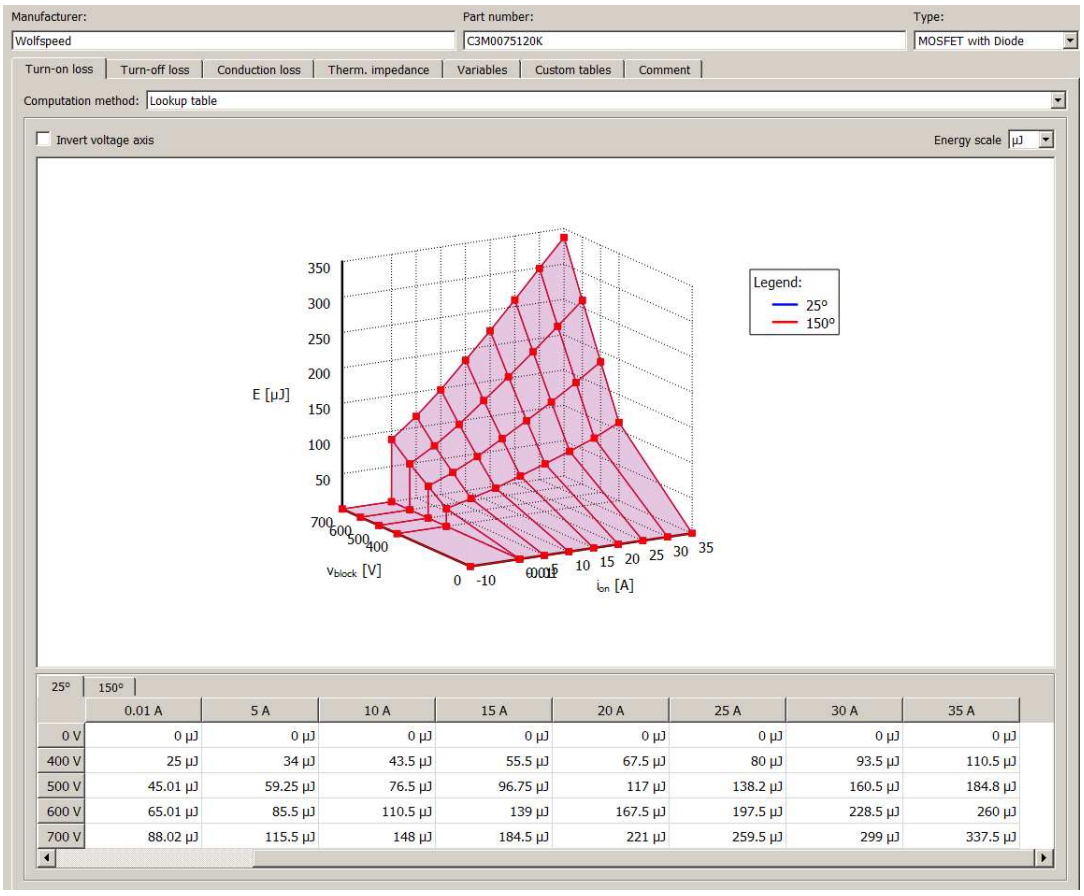
The actual capacitor used is 900 µF.

2.3.8 Selection of SiC MOSFET

The vehicle battery voltage ranges from 250 V to 450 V and the narrow DC gain variance is desired for the charger DC-DC stage, which typically uses a CLLC topology. Therefore, the output DC bus voltage has been selected as 400 V to 600 V for this PFC stage. The maximum DC voltage is 600 V plus approximately 20 V of ripple, which totals to 620 V. A 900-V or 1-kV rated power switch is also required. A 1-kV, 65-mΩ SiC MOSFET (C3M0065100K) has been selected as the high-frequency switching device to account for the reduced switching loss from the TO-247-4 package.

2.3.9 Three-Phase-Interleaved, High-Frequency Bridge Legs

Multi-phase interleaving can both reduce the input current ripple and the conduction loss. To determine how many phases is an optimum solution, use the PLECS® simulation tool PLECS to simulate the power loss of the high-frequency power devices for different options. First, develop a loss model based on the characteristics of the C3M0065100K device, which includes both a conduction loss model and switching loss model over temperature. The second step is to build a full totem-pole PLECS simulation circuit using the previous model, which enables simulating the power device loss. Figure 10 shows the loss model of C3M0065100K.



	0.01 A	5 A	10 A	15 A	20 A	25 A	30 A	35 A
0 V	0 µJ	0 µJ	0 µJ	0 µJ	0 µJ	0 µJ	0 µJ	0 µJ
400 V	25 µJ	34 µJ	43.5 µJ	55.5 µJ	67.5 µJ	80 µJ	93.5 µJ	110.5 µJ
500 V	45.01 µJ	59.25 µJ	76.5 µJ	96.75 µJ	117 µJ	138.2 µJ	160.5 µJ	184.8 µJ
600 V	65.01 µJ	85.5 µJ	110.5 µJ	139 µJ	167.5 µJ	197.5 µJ	228.5 µJ	260 µJ
700 V	88.02 µJ	115.5 µJ	148 µJ	184.5 µJ	221 µJ	259.5 µJ	299 µJ	337.5 µJ

Figure 10. PLECS® Simulation Model for Power Losses

The simulation is performed for three cases: two-phase interleaving, three-phase interleaving, and four-phase interleaving separately. The switching frequencies are chosen as 150 kHz, 100 kHz and 75 kHz. Table 3 summarizes the total C3M0065100K loss for the above three cases with the output DC voltage as 400 V, 500 V and 600 V.

Table 3. Simulated Total Power Loss Among Devices

OUTPUT DC VOLTAGE	400 V	500 V	600 V
Two phases interleaving	55.4 W	66.8 W	78 W
Three phases interleaving	40.2 W	49.5 W	60 W
Four phases interleaving	33.6 W	43.2 W	52.8 W

The use of more phases reduces the total loss, but the difference between three phases and four phases of interleaving is not significant; therefore, a three-phase interleaving design has been selected for as a good compromise between system efficiency and cost.

2.3.10 Auxiliary Power Supply Design

The auxiliary power supply is designed with UCC28700-Q1. It is a flyback power supply controller that provides accurate constant voltage and constant current regulation with primary-side feedback, eliminating the need for opto-coupler feedback circuits. The controller operates in DCM with valley switching to minimize switching losses. The modulation scheme is a combination of frequency and primary peak current modulation to provide high conversation efficiency across the load range.

2.3.10.1 Design Parameters Summary

The design parameters for the auxiliary power supply are shown in Table 4.

Table 4. Specifications of the Auxiliary Power Supply

PARAMETER		MIN	TYP	MAX	UNIT
INPUT					
VIN	Input voltage	120	325	625	VDC
OUTPUT					
V_{OUT}	Output voltage(Non-Isolated)	4.75	5	5.25	VDC
P_{OUT}	Output Power		5		W
	Line Regulation (165V-400VDC)			<2%	
	Load Regulation (10% - 100% load)			<2%	
F_{MAX}	Maximum desired switching frequency			120	kHz
η	Targeted peak efficiency		86%		

2.3.10.2 Transformer Design

The turn ratio of the transformer is determined by the targeted maximum switching frequency at full load, at the minimum input bulk voltage, and the estimated Quasi Resonant (QR) time which is around 2 µs. The resonant switching frequency is estimated as 500 kHz. Hence, the maximum available duty cycle is calculated as:

$$D_{MAX} = 1 - \left(\frac{T_R}{2} \times F_{MAX}\right) - D_{MAGCC} = 0.455 \quad (15)$$

where,

- T_R is the estimated QR resonant period at the switch node
- D_{MAGCC} is the conduction duty cycle of the secondary diode

The turn ratio of the transformer primary winding to the secondary winding is calculated as:

$$N_{PS} = \frac{D_{MAX} \times V_{DC\_min}}{D_{MAGCC} \times (V_{out} + V_F)} = 22.5$$

where,

- V_{DC_min} is the minimum input DC voltage
- V_{out} is the output voltage
- V_F is the secondary diode voltage drop

(16)

N_{PS} is selected as 16, compromising the reflected voltage and transformer size. With this value, the voltage reflected from secondary side to the switch node of the MOSFET is calculated as:

$$V_{ref} = \frac{(V_{out} + V_F)}{N_{PS\_SEL}} = 125V \quad (17)$$

Drain to source voltage stress on the MOSFET needs to conclude the maximum input voltage, the reflected voltage, and the voltage spike induced from parasitic and leakage inductance (V_{LK}):

$$V_{DS} = V_{in\_max} + V_{ref} + V_{LK} = 825V \quad (18)$$

The UCC28700-Q1 controller requires a minimum on time of 300 ns ($T_{ON(min)}$) and minimum secondary rectifier conduction time of 1.1 µs ($T_{DMAG(min)}$) in the high line and minimum load condition. The selection of F_{MAX}, L_P, and R_{CS} affects the minimum $T_{ON(min)}$ and $T_{DMAG(min)}$.

The transformer must be designed such that the saturation current of the winding must be higher than the peak current. The primary peak current of the transformer is calculated as:

$$I_{PP} = \frac{P_{out} \times 2}{\eta \times V_{in\_min} \times D_{max}} = 233mA$$

where,

- P_{out} is the output power
- η is the estimated converter efficiency
- V_{in_min} is the minimum input voltage

(19)

Calculate the primary transformer inductance (L_p) using the standard energy storage equation for flyback transformers. The primary current, maximum switching frequency, output voltage, and transformer power losses are included:

$$L_P = \frac{2 \times (V_{out} + V_F) \times I_{out}}{\eta \times I_{pp}^2 \times F_{max}} = 1.8\ mH \quad (20)$$

The transformer primary RMS current (I_{PRMS}) is calculated as:

$$I_{PRMS} = I_{PP} \times \sqrt{\frac{D_{MAX}}{3}} = 0.098\ A \quad (21)$$

2.3.10.3 Other Parameters

The other parameters of the converter include: rectification diode at the transformer secondary side, output capacitor, capacitor on the VDD pin, VS resistor divider and line compensation resistor.

The selected forward current rating must be larger than the output current. The reverse blocking voltage of the rectification diode is calculated as:

$$V_{db} = \frac{V_{in\_max}}{N_{ps}} + V_{out} + V_F = 45V \quad (22)$$

For this design, the output capacitor (C_{OUT}) was selected to have a 1% ripple of all the outputs with an operating frequency of 120 kHz:

$$C_{out} \geq \frac{I_{out}}{F_{max} \times V_{ripple}} = 166uF \quad (23)$$

The capacitor connected to the VDD pin needs to supply the device operating current until the output of the converter reaches the target minimum operating voltage in CC regulation. The startup resistance (R_{STR}) is selected as 4 MΩ. The startup bias supply current is 1.5 µA, and the turn-on voltage threshold ($V_{DD(on)}$) is 21 V according to the UCC28700-Q1 data sheet.

$$C_{DD} = \left(\frac{V_{in\_min}}{R_{str}} - I_{start}\right) \times \frac{T_{ss}}{V_{DD(on)}} = 2.3\ \mu F$$

where,

- C_{DD} is the minimum required capacitance on the VDD pin
- I_{start} is the startup bias supply current
- T_{ss} is the desired startup time (24)

The VS divider resistors determine the output voltage regulation point of the flyback converter. Also, the high-side divider resistor (R_{S1}) determines the line voltage at which the controller enables continuous DRV operation. R_{S1} is initially determined based on transformer auxiliary-to-primary turns ratio and desired input voltage operating threshold, which is calculated as:

$$R_{S1} = \frac{V_{in\_min}}{N_{PA} \times I_{VSL}} = 86.5\ k\Omega$$

where,

- I_{VSL} is the run-threshold for the current pulled out of the VS pin during the MOSFET on-time = 220 µA according to UCC28700-Q1 data sheet
- N_{PA} is the transformer primary-to-auxiliary turns ratio (25)

The low-side VS pin resistor is selected based on desired VO regulation voltage:

$$R_{S2} = \frac{R_{S1} \times V_{VSR}}{N_{AS} \times (V_{out} + V_F) - V_{VSR}} = 28k\Omega$$

where,

- V_{VSR} is the CV regulating level at the VS input = 4.05 according to UCC28700-Q1 data sheet
- N_{AS} is the transformer auxiliary-to-secondary turns ratio
- V_F is the secondary rectifier diode forward voltage drop at near-zero current (26)

The constant current regulation is achieved by maintaining a maximum DMAG duty cycle of 0.425 at the maximum primary current setting. The transformer turns ratio and the regulating voltage determine the current sense resistor for a target output current. The current sense resistor is calculated as:

$$R_{CS} = \frac{V_{CCR} \times N_{PS}}{2 \times I_{OCC}} \times \eta_{XFMR} = 2.3\ \Omega$$

where,

- V_{CCR} is the CC regulating level given as 0.319 V in the UCC28700-Q1 data sheet
- η_{XFMR} is the estimated efficiency of the transformer (27)

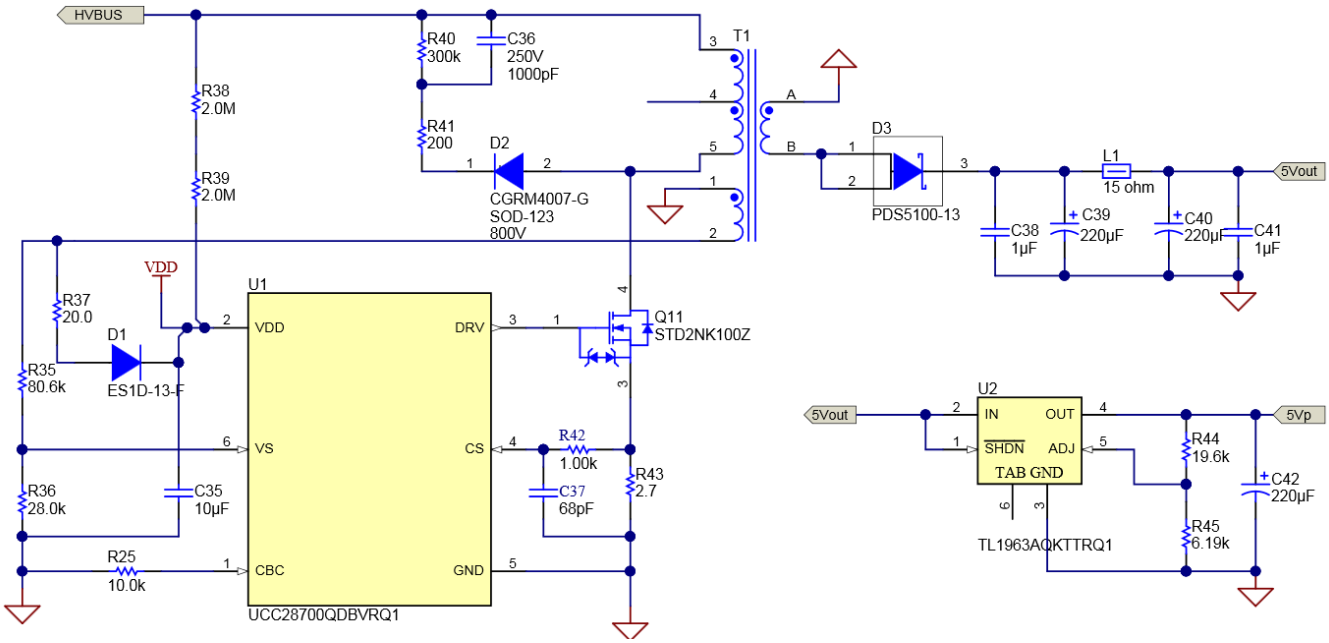


Figure 11. Schematic of the Auxiliary Power Supply

2.3.11 Current and Voltage Sense

The Hall-effect sensor ACS716KLATR-25CB-NL-T is used for the total input current sensing, as Figure 13 shows. The OPA237-based amplifier circuit tunes the low output voltage of the sensor to a higher level and sends this voltage to the controller ADI pin. The ACS722LLCTR-20AB-T device senses the three individual channels for the current which is intended for the balance current control.

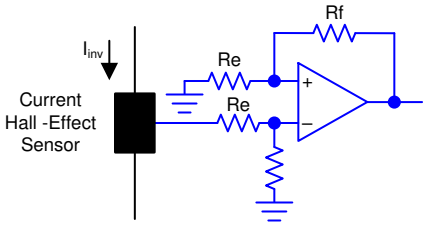


Figure 12. Hall Effector Sensor Signal Conditioning Circuit

The output voltage from the signal conditioning circuit is scaled to match the ADC range using the circuit as shown in Figure 12. The voltage is calculated as:

$$I_{out} = \frac{R_f}{R_e}\left(I_{inv} \times \frac{V_{nominal}}{I_{nominal\_max}} + V_{offset}\right) \quad (28)$$

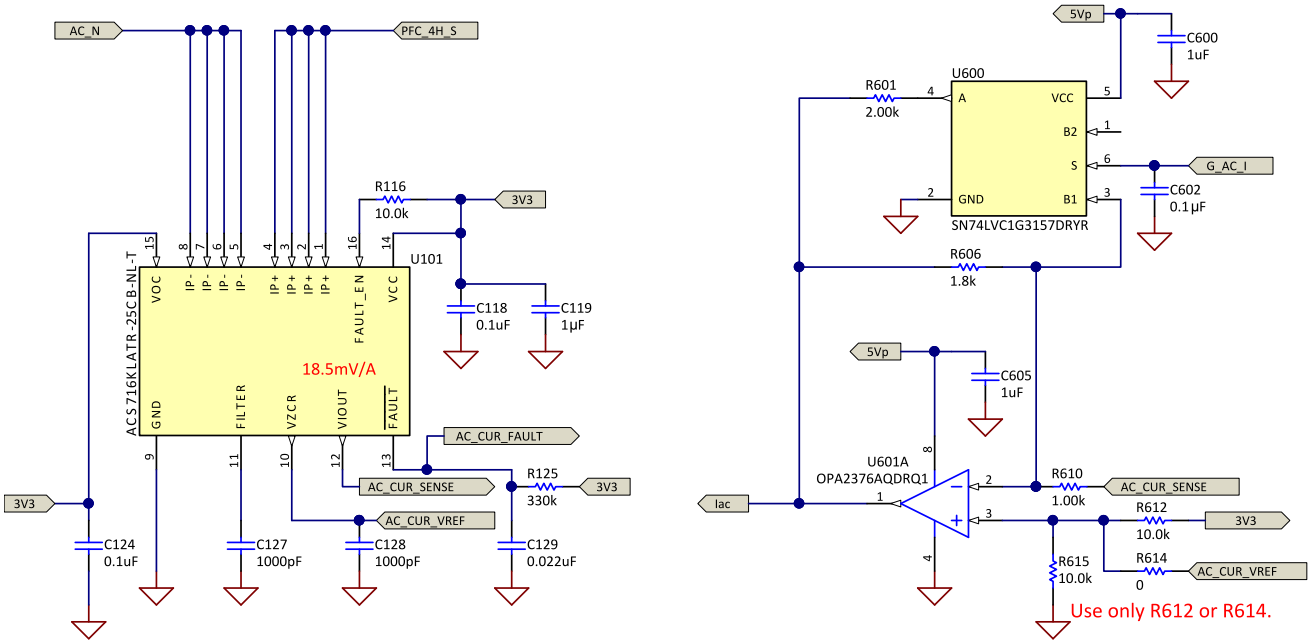


Figure 13. Schematic of Current Sensing

The input AC voltage is sensed differentially by sensing the line, and the neutral inputs refer to the control ground separately with two voltage dividers, as Figure 14 shows. The control ground is the DC link negative terminal; therefore, a single voltage divider can be used to sense the DC bus voltage. An RC filter filters the signals before connecting to the controller. A common RC filter is used for all the sensing signals on this design.

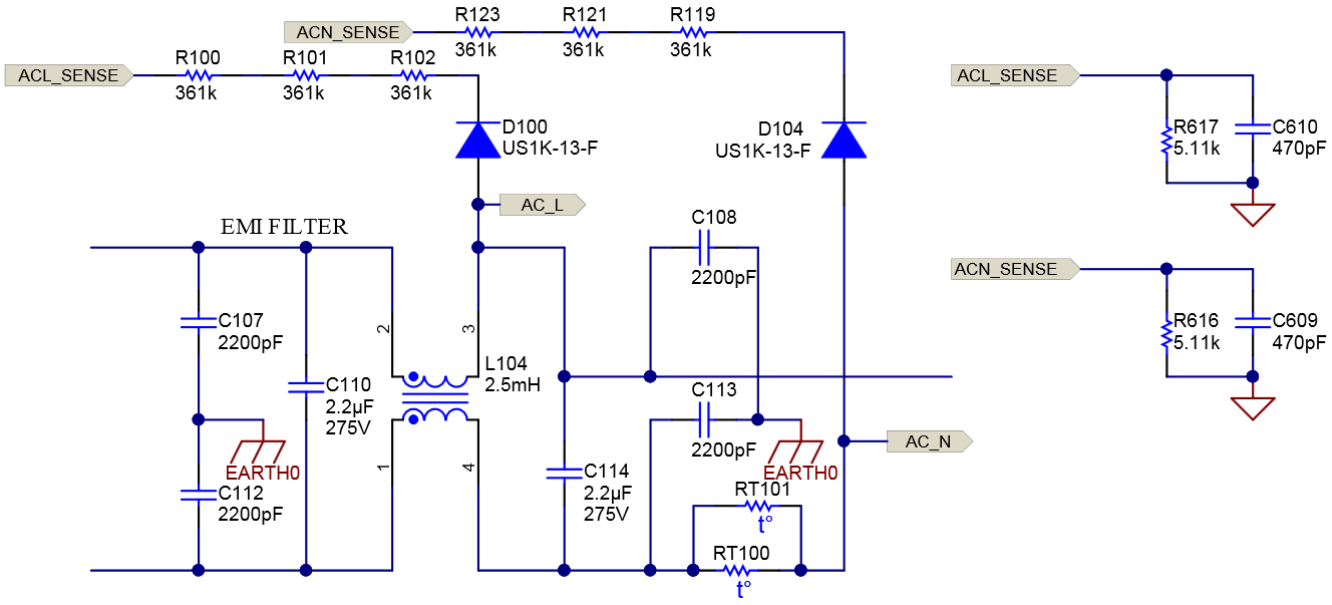


Figure 14. Schematic of Voltage Dividers for AC Input Voltage Sense

2.3.12 Isolated Gate Driver Board

The TIDA-01605 reference design is connected externally as the isolated-gate driver daughtercard. Figure 15 shows the schematic. The TIDA-01605 reference design is an automotive-qualified, isolated-gate driver solution for driving SiC MOSFETs in a half-bridge configuration. The gate driver is capable of delivering a 4-A source and 6-A sink peak current. The design implements reinforced isolation and can withstand 8-kV peak and 5.7-kV_{RMS} isolation voltage and greater than 100 V/ns common-mode transient immunity (CMTI). The reference design contains the two-level turnoff circuit, which protects the MOSFET from voltage overshoot during the short-circuit scenario. The desaturation detection (DESAT) threshold and the delay time for second stage turnoff are configurable. The benefits are summarized as follows:

- Compact, dual-channel gate driver solution for driving SiC MOSFETs in half-bridge configuration
- Confirmed 4-A source and 6-V sink peak current-driving capability suitable for driving SiC MOSFET, Si MOSFET, or IGBT with a switching frequency up to 500 kHz
- Built-in, compact, high-efficiency isolated bias supply with +15-V and –4-V outputs
- Flexible and configurable as dual channel in half bridge, in parallel, dual high side, or dual low side
- Gate driver dead-time control with shoot-through protection ensures safe operation
- Low propagation delay ensures easy control and allows for increased switching frequency
- Discrete two-level turnoff for short-circuit protection with adjustable current limit and delay (blanking) time
- Provides very high CMTI of greater than 100 V/ns and a reinforced isolation of 8-kV peak and 5.7-kV_{RMS} voltages

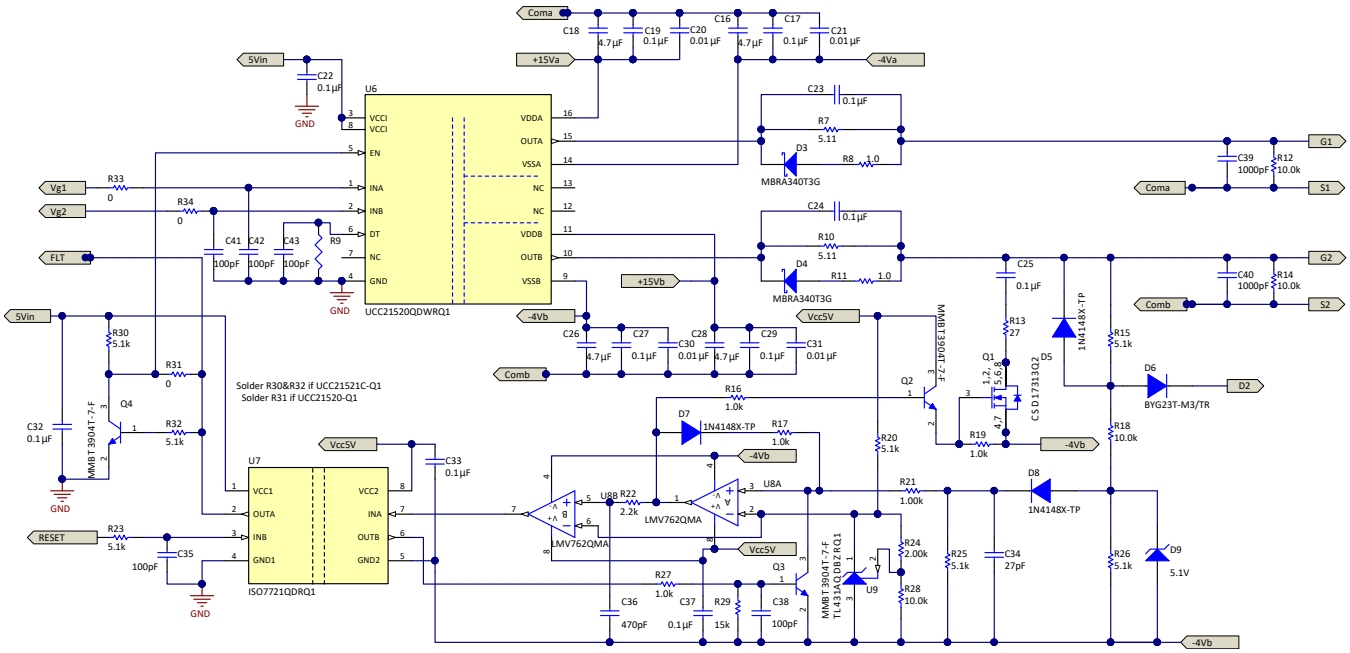


Figure 15. Schematic of SiC Isolated Gate Driver (TIDA-01605 Design)

For details such as design theory, components selection, testing and results, see TIDA-01605: *Automotive Dual-Channel, SiC Gate Driver Reference Design With Two-Level Turn-Off Protection*.

3 Hardware, Testing Requirements, and Test Results

3.1 Hardware

Figure 16 and Figure 17 show the TIDA-01604 prototype from the top view and front view, respectively. The design includes four gate driver daughtercards (see TIDA-01605) and one C2000 controller. The design uses three power inductors for three interleaved channels. The DC link capacitor is formed by twenty-four 350-V, 150-µF capacitors with two in series and twelve groups in parallel. The power devices are under the printed-circuit board (PCB) and mounted on the cold plate.

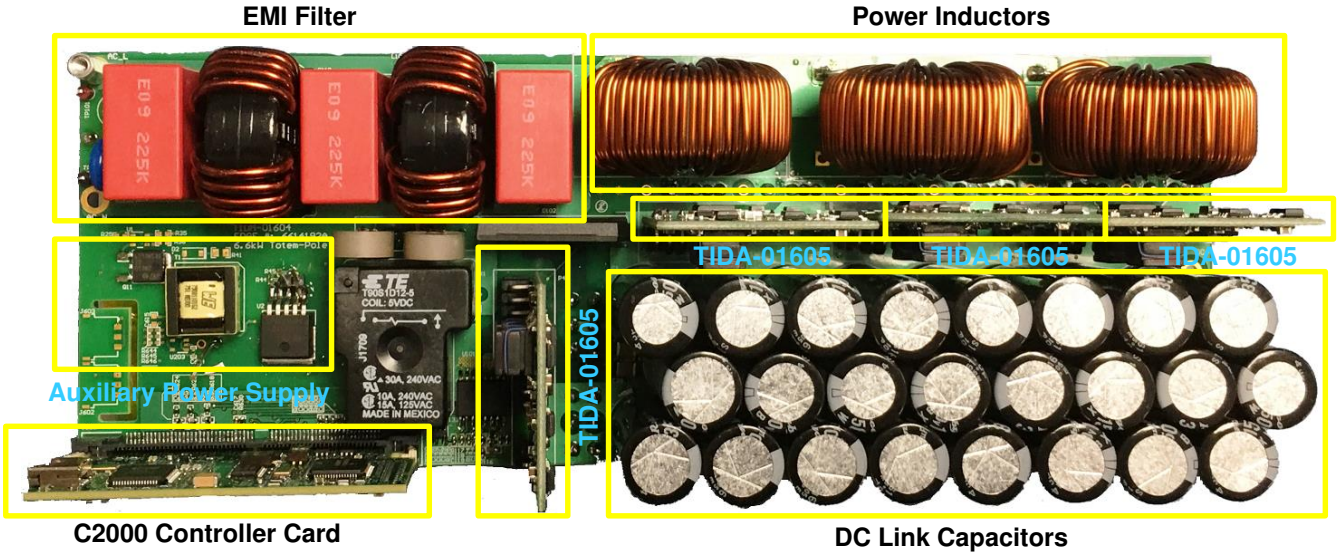


Figure 16. TIDA-01604 PCB Board—Top View

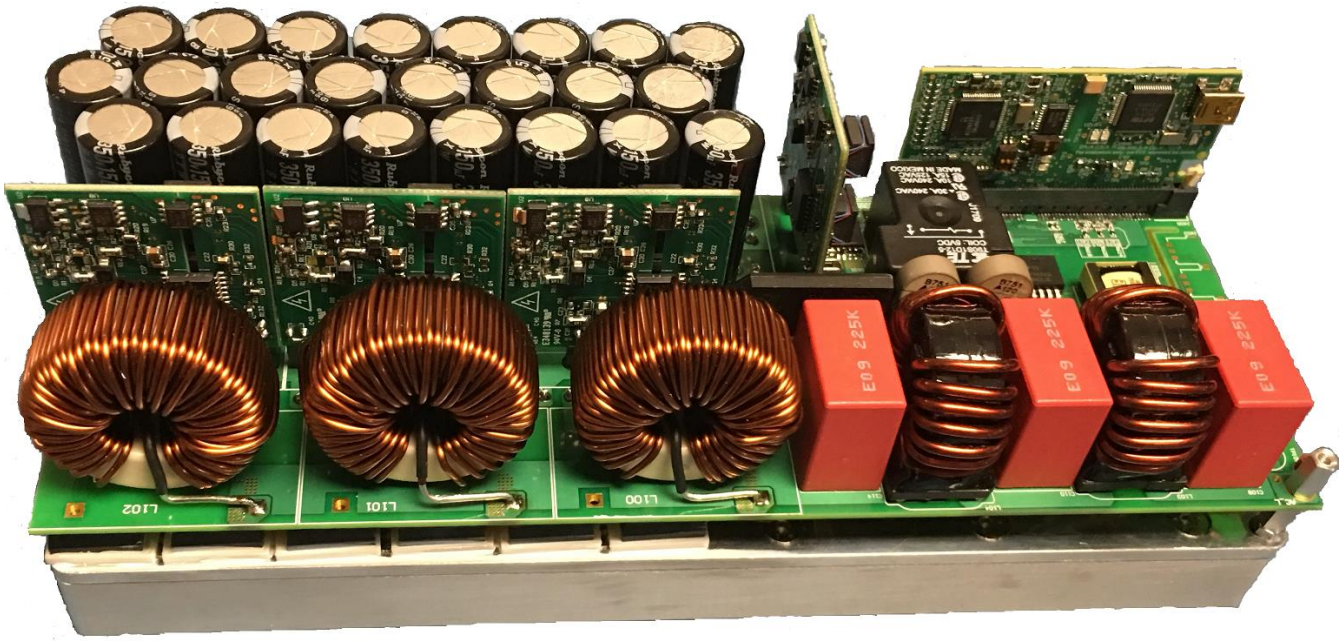


Figure 17. TIDA-01604 PCB Board—Front View

The measurement setup diagram is shown in Figure 20. The C2000 control card is connected to the PC using a USB cable. A programmable AC power supply is connected to the board input. The board output is connected to an electronic load. The current and voltage probes are connected to observe the input current, input voltage, and output voltages:

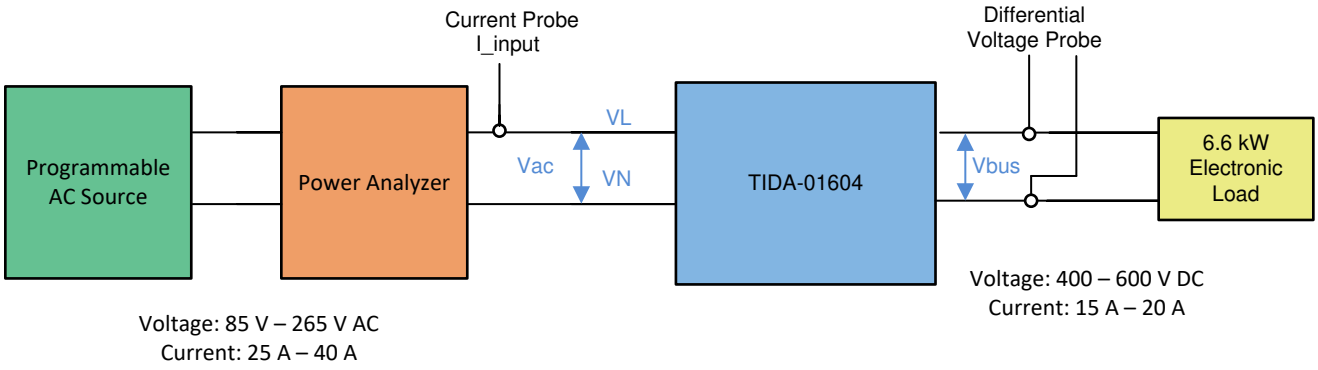


Figure 18. TIDA-01604 Experiment Setup

3.1.1 Control Card Settings

The key controller peripherals used for control of the TIDA-01604 power stage is shown in Table 5.

Table 5. Key Controller Peripherals Used for Control of Power Stage on Board

SIGNAL NAME	HSEC PIN NUMBER	FUNCTION
PWM-1A	49	PWM: low-frequency MOSFET leg, high-side switch
PWM-1B	51	PWM: low-frequency MOSFET leg, low-side switch
PWM-2A	53	PWM: high frequency MOSFET leg, high side switch, phase one
PWM-2B	55	PWM: high-frequency MOSFET leg, low-side switch, phase one
PWM-3A	50	PWM: high-frequency MOSFET leg, high-side switch, phase two
PWM-3B	52	PWM: high-frequency MOSFET leg, low-side switch, phase two
PWM-4A	54	PWM: high-frequency MOSFET leg, high-side switch, phase three
PWM-4B	56	PWM: high-frequency MOSFET leg, low-side switch, phase three
I_{ac}	18	ADC with CMPSS: AC return current measurement
IL1	15	ADC with CMPSS : inductor current measurement Ph1
IL2	21	ADC with CMPSS : inductor current measurement Ph2
IL3	25	ADC with CMPSS : inductor current measurement Ph3
VL	20	ADC: AC voltage line
VN	17	ADC: AC voltage neutral
V_{bus}	24	ADC: bus voltage
In Rush Relay	57	GPIO: used to control the inrush relay
Fault 1	77	GPIO: fault signal phase one
Fault 2	79	GPIO: fault signal phase two
Fault 3	80	GPIO: fault signal phase three
AC Current Sense Gain Change	63	GPIO: controls the gain stage

Certain settings on the device control card are required to communicate over JTAG and use the isolated UART port. A correct ADC reference voltage must also be provided. The following are the required settings for revision A of the F280049 control card. Refer to the info sheet located inside C2000Ware at *<install_path>\c2000ware\boards\controlcards\TMDSCNCD280049* or get it from the Piccolo F280049 controlCARD Information Guide.

1. S1:A on the control card must be set on both ends to “ON (up) ” position to enable JTAG connection to the device and UART connection for SFRA GUI. If this switch is “OFF (down)” the isolated JTAG built in on the control card cannot be used, nor can SFRA GUI communicate to the device.
2. Verify the settings of S5 and S6 on the control card according to the connections listed in Table 5.
3. J1:A is the connector for the USB cable that is used to communicate to the device from a host PC on which Code Composer Studio™ (CCS) runs.
4. A 3.3-V reference is desired for the control loop tuning on this design. Internal reference of the F28004x is used and for this S8 switch must be moved to the left, as in, pointing to VREFHI
5. A capacitor is connected between the isolated grounds on the control card, C26:A. TI recommends removing this capacitor for the best performance of this reference design.

3.2 Software

The software of this design is available inside C2000Ware Digital Power SDK and is supported inside the powerSUITE framework.

3.2.1 Opening Project Inside CCS

Use the following steps to get started:

1. Install CCS from the *Code Composer Studio (CCS) Integrated Development Environment (IDE)* tools folder. Version 9.3 or above is recommended.
2. Open CCS.
3. Install C2000Ware DigitalPower SDK at the *C2000Ware Digital Power SDK* tools folder.
   - PowerSUITE is installed with the SDK in the default install.
4. Go to *View → Resource Explorer*. Under the TI Resource Explorer, go to *C2000Ware DigitalPower SDK* .

Use the following steps to open the reference design software as it is. That is, it opens firmware as it was run on this design and hardware, requires the board to be exactly the same as this reference design.

1. Under *C2000Ware DigitalPower SDK*, select *Development Kits → CCM Totem Pole PFC TIDA-01604*, and click on *Import <device> Project*.
2. These steps import the project, and the development kit or designs page show up. This page can be used to browse all the information on the design including this user guide, test reports, hardware design files, and so forth.
3. Click *Import <device_name> Project*.
4. This action imports the project into the workspace environment, and a cfg page with a GUI shows up.

Open reference design software for adaptation. Power stage parameters can be modified, which are then used to create the model of the power stage in Compensation Designer and can also modify scaling values for voltages and currents for a custom design.

1. Under*C2000Ware Digital Power SDK*click on *powerSUITE →Solution Adapter Tool* ( ).
2. Select *Single Phase CCM Totem Pole PFC* from the list of solutions presented.
3. Select the device this solution must run on the next page.
4. Once the icon is clicked, a pop-up window shows up asking for a location to create the project. The project can be saved inside the workspace itself. Once the location is specified, a project is created, and a GUI page appears with modifiable options for the solution.
5. This GUI can be used to change the parameters for an adapted solution, like power rating, inductance, capacitance, sensing circuit parameters, and so forth.

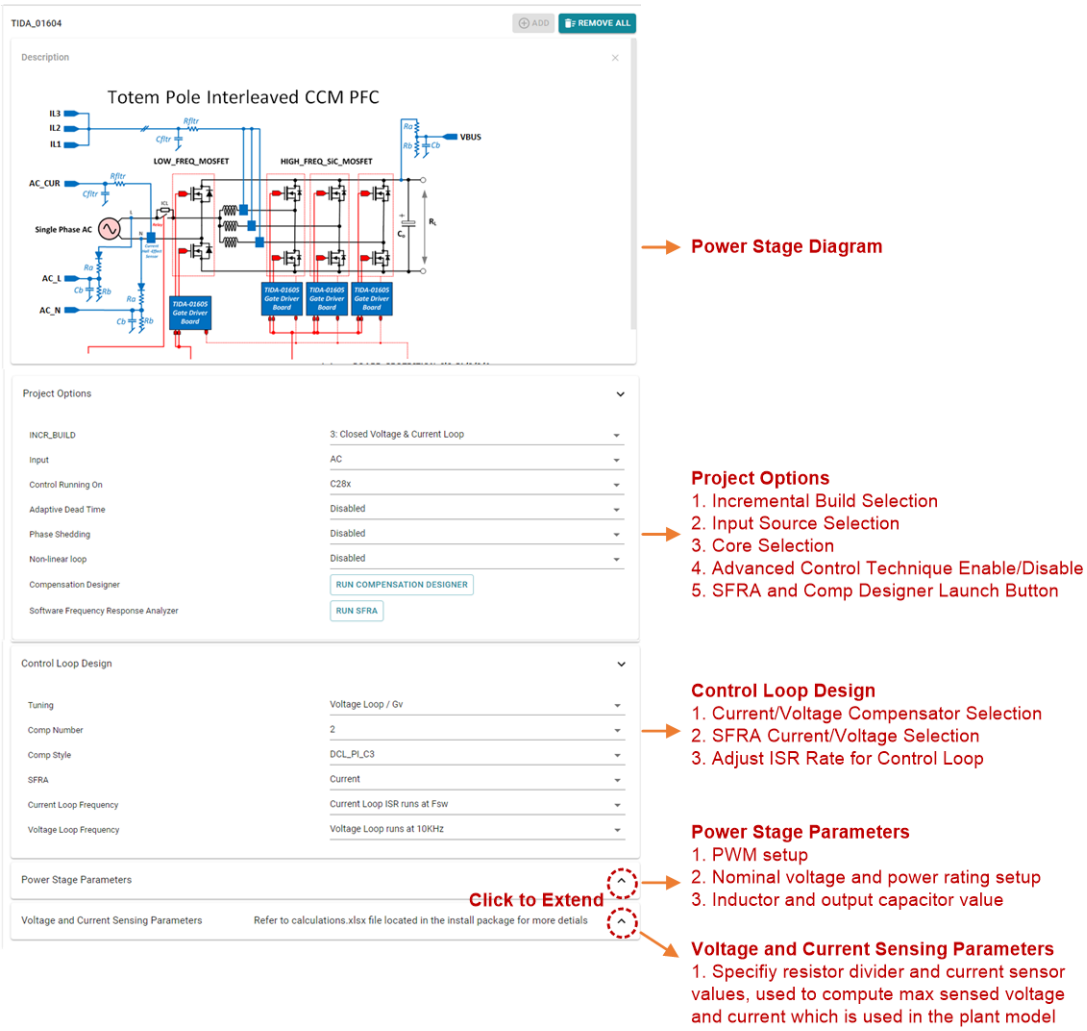


Figure 19. powerSUITE Page for CCM TTPL PFC Solution

3.2.2 Project Structure

Once the project is imported, the project explorer appears inside CCS as shown in Figure 20.

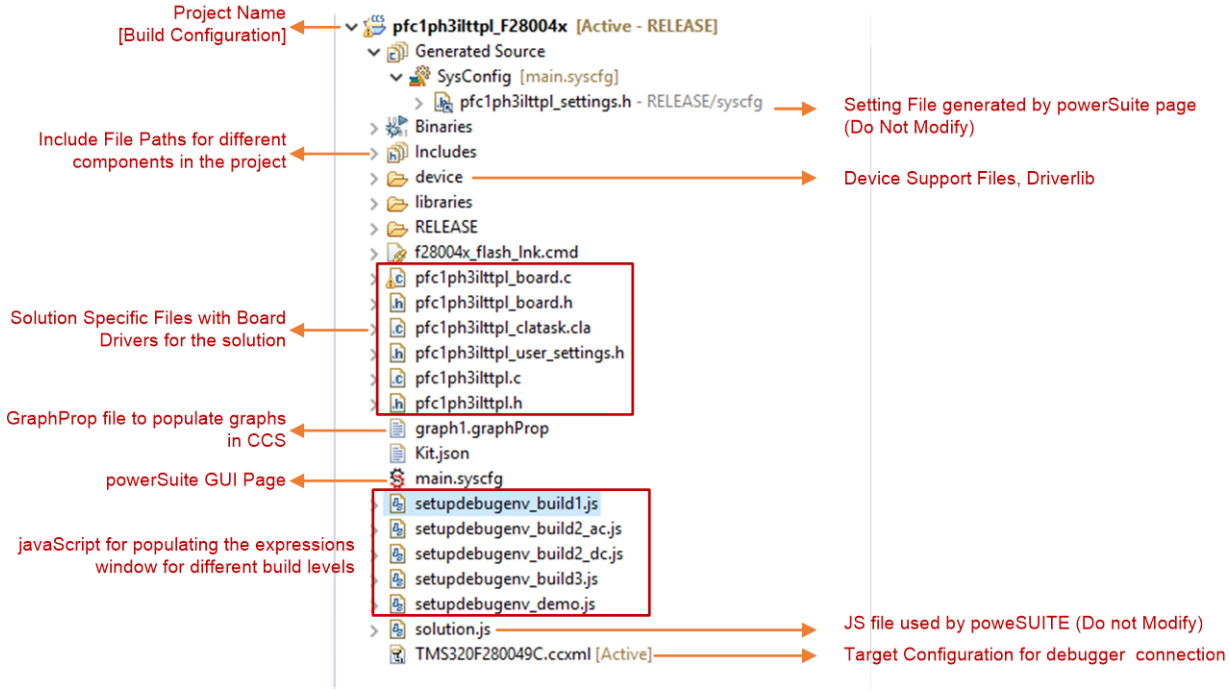


Figure 20. Project Explorer View of Solution Project

The general structure of the project is shown in Figure 21.

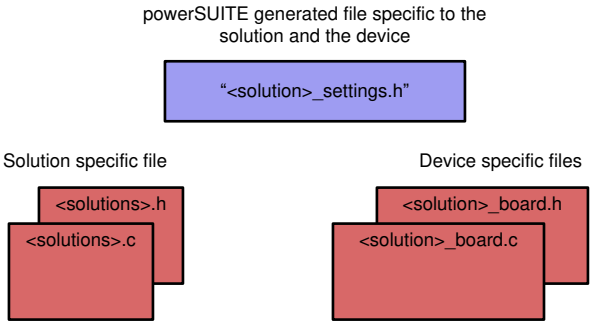


Figure 21. Project Structure Overview

NOTE: Figure 21 shows the project for F28004x. However, if a different device is chosen from the powerSUITE page, the structure is similar.

Solution-specific and device-independent files are *<solution>.c/h*. This file consists of the main.c file of the project and is responsible for the control structure of the solution.

Board-specific and device-specific files are *<solution>_board.c/h*. This file consists of device-specific drivers to run the solution.

The powerSUITE page can be opened by clicking on the *main.syscfg* file, listed under the project explorer. The powerSUITE page generates the *<solution>_settings.h* file. This file is the only file used in the compiling of the project that is generated by the powerSUITE page. Do not modify this file , as the changes are overwritten by powerSUITE every time the project is saved. For the additional options and settings, User can modify user_settings.h.

The *Kit.json* and *solution.js* files are used internally by the powerSUITE and must also not be modified. Any changes to these files results in the project not functioning properly.

The setupdebugenv_build.js are provided to auto-populate the watch window variables for different builds.

The *.graphProp files are provided to auto-populate settings for the data logger graph.

The project consists of an interrupt service routine, which is called every PWM cycle, and a current controller is run inside this ISR. In addition to this, there is a slower ISR of approximately 10 kHz that is called for running the voltage loop and the instrumentation ISR. A few background tasks (A0-A4 and B0-B4) are called in a polling fashion and can be used to run slow tasks for which absolute timing accuracy is not required, such as SFRA background and so on.

Figure 22 shows the software flow diagram of the firmware.

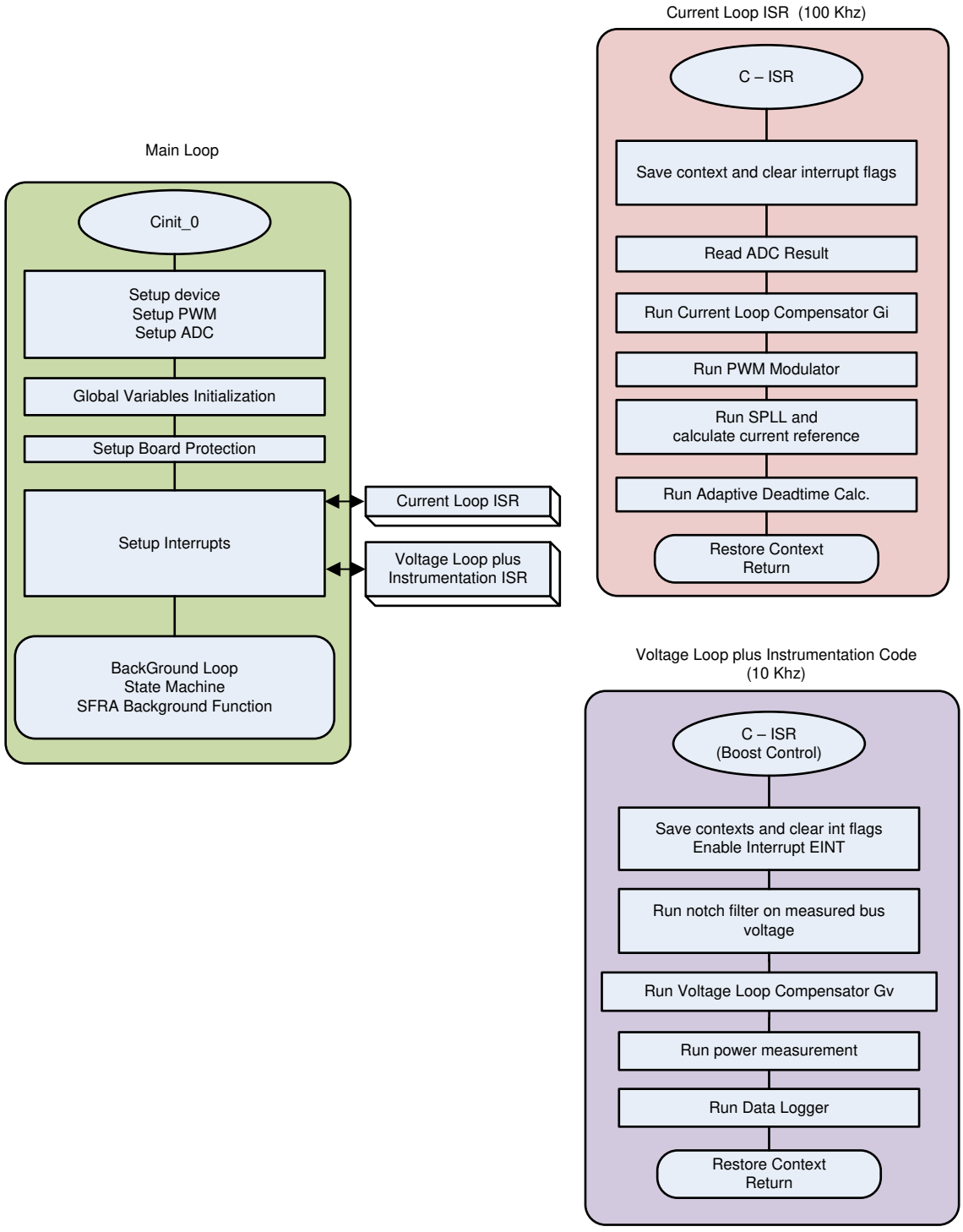


Figure 22. Project Structure Image

To simplify the system bring up and design, the software of this reference design is organized in four incremental builds (INCR_BUILD):

- INCR_BUILD 1: Open Loop Check, DC
- INCR_BUILD 2: Closed Current Loop : DC

- INCR_BUILD 2: Closed Current Loop : AC
- INCR_BUILD 3: Closed Voltage and Current Loop

3.2.3 Running the Project

3.2.3.1 INCR_BUILD 1: Open Loop, DC

In this build, the board is excited in open loop fashion with a fixed duty cycle. The duty cycle is controlled with dutyPU_DC variable. This build verifies the sensing of feedback values from the power stage and also operation of the PWM gate driver and ensures that there are no hardware issues. Additionally, calibration of input and output voltage sensing can be performed in this build. The software structure for this build is shown in Figure 23. There are two ISR in the system: fast ISR for the current loop and a slower ISR to run the voltage loop and instrumentation functions. Modules that are run in each ISR are shown in Figure 23.

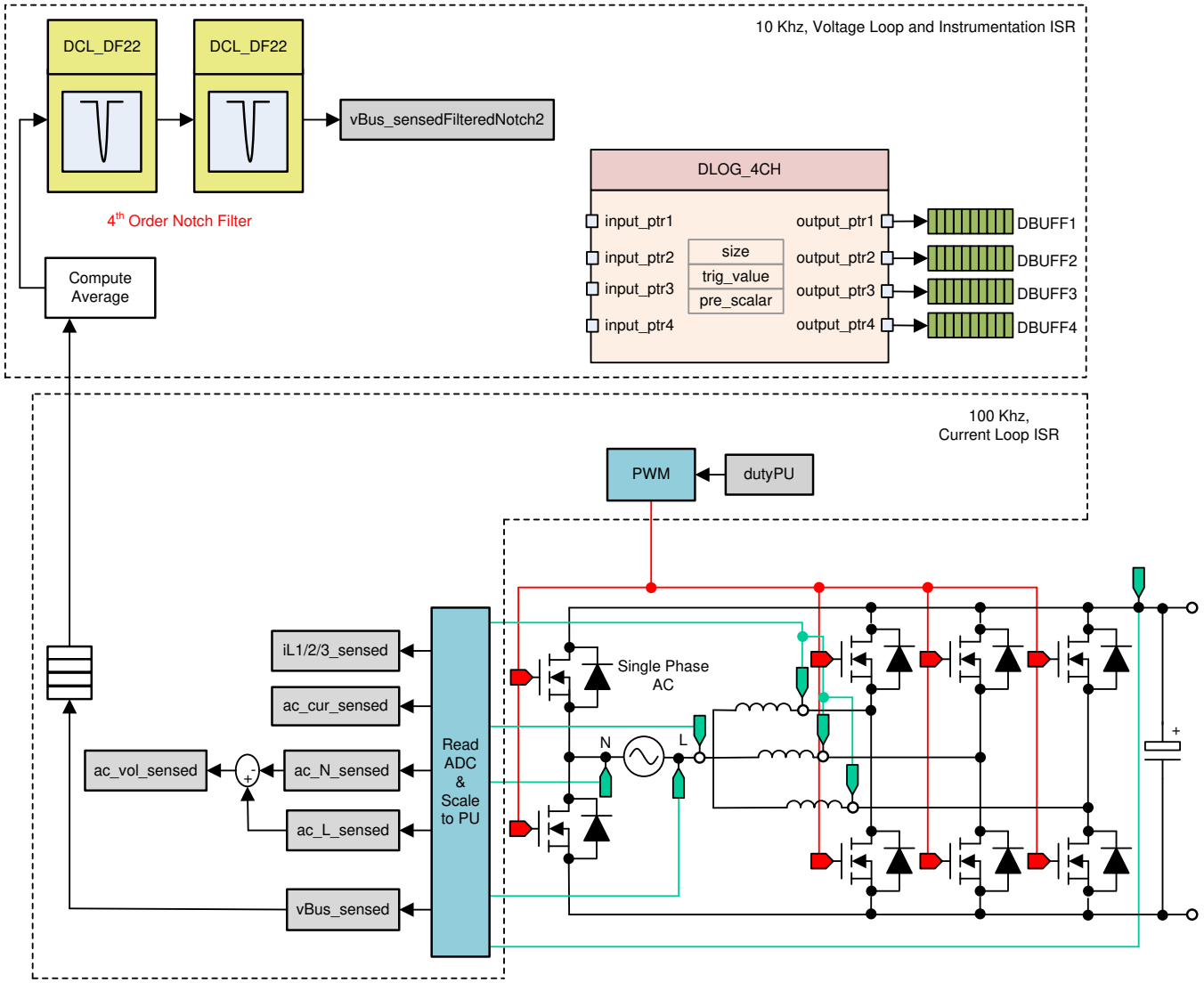


Figure 23. Build Level 1 Control Software Diagram: Open Loop Project

3.2.3.1.1 Setting Software Options for BUILD 1

On the powerSUITE page, under the *Project Options* section:

1. Select *Open Loop* for the build level under INCR_BUILD option.

2. Select input to be DC under INPUT options.
3. Disable the other options such as *Non Linear Voltage Loop, Adaptive Deadtime and Phase shedding*.

If this is an adapted solution, edit the setting under *Voltage and Current Sensing Parameters*. Refer to the *calculations.xlsx* file which is available under the C2000Ware DigitalPower SDK Install directory at *<install_location>\solutions\tida_01604\hardware* for details on sensing circuit and how max range is computed for the powerSUITE pageUnder Power Stage Parameters specify the switching frequency, the dead band, and the power rating. Save the page.

3.2.3.1.2 Building and Loading Project

Right-click on the project name, and click *Rebuild Project*.

The project builds successfully.

In the *Project Explorer* ensure that the correct target configuration file is set as Active under tragetconfigs.

Click *Run → Debug*. This action launches a debugging session. In the case of dual CPU devices, a window may appear to select the CPU that the debug must be performed. In this case, select CPU1.

The project then loads on the device, and CCS debug view becomes active. The code halts at the start of the main routine.

3.2.3.1.3 Setup Debug Environment Windows

To add the variables in the watch and expressions window, click *View → Scripting Console* to open the scripting console dialog box. On the upper-right corner of this console, click on open. Browse to the *setupdebugenv_build1.js* script file located inside the project folder. This script file populates the watch window with appropriate variables required to debug the system. Click on the Continuous Refresh button on the watch window to enable continuous update of values from the controller. The watch window appears as shown in Figure 24.

Variables | Expressions | Registers | Breakpoints

Expression	Type	Value	Address
buildInfo	enum enum_BuildLevel	BuildLevel1_OpenLoop_DC	0x0000A817@Data
guiVbus	float	-0.000226858858	0x0000A87E@Data
guiVin	float	-0.714660585	0x0000A876@Data
guiIi	float	0.0891165435	0x0000A874@Data
ac_cur_sensed	float	0.00343942642	0x0000A8A4@Data
clearTrip	int	0	0x0000A827@Data
EPwm1Regs.TZFLG	Register	0x0000	
EPwm2Regs.TZFLG	Register	0x0000	
dutyPU	float	0.5	0x0000A858@Data
dutyPU_DC	float	0.5	0x0000A85E@Data
vBus_sensed	float	0.0	0x0000A8C0@Data
iL1_sensed	float	-0.00341796875	0x0000A8C4@Data
iL2_sensed	float	-0.00830078125	0x0000A8C6@Data
iL3_sensed	float	-0.00732421875	0x0000A8AA@Data
Add new expression			

Figure 24. Build Level 1 Expressions View

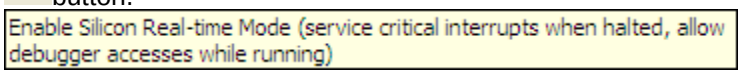
Run the project by clicking on  .

Halt the processor by using the *Halt* button on the toolbar ().

3.2.3.1.4 Using Real-Time Emulation

Real-time emulation is a special emulation feature that allows windows within CCS to be updated while the MCU is running. This feature allows graphs and watch views to update but also allows for changing of values in watch or memory windows and the ability to see the effect of these changes in the system without halting the processor.

Enable real-time mode by hovering the mouse on the buttons on the horizontal toolbar and clicking the  button.



A message box may appear. If so, select *YES* to enable debug events. This action sets bit 1 (DGBM bit) of status register 1 (ST1) to a *0*. The DGBM is the debug enable mask bit. When the DGBM bit is set to *0*, memory and register values can be passed to the host processor for updating the debugger windows.

3.2.3.1.5 Running Code

Run the project again by clicking on  .

After a few seconds, the inrush relay clicks. The software is programmed to do so in the build level with DC. The trip clears, and a duty cycle of 0.5 is applied.

In the watch view, check if the guiVin, guiVbus, guiIi, variables are updating periodically. As no power is applied, this value is close to zero.

Slowly increase the input DC voltage from zero to 120 V. The output voltage shows a boosted voltage as a steady duty cycle of 0.5 PU is applied as the default setting. If a high current is drawn, verify if the voltage terminals are swapped. If true, reduce the voltage to zero first and correct the issue before resuming the test.

Verify the voltage sensing by ensuring that *guiVin* and *guiVbus* display the correct values. For 120-V DC input, guiVbus is close to 240 V. This verifies the voltage sensing of the board in some manner.

Observe the *guiIIi* for the given test condition. This value is close to 1 A.

Variables | Expressions | Registers | Breakpoints

Expression	Type	Value	Address
buildInfo	enum enum_BuildLevel	BuildLevel1_OpenLoop_DC	0x0000A817@Data
guiVbus	float	236.679321	0x0000A87E@Data
guiVin	float	117.730934	0x0000A876@Data
guiIi	float	1.01184416	0x0000A874@Data
ac_cur_sensed	float	0.0393730402	0x0000A8A4@Data
clearTrip	int	0	0x0000A827@Data
EPwm1Regs.TZFLG	Register	0x0000	
EPwm2Regs.TZFLG	Register	0x0000	
dutyPU	float	0.5	0x0000A858@Data
dutyPU_DC	float	0.5	0x0000A85E@Data
vBus_sensed	float	0.511474609	0x0000A8C0@Data
iL1_sensed	float	0.0161132813	0x0000A8C4@Data
iL2_sensed	float	0.01171875	0x0000A8C6@Data
iL3_sensed	float	0.0141601563	0x0000A8AA@Data
Add new expression			

Figure 25. Build Level 1: Watch Expression Showing Measured Voltage and Currents

The dutyPU_DC variable can be changed to see operation under various boost conditions. This verifies at a basic level the PWM driver and connection of hardware

Once finished, reduce the input voltage to zero and watch for the bus voltages to reduce down to zero.

This completes the check for this build. The following items are verified on successful completion of this build:

- Sensing of voltages and currents and scaling for accuracy
- Interrupt generation and execution of the BUILD 1 code in the current loop ISR and Voltage Loop Instrumentation ISR
- PWM driver and switching

If any issues are observed, a careful inspection of the hardware may be required to eliminate any build issues and so forth.

The controller can now be halted, and the debug connection terminated.

Fully halting the MCU when in real-time mode is a two-step process. First halt the processor by using the *Halt* button on the toolbar () or by using *Target* → *Halt*. Then, take the MCU out of real-time mode by clicking on  . Finally, reset the MCU by clicking on  .

Close CCS debug session by clicking on *Terminate Debug Session* (*Target* → *Terminate all*).

3.2.3.2 INCR_BUILD 2: Closed Current Loop DC

In BUILD 2, the inner current loop is closed, that is, the inductor current is controlled using a current compensator Gi. Both DC bus and output voltage feedforward are applied to the output of this current compensator to generate the duty cycle of the inverter. This makes the plant for the current compensator simple and a proportional (P) controller can be used to tune the loop of the inner current. The model for the current loop was derived. Complete software diagram for this build is illustrated in Figure 26.

$$\text{duty1PU} = \frac{(\text{ac\_cur\_meas} - \text{ac\_cur\_ref\_inst}) \times \text{Gi} + \text{ac\_vol\_sensed}}{\text{vBus\_sensed}} \tag{29}$$

Complete software diagram for this build is illustrated in Figure 26.

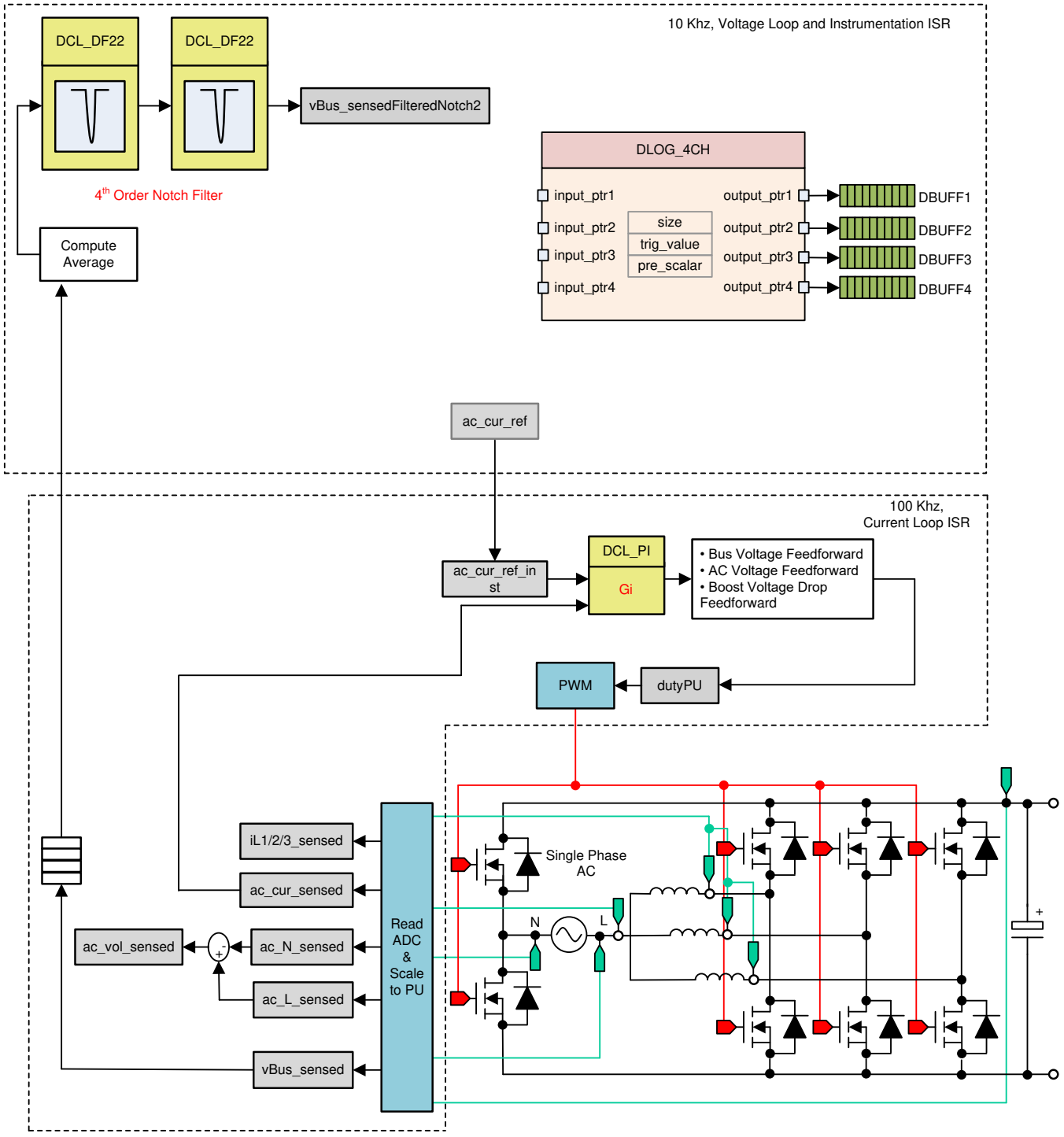


Figure 26. Build Level 2 Control Software Diagram: Closed Current Loop

3.2.3.2.1 Setting Software Options for BUILD 2

Ensure that the hardware is set up as outlined in Figure 18. Do not supply any high voltage (HV) power to the board yet.

On the powerSUITE page, under *Project Options* section:

1. Select *Closed Current Loop* for the build level under INCR_BUILD option.

2. Select input to be DC under INPUT options.
3. Disable the other options such as *Non Linear Voltage Loop, Adaptive Deadtime and Phase shedding*.

Ensure that all other options are the same as specified earlier in Section 3.2.3.2.

Under *Control Loop Design*, options for the current loop tuning will automatically be selected (*Tuning → Current Loop → COMP1 → DCL_PI_C1*). Click on the *Compensation Designer* icon ( ).

3.2.3.2.2 Designing Current Loop Compensator

Compensation Designer launches with the model of the current loop plant with parameters specified on the powerSUITE page. PI-based controller can be tuned from a pole zero perspective to ensure stable closed loop operation. Stability of the system when using the designed compensator can be verified by observing the gain and phase margins on the open loop transfer function plot in the Compensation Designer, as shown in Figure 27.

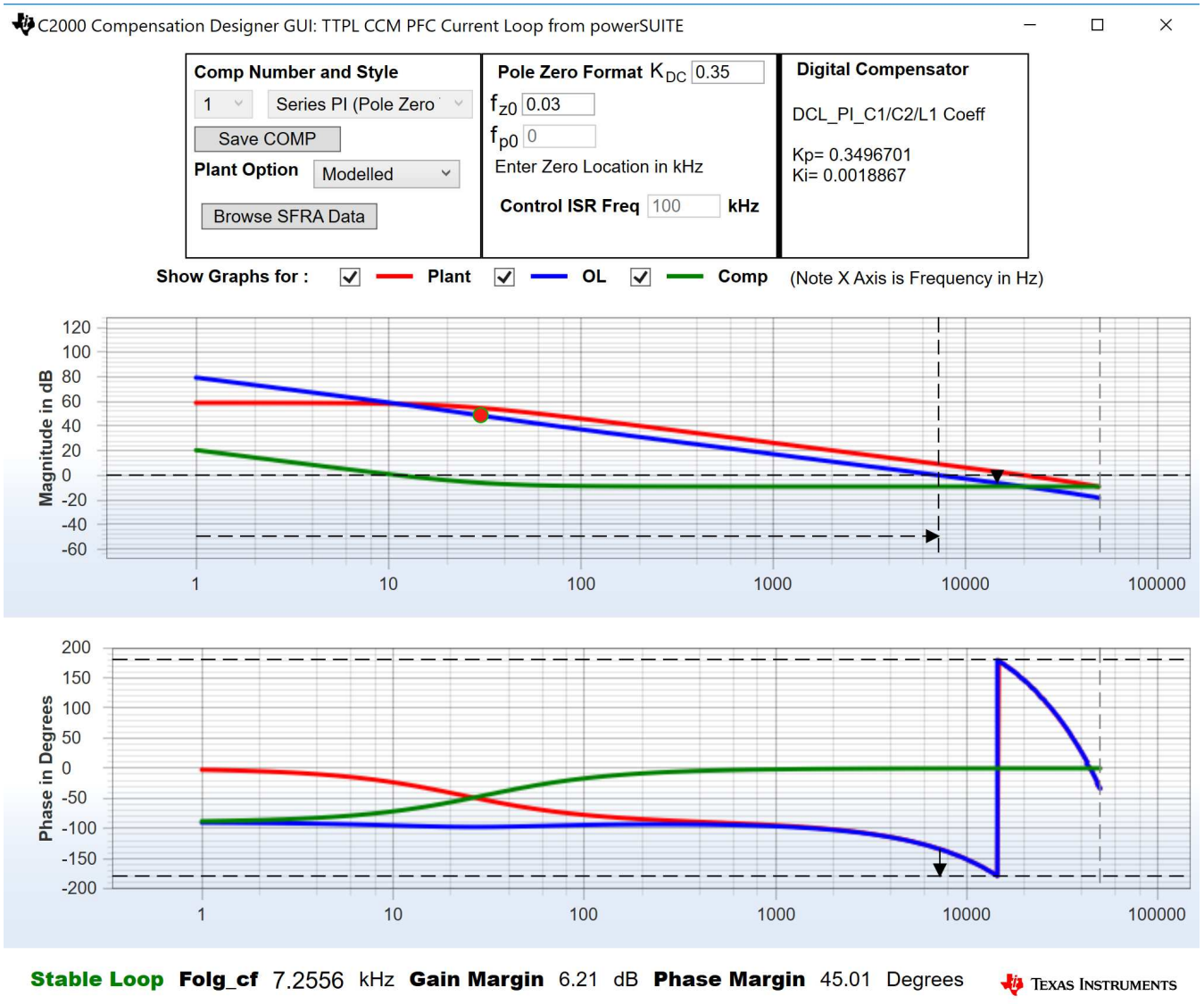


Figure 27. Current Loop Design Using Compensation Designer

Once satisfied with the open loop gain, click on *Save COMP*. This action saves the compensator values into the project. If the project was not selected from the solution adapter, changes to the compensator are not allowed. Select the solution through the solution adapter.

Close the Compensation Designer, and return to the powerSUITE page.

3.2.3.2.3 Building and Loading Project and Setting Up Debug

Right-click on the project name, and click *Rebuild Project*. The project builds successfully. Click *Run → Debug*, which launches a debugging session. In the case of dual CPU devices, a window may appear to select the CPU the debug must be performed. In this case, select CPU1. The project then loads on the device, and CCS debug view becomes active. The code halts at the start of the main routine.

To add the variables in the watch and expressions window, click *View → Scripting Console* to open the scripting console dialog box. On the upper-right corner of this console, click on *Open* to browse to the *setupdebugenv_build2_dc.js* script file, which is located inside the project folder. This file populates the watch window with appropriate variables required to debug the system. Click on *Continuous Refresh* button ( ) on the watch window to enable continuous update of values from the controller. The watch window appears as Figure 28.

Variables | Expressions | Registers | Breakpoints

Expression	Type	Value	Address
buildInfo	enum enum_BuildLevel	BuildLevel2_CurrentLoop_DC	0x0000A80C@Data
boardStatus	enum enum_boardStatus	boardStatus_Idle	0x0000A804@Data
clearTrip	int	0	0x0000A824@Data
closeGiLoop	int	0	0x0000A819@Data
ac_cur_ref	float	0.0299999993	0x0000A838@Data
ac_cur_sensed	float	0.0118730068	0x0000A8A4@Data
guiVbus	float	0.347434014	0x0000A846@Data
guiVin	float	-0.678055584	0x0000A86C@Data
guiIi	float	0.274688691	0x0000A86A@Data
EPwm1Regs.TZFLG	Register	0x0004	
EPwm2Regs.TZFLG	Register	0x0004	
dutyPU	float	0.00999999978	0x0000A84E@Data
dutyPU_DC	float	0.5	0x0000A84C@Data
iL1_sensed	float	-0.00537109375	0x0000A8AE@Data
iL2_sensed	float	-0.00537109375	0x0000A8AC@Data
iL3_sensed	float	-0.00634765625	0x0000A8AA@Data
autoStartSlew	unsigned long	14	0x0000A87C@Data
Add new expression			

Figure 28. Build Level 2: Closed Current Loop Expressions View

Enable real-time mode by hovering the mouse on the buttons on the horizontal toolbar and clicking the button.

Run the project by clicking on .

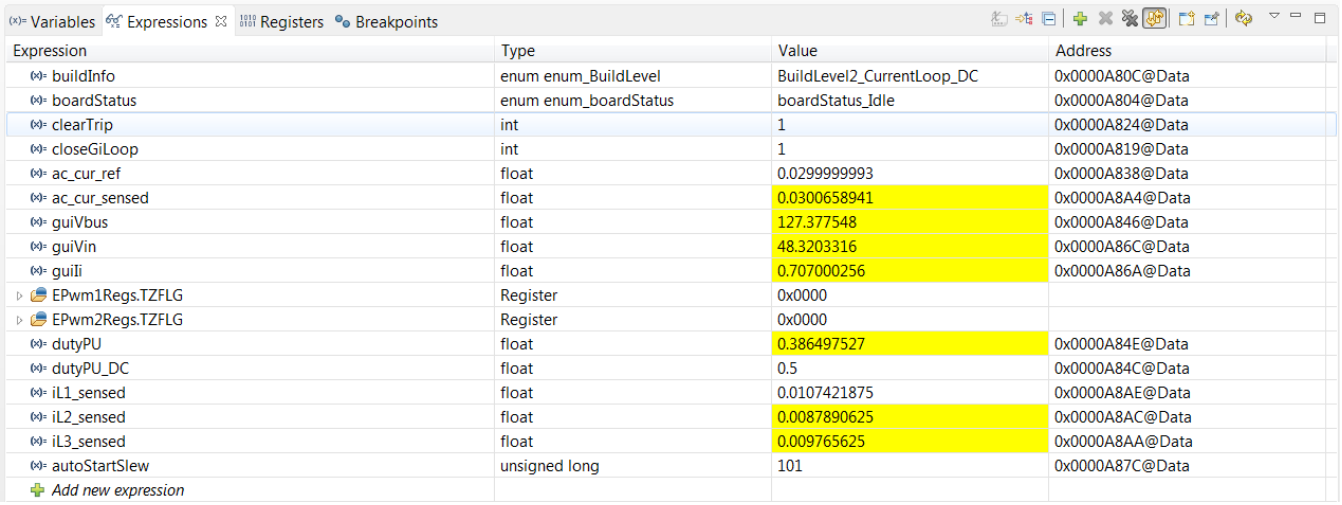
Halt the processor by using the *Halt* button on the toolbar .

3.2.3.2.4 Running Code

The project is programmed to drive the inrush relay and clear the trip after a set amount of time, that is, autoStartSlew==100. The software is programmed to do so in the build level with DC. An input voltage must be applied after hitting run and before this autoslew counter reaches 100. If the counter reaches 100, before voltage is applied at the input, the code must be reset. For which the controller must be brought out of real time mode, a reset performed and restarted. Repeat the step from Section 3.2.3.2.3 of enabling real-time mode by hovering the mouse on the buttons on the horizontal toolbar and click the button.

Run the project by clicking  .

Apply an input voltage of approximately 50 V before the autoStartSlew reaches 100. As soon autoStartSlew reaches 100, the inrush relay is triggered, and PWM trip is cleared along with closing the current loop flag.



Variables | Expressions | Registers | Breakpoints

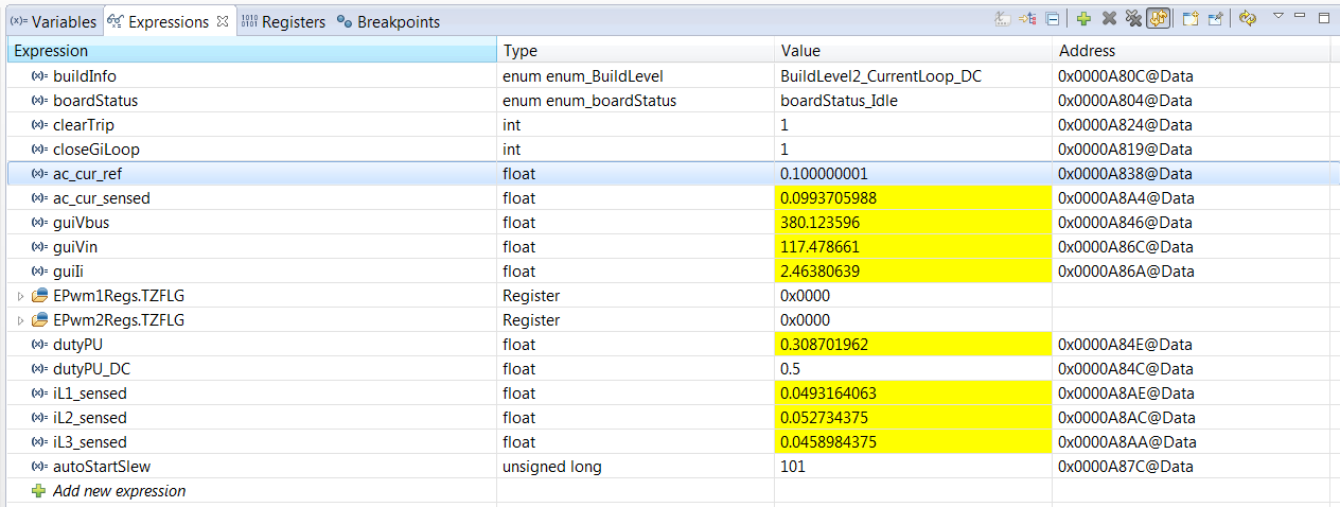
Expression	Type	Value	Address
buildInfo	enum enum_BuildLevel	BuildLevel2_CurrentLoop_DC	0x0000A80C@Data
boardStatus	enum enum_boardStatus	boardStatus_Idle	0x0000A804@Data
clearTrip	int	1	0x0000A824@Data
closeGiLoop	int	1	0x0000A819@Data
ac_cur_ref	float	0.0299999993	0x0000A838@Data
ac_cur_sensed	float	0.0300658941	0x0000A8A4@Data
guiVbus	float	127.377548	0x0000A846@Data
guiVin	float	48.3203316	0x0000A86C@Data
guiIi	float	0.707000256	0x0000A86A@Data
EPwm1Regs.TZFLG	Register	0x0000	
EPwm2Regs.TZFLG	Register	0x0000	
dutyPU	float	0.386497527	0x0000A84E@Data
dutyPU_DC	float	0.5	0x0000A84C@Data
iL1_sensed	float	0.0107421875	0x0000A8AE@Data
iL2_sensed	float	0.0087890625	0x0000A8AC@Data
iL3_sensed	float	0.009765625	0x0000A8AA@Data
autoStartSlew	unsigned long	101	0x0000A87C@Data
Add new expression			

Figure 29. Watch Expression, Build Level 2, DC After Closed Current Loop Operation Begins

The input current regulates approximately 1.5 A, and the output voltage boosts to approximately 193 V.

Slowly increase ac_cur_ref to 0.045, that is, 2.4-A input.

Slowly increase V_{in} = 120 V, and the output voltage will be greater than 370 V.



Variables | Expressions | Registers | Breakpoints

Expression	Type	Value	Address
buildInfo	enum enum_BuildLevel	BuildLevel2_CurrentLoop_DC	0x0000A80C@Data
boardStatus	enum enum_boardStatus	boardStatus_Idle	0x0000A804@Data
clearTrip	int	1	0x0000A824@Data
closeGiLoop	int	1	0x0000A819@Data
ac_cur_ref	float	0.100000001	0x0000A838@Data
ac_cur_sensed	float	0.0993705988	0x0000A8A4@Data
guiVbus	float	380.123596	0x0000A846@Data
guiVin	float	117.478661	0x0000A86C@Data
guiIi	float	2.46380639	0x0000A86A@Data
EPwm1Regs.TZFLG	Register	0x0000	
EPwm2Regs.TZFLG	Register	0x0000	
dutyPU	float	0.308701962	0x0000A84E@Data
dutyPU_DC	float	0.5	0x0000A84C@Data
iL1_sensed	float	0.0493164063	0x0000A8AE@Data
iL2_sensed	float	0.052734375	0x0000A8AC@Data
iL3_sensed	float	0.0458984375	0x0000A8AA@Data
autoStartSlew	unsigned long	101	0x0000A87C@Data
Add new expression			

Figure 30. Watch Expression, Build Level 2, DC After Closed Current Loop Operation Begins at Full Voltage

SFRA is integrated in the software of this build to verify that the designed compensator provides enough gain and phase margin by measuring on hardware. To run the SFRA, keep the project running. From the cfg page, click on the *SFRA* icon. SFRA GUI appears.

Select the options for the device on the SFRA GUI. For example, for F28004x, select floating point. Click on *Setup Connection*. On the pop-up window, uncheck the boot on connect option, and select an appropriate COM port. Ensure *Boot on Connect* is deselected. Click *OK*. Return to the SFRA GUI, and click *Connect*.

The SFRA GUI connects to the device. An SFRA sweep can now be started by clicking *Start Sweep*. The complete SFRA sweep takes a few minutes to finish. Activity can be monitored by seeing the progress bar on the SFRA GUI and also checking the flashing of blue LED on the back on the control card that indicates UART activity. Once complete, a graph with the open loop plot appears. The frequency response data is also saved in the project folder under an SFRA data folder and is time stamped with the time of the SFRA run.

Additionally, the measured frequency response of the plant can be used to design the current compensator by clicking on the Compensation Designer again from the CFG page. Choose *SFRA Data* for plant option on the GUI. This uses the measured plant information to design the compensator. This option can be used to fine tune the compensation. By default, the compensation designer points to the latest SFRA run. If a previous SFRA run plant information must be used, select the SFRAData.csv file by browsing to it by clicking on *Browse SFRA Data*. This action verifies the current compensator design.

Bring the system to a safe stop by bringing the input DC voltage down to zero. Ensure that the guiVbus comes down to zero as well.

Fully halting the MCU when in real-time mode is a two-step process. First halt the processor by using the *Halt* button on the toolbar () or by using *Target* → *Halt*. Then take the MCU out of real-time mode by clicking on  . Finally, reset the MCU () .

Close the CCS debug session by clicking on *Terminate Debug Session* (*Target* → *Terminate all*).


3.2.3.3 INCR_BUILD 2: Closed Current Loop, AC

In BUILD 2, the inner current loop is closed, that is, the inductor current is controlled using a current compensator Gi. Both DC bus and output voltage feedforward are applied to the output of this current compensator to generate the duty cycle of the inverter along with soft start for PWM around the zero-crossing.

Complete software diagram for this build as illustrated in Figure 31.

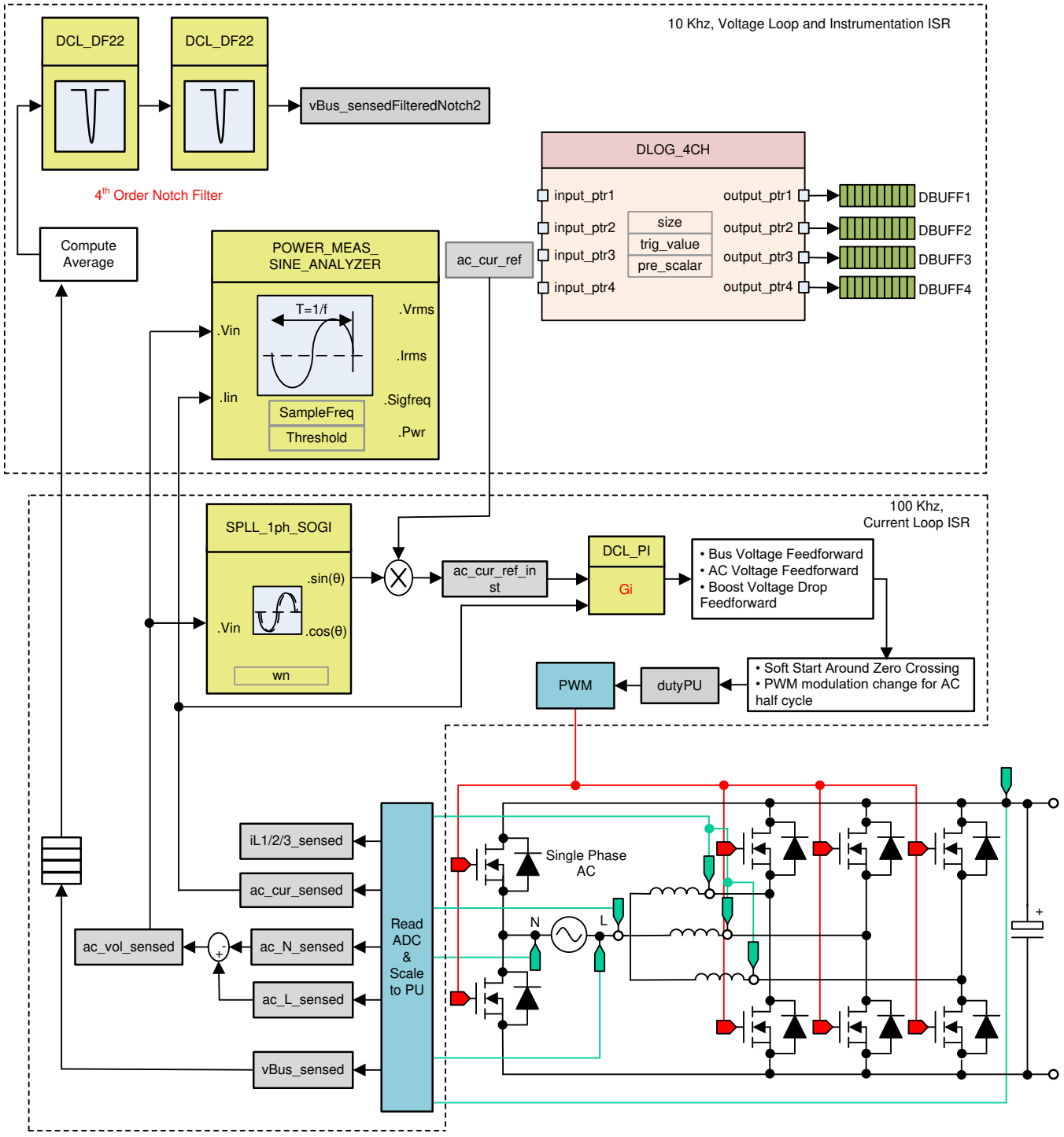


Figure 31. Build Level 2 Control Software Diagram: Closed Current Loop AC

3.2.3.3.1 Setting Software Options for BUILD 2

On the *powerSUITE* page, assuming that options were selected under *Project Options* section, select *Closed Current Loop* and AC input for the build level. Save the page.

Current compensator from the previous build is re-used in this build so no additional steps are required for tuning the current loop in the build level.

3.2.3.3.2 Building and Loading Project and Setting Up Debug

Right-click on the project name, and click *Rebuild Project*. The project builds successfully. Click *Run → Debug*, which launches a debugging session. In the case of dual CPU devices, a window may appear to select the CPU the debug must be performed. In this case, select CPU1. The project then loads on the device, and CCS debug view becomes active. The code halts at the start of the main routine.

To add the variables in the watch and expressions window click *View → Scripting Console* to open the scripting console dialog box. On the upper-right corner of this console, click on *Open* to browse to the *setupdebugenv_build2_ac.js* script file, which is located inside the project folder. This file populates the watch window with appropriate variables required to debug the system. Click on *Continuous Refresh* button () on the watch window to enable continuous update of values from the controller. The watch window appears as Figure 32.

Variables | Expressions | Registers | Breakpoints

Expression	Type	Value	Address
buildInfo	enum enum_BuildLevel	BuildLevel2_CurrentLoop_AC	0x0000A806@Data
pwmSwState	enum enum_pwmSwState	pwmSwState_defaultState	0x0000A824@Data
boardStatus	enum enum_boardStatus	boardStatus_InputUnderVoltageTrip	0x0000A814@Data
clearTrip	int	0	0x0000A809@Data
closeGiLoop	int	0	0x0000A807@Data
ac_cur_ref	float	0.0299999993	0x0000A840@Data
ac_cur_sensed	float	0.010755837	0x0000A8A8@Data
guiVbus	float	0.344914794	0x0000A874@Data
guiVin	float	-0.563325524	0x0000A882@Data
guiVrms	float	0.0	0x0000A872@Data
guiIrms	float	0.0	0x0000A878@Data
guiPrms	float	0.0	0x0000A86E@Data
guiFreqAvg	float	0.0	0x0000A880@Data
guiPowerFactor	float	0.0	0x0000A87C@Data
EPwm1Regs.TZFLG	Register	0x0004	
EPwm2Regs.TZFLG	Register	0x0004	
dutyPU	float	0.00999999978	0x0000A86C@Data
dutyPU_DC	float	0.5	0x0000A862@Data
iL1_sensed	float	-0.00634765625	0x0000A8C4@Data
iL2_sensed	float	-0.00830078125	0x0000A8BE@Data
iL3_sensed	float	-0.0112304688	0x0000A8C0@Data
autoStartSlew	unsigned long	0	0x0000A85E@Data
Add new expression			

Figure 32. Build Level 2 AC: Closed Current Loop Expressions View

Enable real-time mode by hovering the mouse on the buttons on the horizontal toolbar, and clicking the  button.

3.2.3.3.3 Running Code

The project is programmed to wait for input voltage to exceed approximately 70 V_{rms} to drive the in rush relay and clear the trip.

Run the project by clicking  .

Apply an input voltage of approximately 120 V. The board comes out of the undervoltage condition and inrush relay is driven. The trip clears, and a small amount of current of approximately 1.3-A RMS is drawn. The watch window looks similar to Figure 33. The bus voltage is close to 270 V.

Variables | Expressions | Registers | Breakpoints

Expression	Type	Value	Address
buildInfo	enum enum_BuildLevel	BuildLevel2_CurrentLoop_AC	0x0000A806@Data
pwmSwState	enum enum_pwmSwState	pwmSwState_positiveHalf	0x0000A824@Data
boardStatus	enum enum_boardStatus	boardStatus_NoFault	0x0000A814@Data
clearTrip	int	1	0x0000A809@Data
closeGiLoop	int	1	0x0000A807@Data
ac_cur_ref	float	0.0299999993	0x0000A840@Data
ac_cur_sensed	float	-0.00663924217	0x0000A8A8@Data
guiVbus	float	180.061981	0x0000A874@Data
guiVin	float	-49.6501122	0x0000A882@Data
guiVrms	float	117.459831	0x0000A872@Data
guiIrms	float	0.551513135	0x0000A878@Data
guiPrms	float	64.2371902	0x0000A86E@Data
guiFreqAvg	float	59.8999023	0x0000A880@Data
guiPowerFactor	float	0.978407621	0x0000A87C@Data
EPwm1Regs.TZFLG	Register	0x0000	
EPwm2Regs.TZFLG	Register	0x0000	
dutyPU	float	-0.880984187	0x0000A86C@Data
dutyPU_DC	float	0.5	0x0000A862@Data
iL1_sensed	float	0.0180664063	0x0000A8C4@Data
iL2_sensed	float	-0.0048828125	0x0000A8BE@Data
iL3_sensed	float	-0.0283203125	0x0000A8C0@Data
autoStartSlew	unsigned long	5	0x0000A85E@Data
Add new expression			

Figure 33. Watch Expression, Build Level 2, AC After Closed Current Loop Operation Begins

Slowly increase ac_cur_ref to 0.078, that is, 2.4-A input, and the bus voltage rises to 400 V. The voltage and current waveform are shown in Figure 34.

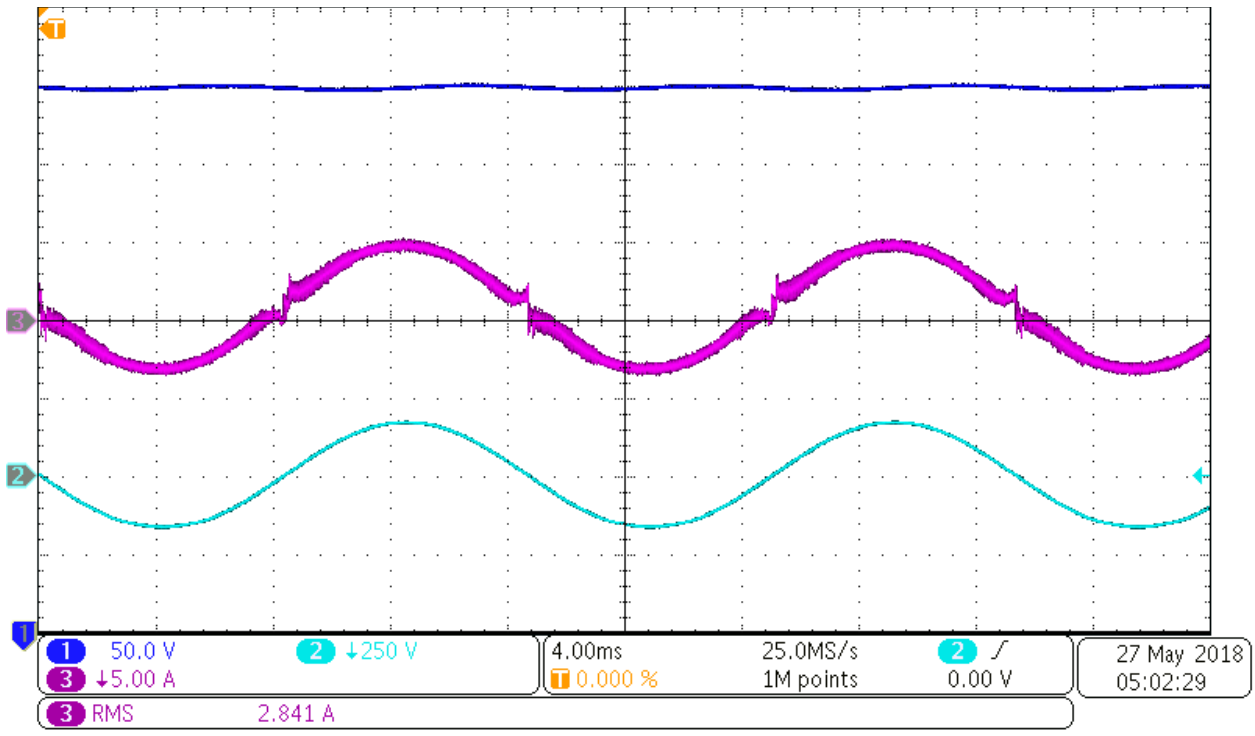


Figure 34. Input AC Current and Output DC Voltage Waveform

SFRA is integrated in the software of this build to verify the designed compensator provides enough gain and phase margin by measuring on hardware. To run the SFRA, keep the project running, and from the cfg page, click on the *SFRA* icon. SFRA GUI appears.

Select the options for the device on the SFRA GUI. For example, for F28377D, select floating point. Click on *Setup Connection*. On the pop-up window, uncheck the boot on connect option, and select an appropriate COM port. Click *OK*. Return to the SFRA GUI, and click *Connect*.

The SFRA GUI connects to the device. A SFRA sweep can now be started by clicking *Start Sweep*. The complete SFRA sweep takes a few minutes to finish. Activity can be monitored by seeing the progress bar on the SFRA GUI and also by checking the flashing of blue LED on the back on the control card that indicates UART activity. Once complete, a graph with the open loop plot appears. This is similar to the plot seen under DC conditions; however, some additional noise is visible due to AC harmonic frequencies close to the measured frequencies. The BW, PM, and GM numbers are very similar to the DC case.

To bring the system to a safe stop, switch off the output from the AC power supply, thus bringing the input AC voltage down to zero. Ensure that the guiVbus comes down to zero, as well.

Fully halting the MCU when in real-time mode is a two-step process. First, halt the processor by using the *Halt* button on the toolbar () or by using *Target* → *Halt*. Then take the MCU out of real-time mode by clicking on  . Finally, reset the MCU () .

Close the CCS debug session by clicking on *Terminate Debug Session* (*Target* → *Terminate all*).


3.2.3.4 INCR_BUILD 3: Closed Voltage and Current Loop

In this build, the outer voltage loop is closed with the inner current loop closed. The model of the outer voltage loop is derived in Figure 35. A PI-based compensator is used and tuned through the compensation designer for the outer voltage loop.

Figure 35 shows the software diagram for this build.

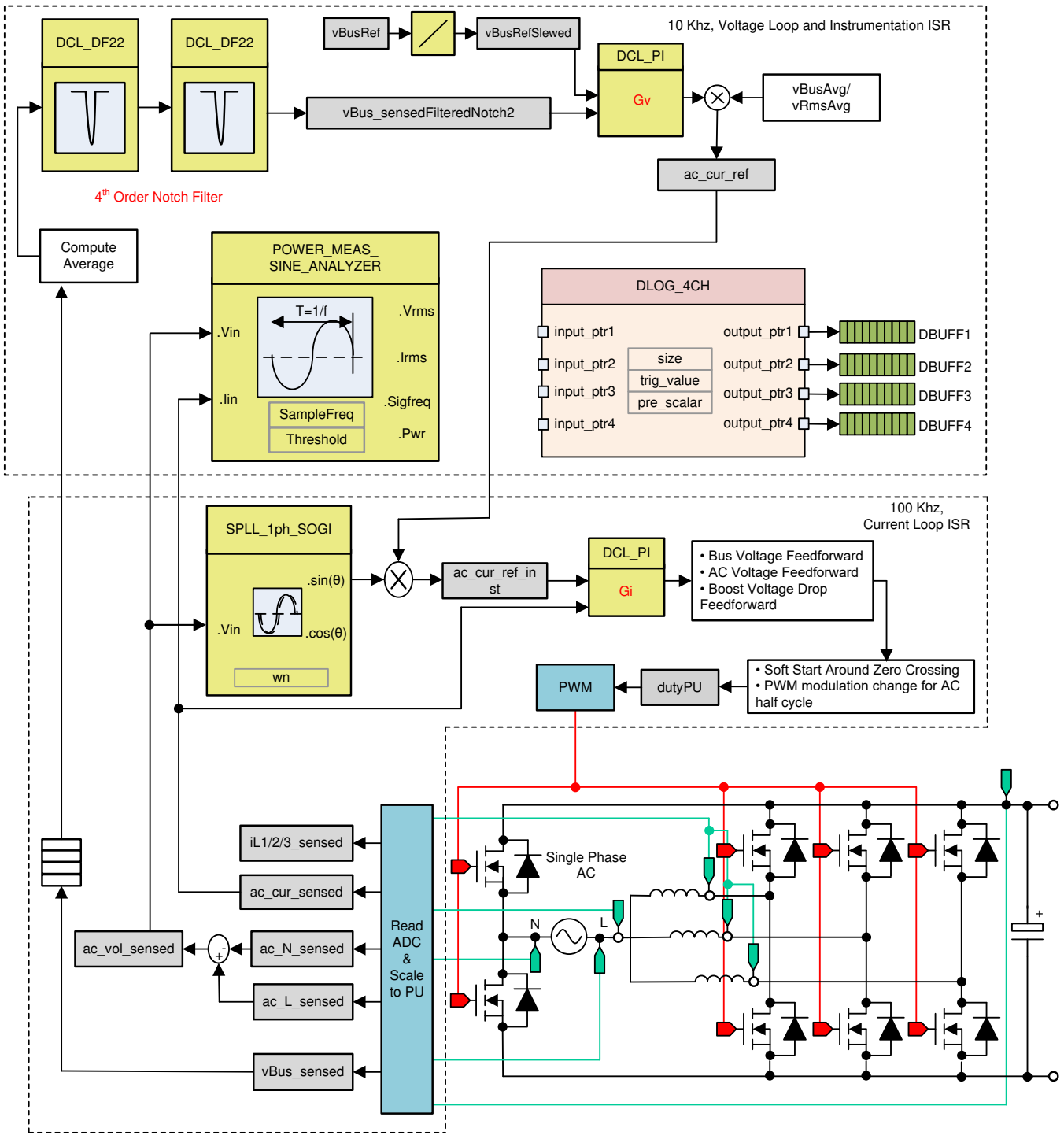


Figure 35. Build Level 3 Control Diagram: Output Voltage Control With Inner Current Loop

3.2.3.4.1 Setting Software Options for BUILD 3

Ensure that the hardware is setup as outlined in Figure 18. Do not supply any HV power yet to the board.

On the powerSUITE page, under the *Project Options* section:

1. Select *Closed Voltage & Current Loop* for the build level under INCR_BUILD option.
2. Select input to be AC under INPUT options.

3. Disable the other options such as *Non Linear Voltage Loop, Adaptive Deadtime and Phase shedding*.

Ensure that all other options are same as specified earlier in Section 3.2.3.1.1.

Under *Control Loop Design*, select *Tuning* as *Voltage Loop*. Style presets to *DCL PI*. Save the page by *Ctrl* + *S*, and click on the Compensation Designer button ( ).

Ensure that the load connected at the output of the board is correctly entered on the powerSUITE cfg page because this load value is used in the design of the voltage compensator.

3.2.3.4.2 Designing Voltage Loop Compensator

Compensation designer launches with the model of the voltage loop plant. The PI compensator can be edited to get the desired gain and phase margin, keeping in mind that the bandwidth of the voltage loop has an inverse relationship with the THD achieved. Typically in a PFC application, this bandwidth is kept at approximately 10 Hz, as shown in Figure 36.

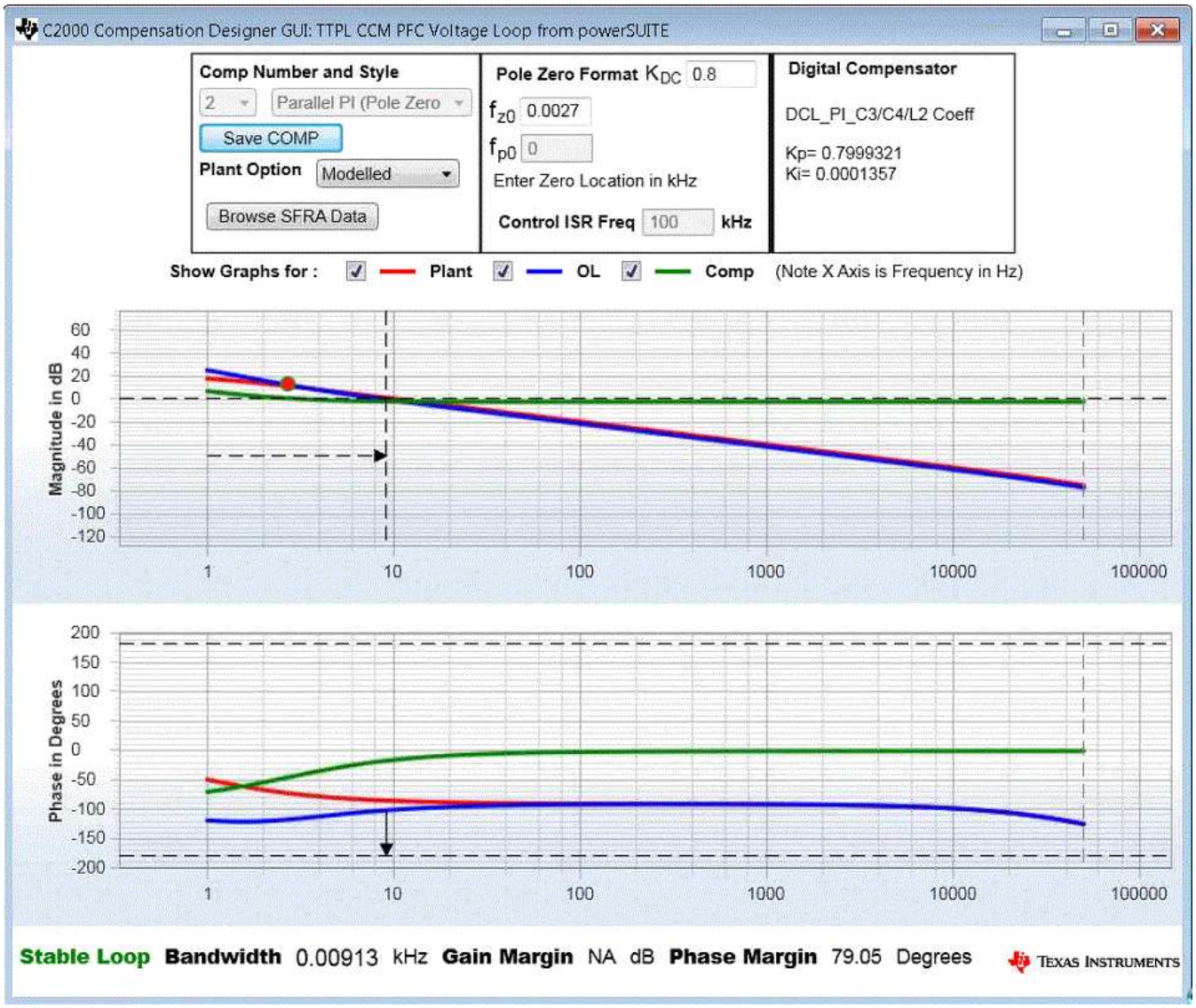


Figure 36. Voltage Loop Design Using Compensation Designer

Once satisfied with the compensator design, click on *Save COMP*. This action saves the compensator values into the project. If the project was not selected from the solution adapter, changes to the compensator are not allowed. For alternative usess, select the solution through the solution adapter.

Close the Compensation Designer, and return to the powerSUITE page. Save using *Ctrl + S*.

3.2.3.4.3 Building and Loading Project and Setting up Debug

Right-click on the project name, and click *Rebuild Project*. The project builds successfully. Click *Run → Debug*, which launches a debugging session. In the case of dual CPU devices, a window may appear to select the CPU the debug must be performed. In this case, select CPU1. The project then loads on the device, and CCS debug view becomes active. The code halts at the start of the main routine.

To add the variables in the watch and expressions window, click *View → Scripting Console* to open the scripting console dialog box. On the upper-right corner of this console, click on *Open* to browse to the *setupdebugenv_build3.js* script file located inside the project folder. This file populates the watch window with appropriate variables required to debug the system. Click on the *Continuous Refresh* button ( ) on the watch window to enable continuous update of values from the controller.
The watch window appears as shown in Figure 37.

Variables | Expressions | Registers

Expression	Type	Value	Address
buildInfo	enum enum_BuildLevel	BuildLevel3_VoltageLoop_AC	0x0000A811@Data
pwmSwState	enum enum_pwmSwState	pwmSwState_defaultState	0x0000A826@Data
boardStatus	enum enum_boardStatus	boardStatus_InputUnderVoltageTrip	0x0000A80F@Data
clearTrip	int	0	0x0000A81A@Data
closeGvLoop	int	0	0x0000A819@Data
vBusRef	float	0.821337461	0x0000A850@Data
vBus_sensed	float	0.000651041686	0x0000A8C0@Data
closeGiLoop	int	0	0x0000A81C@Data
ac_cur_senseOffset	float	0.502499998	0x0000A888@Data
guiVbus	float	0.353723764	0x0000A858@Data
guiVin	float	0.375192761	0x0000A82C@Data
guiVrms	float	0.0	0x0000A842@Data
guiIrms	float	0.0	0x0000A832@Data
guiPrms	float	0.0	0x0000A834@Data
guiPowerFactor	float	0.0	0x0000A82E@Data
guiFreqAvg	float	0.0	0x0000A844@Data
EPwm1Regs.TZFLG	Register	0x0004	
EPwm2Regs.TZFLG	Register	0x0004	
dutyPU	float	0.00999999978	0x0000A86E@Data
dutyPU_DC	float	0.5	0x0000A86C@Data
iL1_sensed	float	-0.00390625	0x0000A884@Data
iL2_sensed	float	-0.00634765625	0x0000A880@Data
iL3_sensed	float	-0.00244140625	0x0000A882@Data
autoStartSlew	unsigned long	0	0x0000A83E@Data
Add new expression			

Figure 37. Build Level 3: Expressions View

Enable real-time mode by hovering the mouse on the buttons on the horizontal toolbar and clicking the button.

Run the project by clicking on .

Halt the processor by using the *Halt* button on the toolbar ( ) .

3.2.3.4.4 Running Code

The project is programmed to wait for input voltage to excel at approximately 70 V_{rms} to drive the in rush relay and clear the trip.

Run the project by clicking  .

Apply an input voltage of approximately 120 V. The board comes out of the undervoltage condition and inrush relay is driven. The trip clears, and the output rises to 380-V DC. A sinusoidal current is drawn from the AC input. Figure 38 shows the watch window when the program is running at this stage.

Variables | Expressions | Registers

Expression	Type	Value	Address
buildInfo	enum enum_BuildLevel	BuildLevel3_VoltageLoop_AC	0x0000A811@Data
pwmSwState	enum enum_pwmSwState	pwmSwState_negativeHalf	0x0000A826@Data
boardStatus	enum enum_boardStatus	boardStatus_NoFault	0x0000A80F@Data
clearTrip	int	1	0x0000A81A@Data
closeGvLoop	int	1	0x0000A819@Data
vBusRef	float	0.821337461	0x0000A850@Data
vBus_sensed	float	0.822998047	0x0000A8C0@Data
closeGiLoop	int	1	0x0000A81C@Data
ac_cur_senseOffset	float	0.502499998	0x0000A888@Data
guiVbus	float	380.081421	0x0000A858@Data
guiVin	float	-152.073486	0x0000A82C@Data
guiVrms	float	120.093376	0x0000A842@Data
guiIrms	float	2.40836215	0x0000A832@Data
guiPrms	float	277.007263	0x0000A834@Data
guiPowerFactor	float	0.990778685	0x0000A82E@Data
guiFreqAvg	float	60.0219727	0x0000A844@Data
EPwm1Regs.TZFLG	Register	0x0000	
EPwm2Regs.TZFLG	Register	0x0000	
dutyPU	float	-0.4262546	0x0000A86E@Data
dutyPU_DC	float	0.5	0x0000A86C@Data
iL1_sensed	float	0.0561523438	0x0000A884@Data
iL2_sensed	float	-0.0673828125	0x0000A880@Data
iL3_sensed	float	-0.0434570313	0x0000A882@Data
autoStartSlew	unsigned long	5	0x0000A83E@Data
Add new expression			

Figure 38. Build Level 3: Expressions View After AC Voltage is Applied

SFRA is integrated in the software of this build to verify the designed compensator provides enough gain and phase margin by measuring on hardware. To run the SFRA, keep the project running, and from the cfg page, click on the *SFRA* icon. SFRA GUI appears.

Select the options for the device on the SFRA GUI. For example, for F28004x, select floating point. Click on *Setup Connection*, and on the pop-up window, uncheck the boot on connect option and select an appropriate COM port. Click *OK*. Return to the SFRA GUI, and click *Connect*.

The SFRA GUI connects to the device. An SFRA sweep can now be started by clicking *Start Sweep*. The complete SFRA sweep takes a few minutes to finish. Activity can be monitored by seeing the progress bar on the SFRA GUI and checking the flashing of blue LED on the back on the control card that indicates UART activity. Once complete, a graph with the open loop plot appears, as seen in Figure 39. This action verifies that the designed compensator is indeed stable.

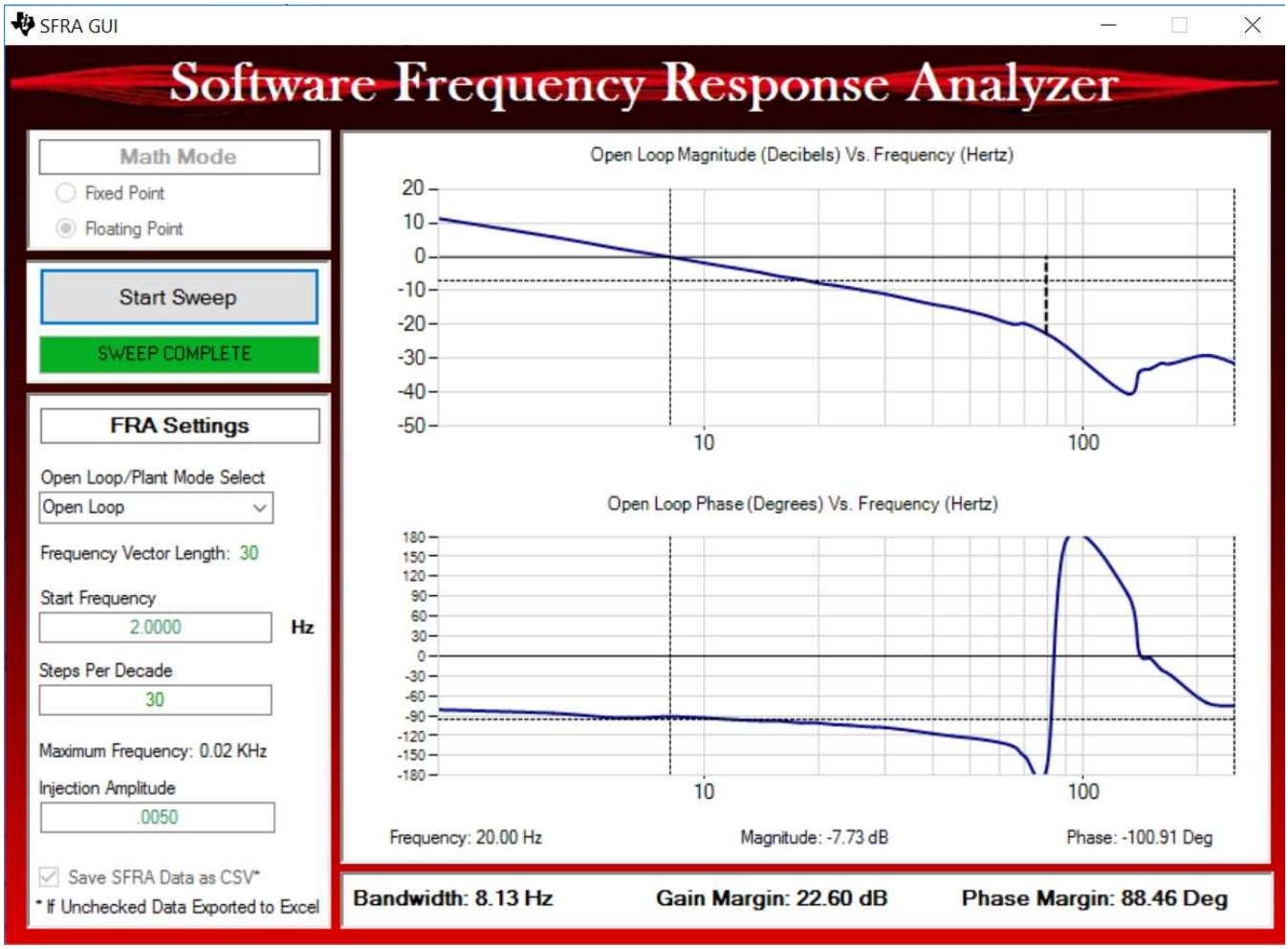


Figure 39. SFRA Run on Closed Voltage Loop

Alternately, click on the Compensation Designer again from the CFG page, and choose *SFRA Data* for plant option on the GUI. This option uses the measured plant information to design the compensator, and can be used to fine tune the compensation. By default, the Compensation Designer points to the latest SFRA run. If a previous SFRA run plant information must be used, select the *SFRAData.csv* file by browsing to it by clicking on *Browse SFRA Data*. Close the Compensation Designer to return to the cfg page once complete. This verifies the voltage compensator design.

To bring the system to a safe stop, bring the input AC voltage down to zero. Ensure that the guiVBus comes down to zero, as well.

Fully halting the MCU when in real-time mode is a two-step process. First, halt the processor by using the *Halt* button on the toolbar ( ) or by using *Target* → *Halt*. Then take the MCU out of real-time mode by clicking on . Finally, reset the MCU ( ).

Close CCS debug session by clicking on *Terminate Debug Session* (*Target* → *Terminate all*).

3.2.4 Running Code on CLA

This solution is supported with an option to run the code on the CLA. This option is selected using a drop-down box under project option on the powerSUITE main.cfg page. Running on CLA can be selected for any build level option.

NOTE: SFRA library does not support CLA, hence the SFRA cannot be run when using CLA.

DLOG is also not used when using CLA, hence the datalogging graphs will not work when using CLA.

Once the option is changed, the CFG file must be saved and the project re-compiled. Once recompiled, follow the steps as outlined in the specific incremental build level documentation.

Depending on the device, such as with F28004x, CLA supports CLA tasks and a background task, thus both 100-kHz ISR and 10-kHz IST can be offloaded to the CLA. By default, if the selection from the powerSUITE page is made, the faster ISR is moved to the CLA task and the slower ISR is moved to the background task by default. The option to not run the 10-kHz ISR on the CLA is available under the "USER SECTION" in the solutions-settings.h file.

```
#if CONTROL_RUNNING_ON == CLA_CORE
#define INSTRUMENTATION_ISR_RUNNING_ON CLA_CORE
#else
#define INSTRUMENTATION_ISR_RUNNING_ON C28x_CORE
#endif
```

3.2.5 Advanced Options

3.2.5.1 Phase Shedding for Efficiency Improvements

Phase shedding can be an effective technique to improve efficiency in interleaved application by optimizing for the conduction and the switching losses. In this design there are three phases, so three different configurations are possible as shown in Figure 40.

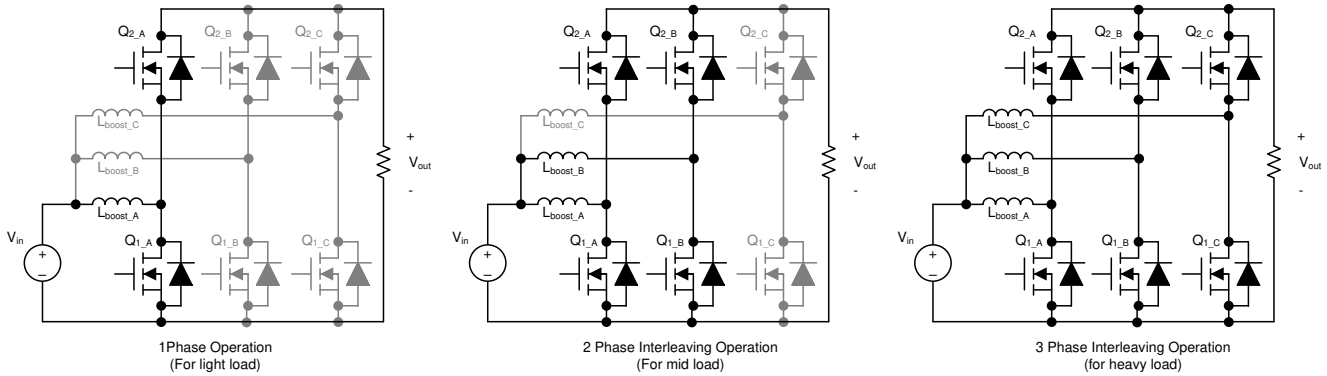


Figure 40. Phase Shedding Options on TTPL PFC

In each of these modes, the phase shift between each of them must be adjusted. When in two-phase mode, a 180° phase shift is desired between the PWMs. When in three-phase mode, a 120° of phase shift is desired.

The decision to do phase shedding can be made on different parameters, such as the RMS current, power, the peak inductor current, and so on. When using RMS current, the change of phases can be significantly delayed. Code takes multiple AC cycles before the phases are added.

This delay may not be acceptable for many applications. Thus, the voltage controller output is chosen as the decision point to drop or add phases. A state machine is constructed as shown in Figure 41, with some hysteresis built around the phase shedding points.

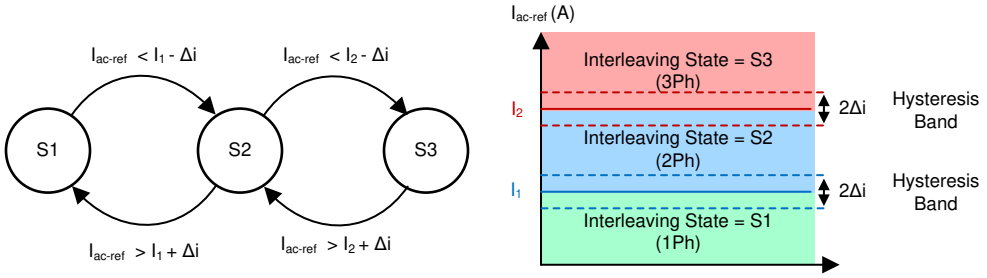


Figure 41. State Machine for Phase Shedding Control

Bringing a phase in and out can cause inadvertent pulses to be generated. Therefore, the implementation to drop and add phase is done through the GPIO and PWM peripheral switch using the GPIO pin Mux registers. All PWM-capable pins are configured and GPIO outputs are driven low. Based on how many phases must be applied, the GPIO pin mux is changed accordingly. It is safe to enable and disable the phases using the GPIO pin mux switch at any point in the AC cycle as the registers in the PWM are shadowed. Figure 42 shows details of the implementation of phase shedding on the C2000 MCU.

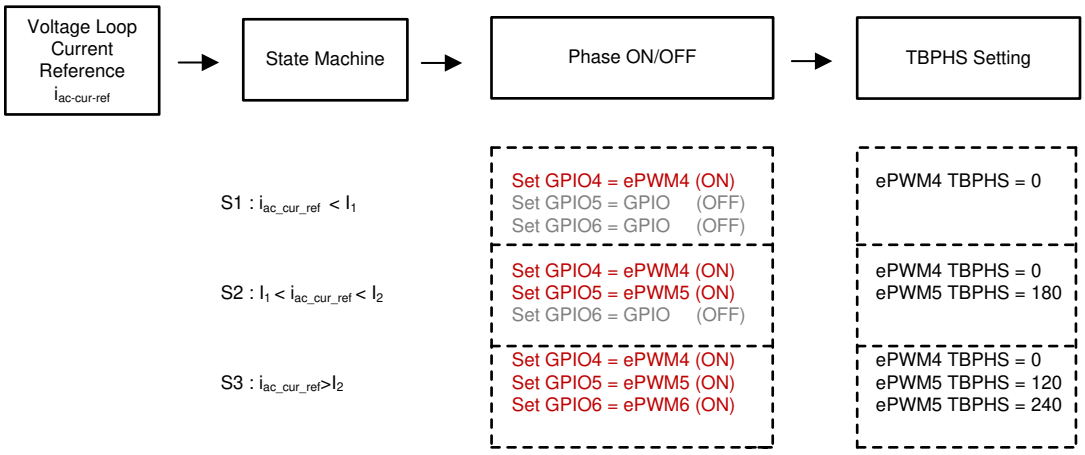


Figure 42. Implementation of Phase Shedding on TTPL PFC Using C2000™ MCU

To enable phase shedding, settings can be set in the user section of the code in *<solution>-settings.h* file and modifying *PHASE_SHEDDING_ENABLED* define. The points at which phases are brought in and out are set by changing the *PHASE_SHEDDING_1PH_2PH_TRANSITION_CURRENT* and *PHASE_SHEDDING_2PH_3PH_TRANSITION_CURRENT* define, which correspond to I1 and I2 as shown in Figure 42. Recompile the code, load the code, and repeat the process as outlined in Section 3.2 to test this feature. With this feature implemented, under transients the phases are dropped and added quickly. The detailed results while transitioning from single phase to multiple phases are shown in Section 3.3.

3.2.5.2 Non-Linear Voltage Loop for Transient Reduction

The PFC stage control is composed of an inner current loop, which tries to follow the input voltage and an outer voltage loop that tries to maintain a constant DC bus voltage at the output. The voltage loop is thus in conflict with the current loop and hence must be designed to be very low bandwidth (approximately 10 Hz) to achieve good power factor. The slow voltage loop results in significant overshoot and undershoot under transients (see Figure 43).

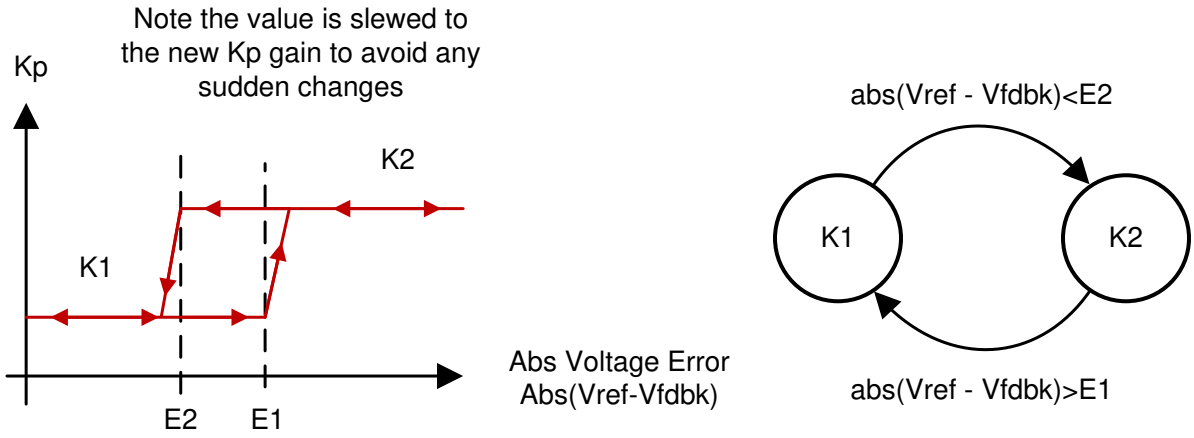


Figure 43. Non-Linear Voltage Loop With Hysteresis

To improve voltage overshoot and undershoot while maintaining good power factor, a non-linear voltage control loop is implemented as shown in Figure 44. A hysteresis band is added in the non-linear voltage loop to avoid oscillation between high-gain and low-gain mode. Furthermore, the gain change is slewed to avoid any sudden changes. Figure 45 shows the result with non-linear voltage loop.

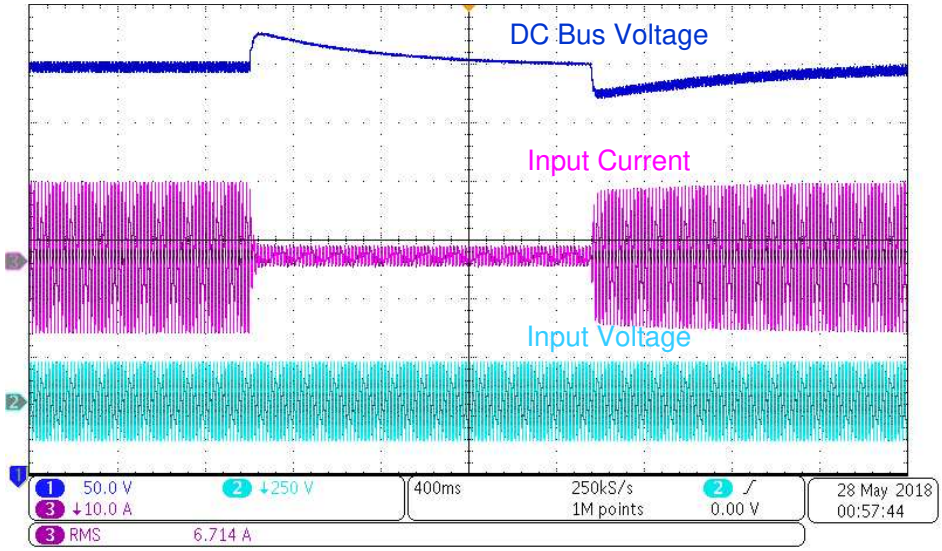


Figure 44. Voltage Transient Without Non-Linear Voltage Loop, V_{in} 120 V_{rms}, 1-kW to 100-W Transient, Overshoot 26 V

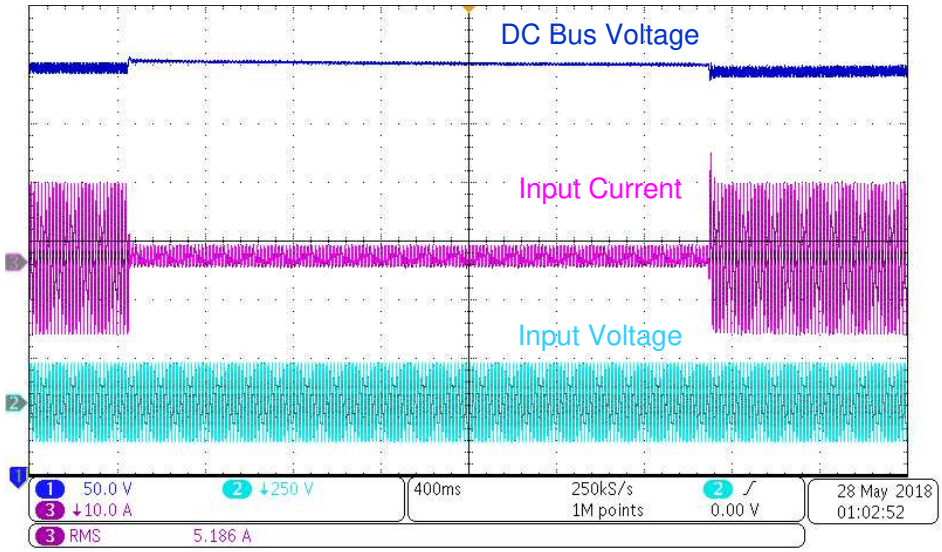


Figure 45. Voltage Transient With Non-Linear Voltage Loop, V_{in} 120 V_{rms}, 1-kW to 100-W Transient, Overshoot 10 V

To enable non-linear voltage loop, select the drop-down box under *Project Options* on the *CFG/powerSUITE* page of the solution. A default value of five times the gain is applied for the proportional term under transient condition. This value can be adjusted under the *user section* of the *<solution>-settings.h* file by modifying the *NON_LINEAR_V_LOOP_KP_MULTIPLIER* define. The project must be saved, re-compiled, and loaded on the controller when this option is changed. Hardware setup and software instructions for the Build Level 3 can be followed to see the behavior of the board under transients.

3.3 Testing and Results

3.3.1 Test Results at 120 V_{rms} Input

3.3.1.1 Startup

The startup waveform with single AC phase input of 120-V AC, 400-V DC Bus output is shown in Figure 46. The PFC is loaded with 1.6 kW.

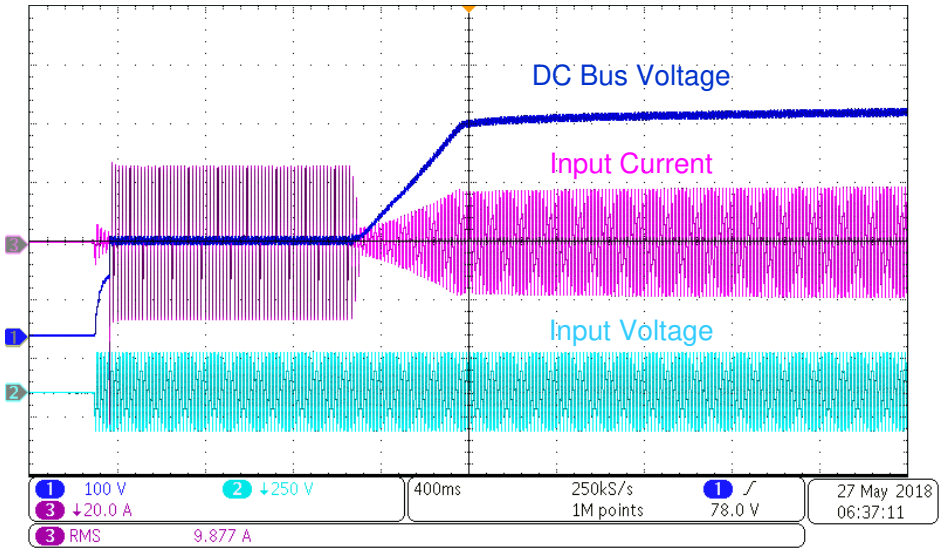


Figure 46. Startup at 120-V AC Input, 400-V DC Output and 1.6-kW Load

The startup waveform with single AC phase input of 120-V AC, 400-V DC Bus output is shown in Figure 47. The PFC is loaded with 3.3 kW.

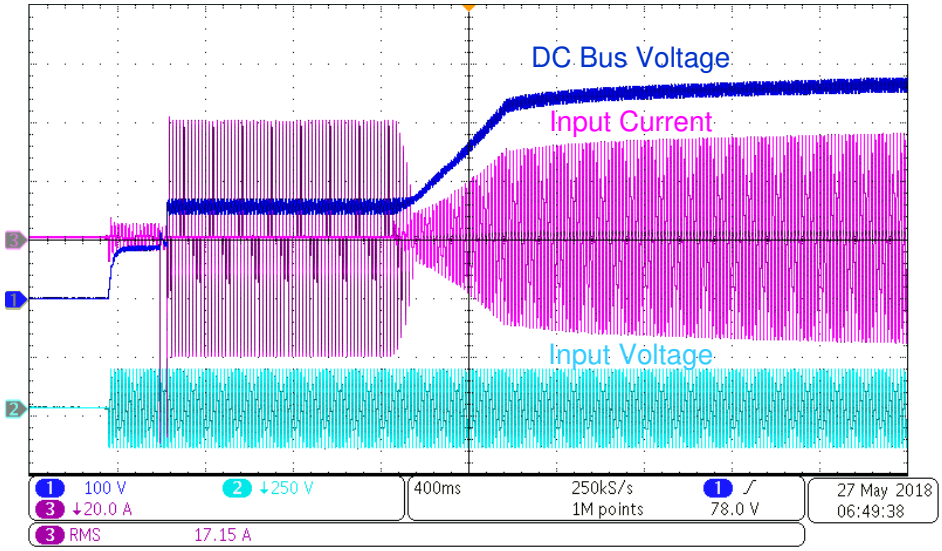


Figure 47. Startup at 120-V AC Input, 400-V DC Output and 3.3-kW Load

The startup waveform with 120-V AC, 400-V DC output, and with no load is shown in Figure 48.

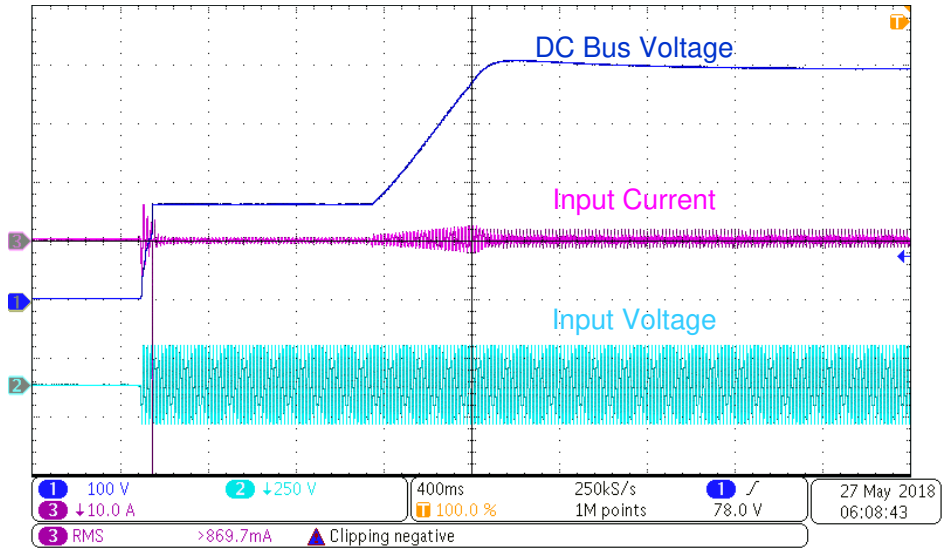


Figure 48. Startup at 120-V AC Input, 400-V DC Output and No Load

3.3.1.2 Steady State Condition

The stead state waveforms of TIDA-01604 at 120-V input with 330-W load, 1.65-kW load, 2.2-kW load, and 3.3-kW load are shown in Figure 49, Figure 50, Figure 51, and Figure 52 respectively.

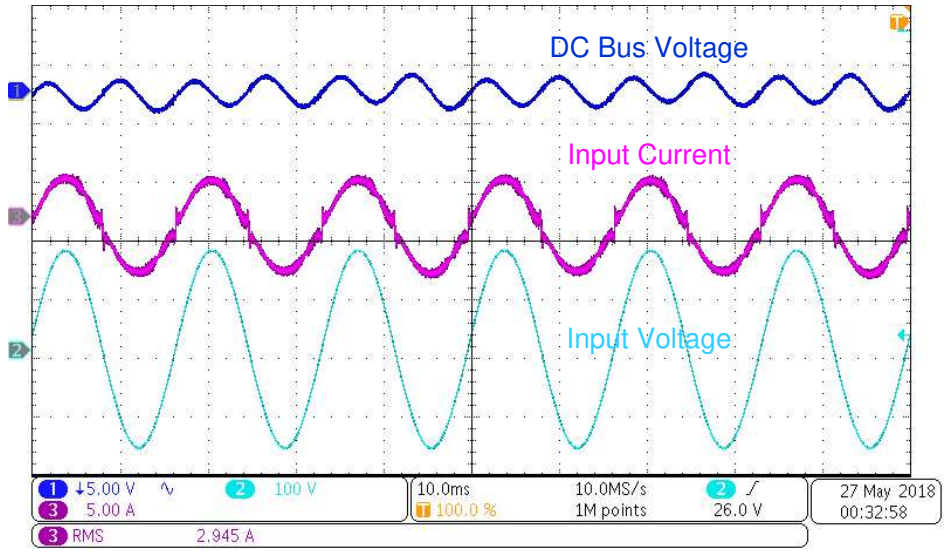


Figure 49. Steady State Waveforms at 120-V AC Input, 400-V DC Output and 330-W Load

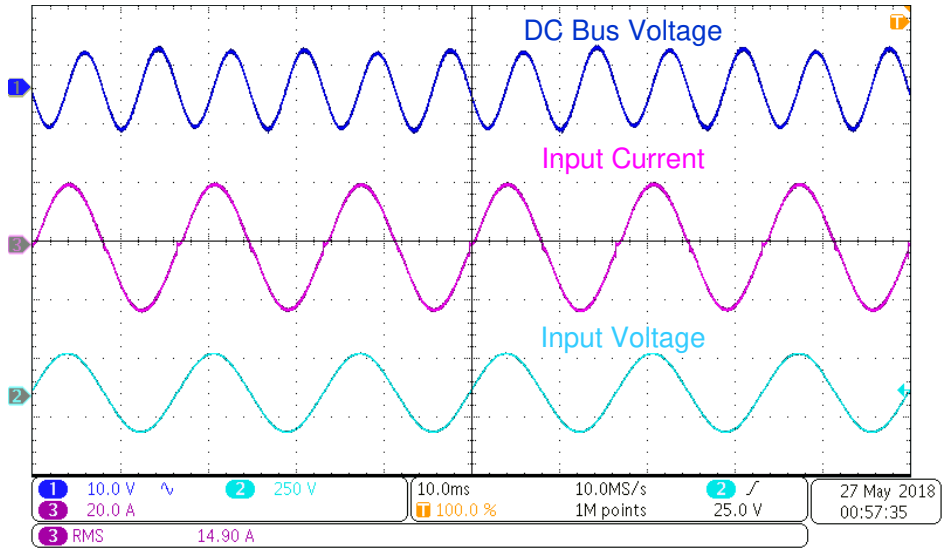


Figure 50. Steady State Waveforms at 120-V AC Input, 400-V DC Output and 1.65-kW Load

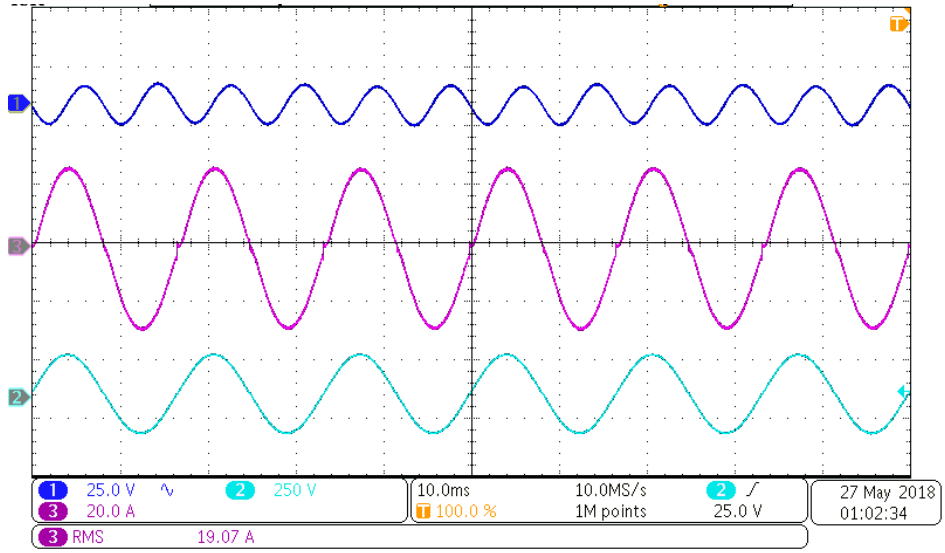


Figure 51. Steady State Waveforms at 120-V AC Input, 400-V DC Output and 2.2-kW Load

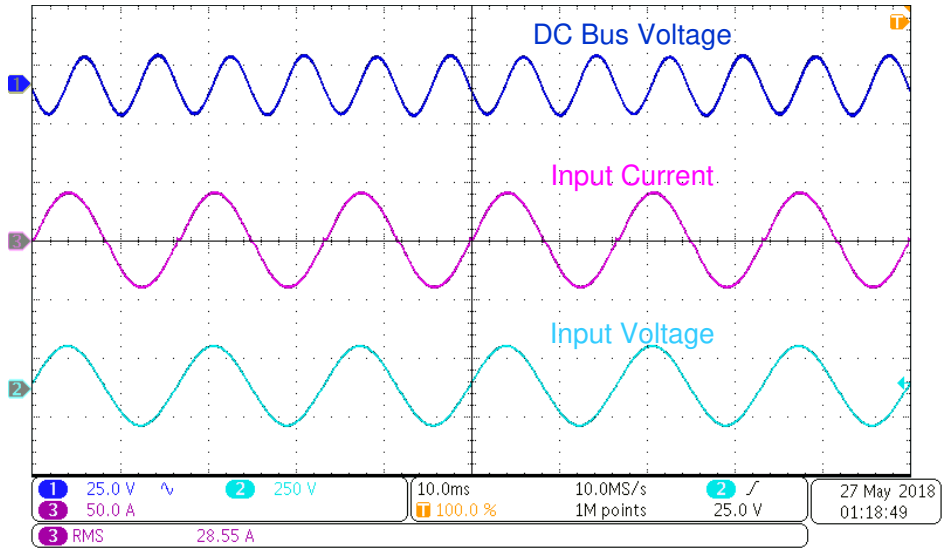


Figure 52. Steady State Waveforms at 120-V AC Input, 400-V DC Output and 3.3-kW Load

3.3.1.3 Detailed Results

Table 6 lists the detailed test results under varying load conditions with 120-Vac input and 400-Vdc output. Phase shedding is disabled. The efficiency is 97.30% at a 3.3-kW full load. The peak efficiency (97.77%) is achieved at approximately 50% load.

Table 6. Detailed Test Results With 120-V AC V_{in}, 400 V_{out}, and Different Power Levels

V_{in} (RMS)	V_{out} (RMS)	Pin (W)	I_{out} (A)	P_{out} (W)	Efficiency (%)	THD (%)	PF	% of Load
120.016	399.939	344.03	0.83395	333.45	96.33%	5.56%	0.99409	10%
119.973	399.929	474.52	1.14664	458.51	96.63%	4.58%	0.99585	14%
119.921	399.945	637.46	1.54467	617.74	96.91%	4.14%	0.99673	19%
119.875	399.94	786.26	1.191124	786.26	97.21%	3.75%	0.99741	24%
119.834	399.949	926.69	2.25745	902.83	97.43%	3.37%	0.99788	27%
119.803	399.92	1029.77	2.5113	1004.29	97.53%	3.15%	0.99811	30%
119.741	399.954	1230.32	3.00455	1201.65	97.67%	2.81%	0.99844	36%
119.71	399.959	1329.84	3.24868	1299.31	97.70%	2.67%	0.99854	39%
119.697	399.945	1542.24	3.76969	1507.65	97.76%	2.44%	0.99874	46%
119.651	400	1685.99	4.1212	1648.46	97.77%	2.31%	0.99882	50%
119.597	399.996	1858.37	4.54231	1816.88	97.77%	2.18%	0.99892	55%
119.587	400.04	2044.41	4.9952	1998.26	97.74%	2.06%	0.99898	61%
119.502	400.115	2274.05	5.5522	2221.51	97.69%	1.95%	0.99905	67%
119.487	400.124	2482.69	6.058	2423.94	97.63%	1.85%	0.99911	73%
119.426	400.143	2687.83	6.5536	2622.33	97.56%	1.77%	0.99915	79%
119.421	400.205	2879.44	7.0157	2807.69	97.51%	1.70%	0.99917	85%
119.362	400.224	3098.64	7.5424	3018.63	97.42%	1.63%	0.99921	91%
119.28	400.303	3392.64	8.2461	3300.87	97.30%	1.56%	0.99924	100%

3.3.1.4 Load Transient Test

Figure 53 shows the transient response when input is 120 V_{rms} and a load step change from 100 W to 1.6 kW.

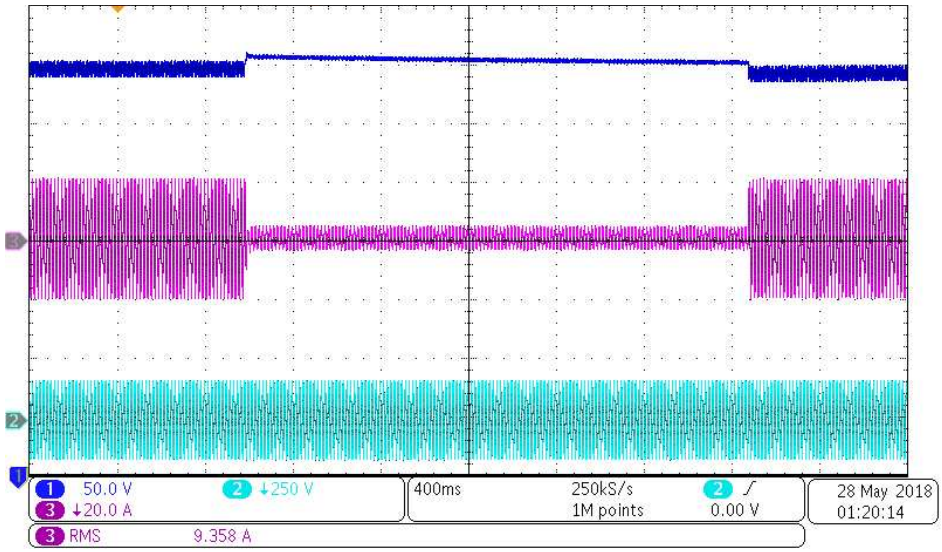


Figure 53. Load Transient Response From 100-W to 1.6-kW Step With 120-V AC Input

Figure 54 shows the transient response when input is 120 V_{rms} and a load step change from 1.6 kW to 2.2 kW.

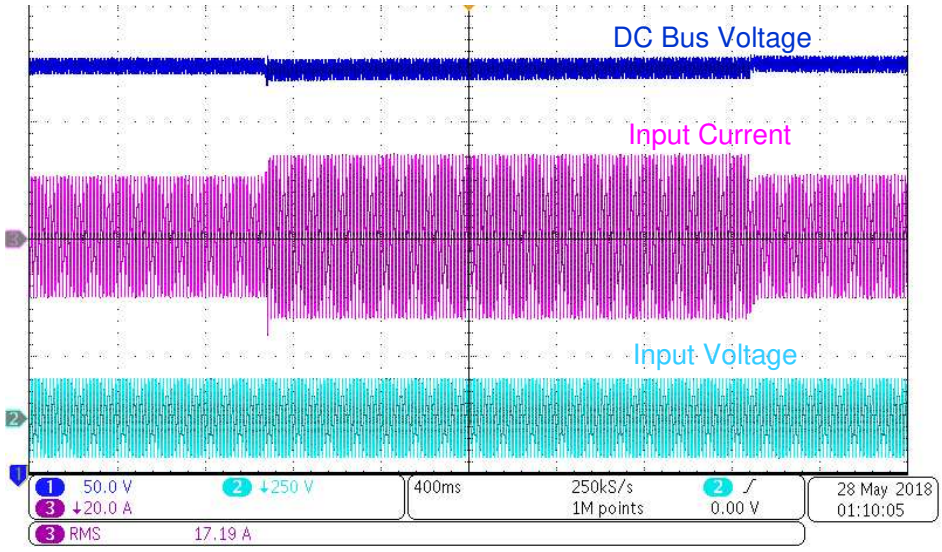


Figure 54. Load Transient Response From 1.6-kW to 2.2-kW Step With 120-V AC Input

Figure 55 shows the transient response when input is 120 V_{rms} and a load step change from 1.6 kW to 3.3 kW.

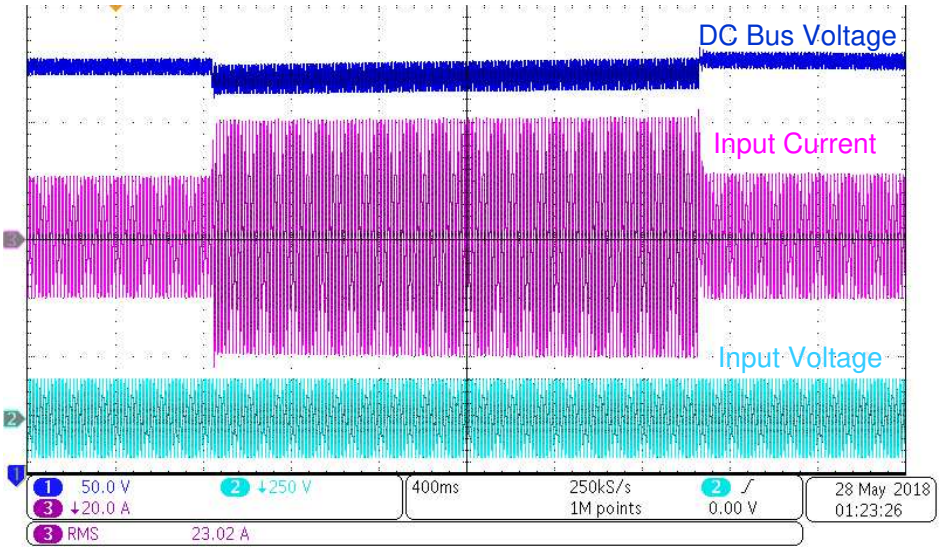


Figure 55. Load Transient Response From 1.6-kW to 3.3-kW Step With 120-V AC Input

3.3.1.5 Phase Shedding Test

The input RMS current is detected for transitioning from three-phase to dual-phase and single-phase operations. Figure 56 shows when PFC runs from 1 phase to dual phases. The load step changes from 320 W to 1 kW.

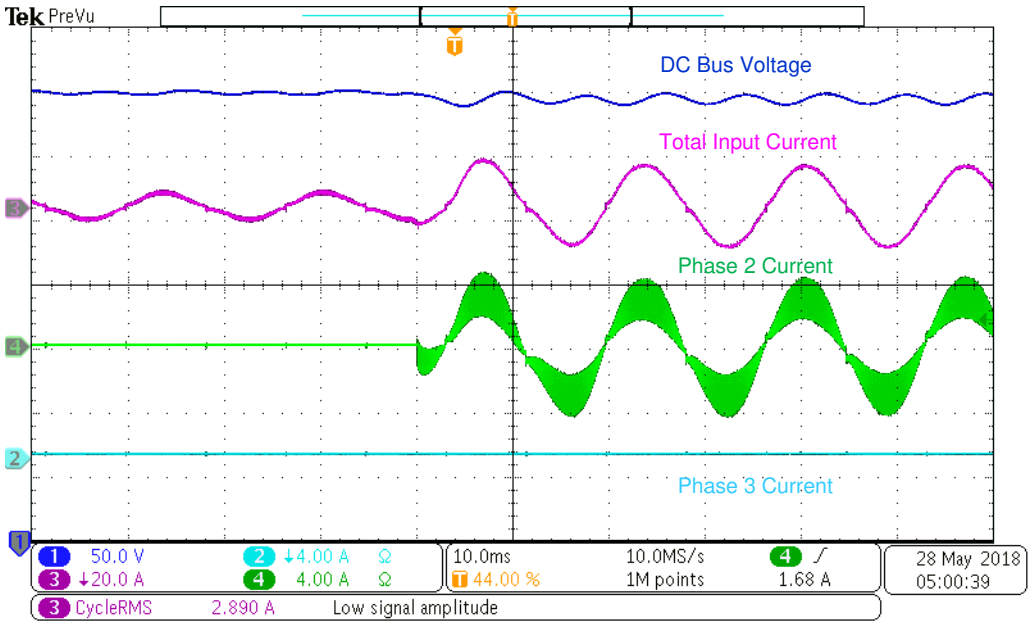


Figure 56. Phase Added Transition From Single Phase to Dual Phases, Load Step From 320 W to 1 kW

Figure 57 shows when the PFC runs from 1 phase to 3 phases. The load step changes from 320 W to 1.8 kW.

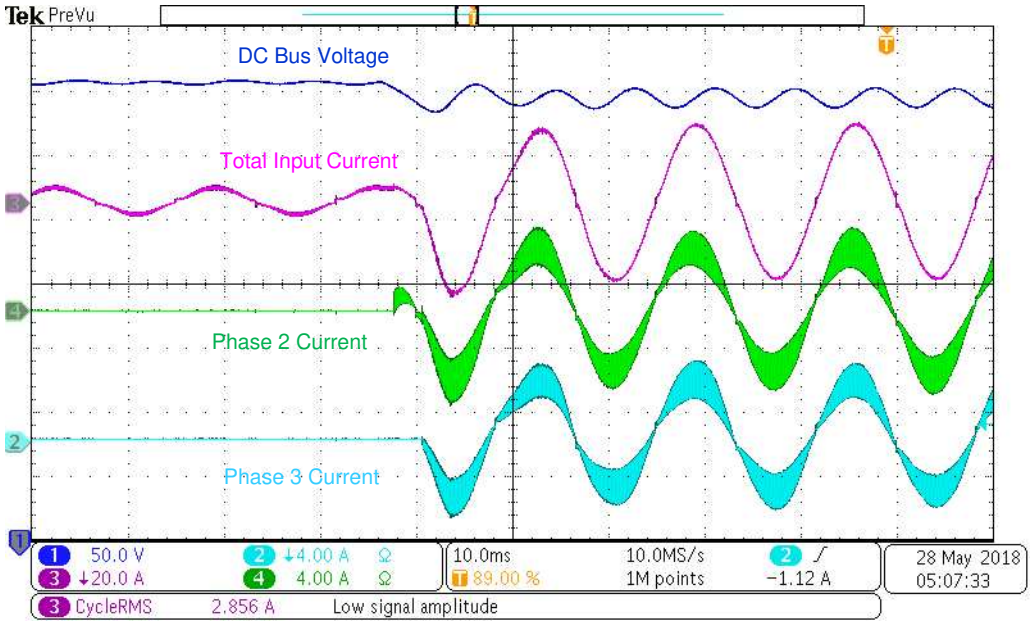


Figure 57. Phase Added Transition From Single Phase to Three Phases, Load Step From 320 W to 1.8 kW

Figure 58 shows when PFC runs from dual phases to 3 phases. The load step changes from 720 W to 1.8 kW.

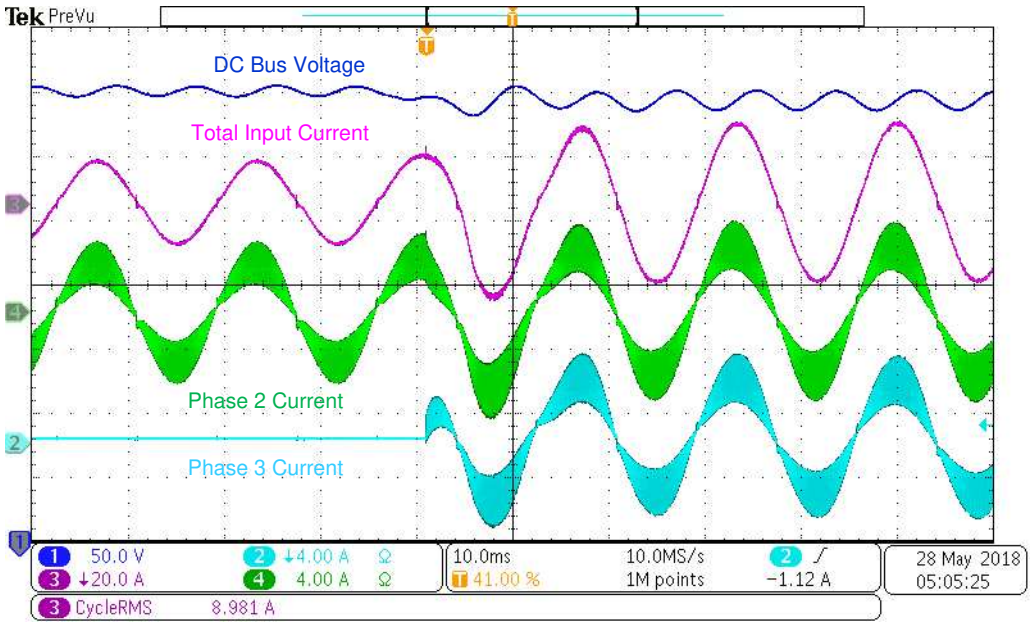


Figure 58. Phase Added Transition From Dual Phases to Three Phases, Load Step From 720 W to 1.8 kW

Comparison of the efficiency curves with and without phase shedding is shown in Figure 59. 1% efficiency improvement has been achieved.

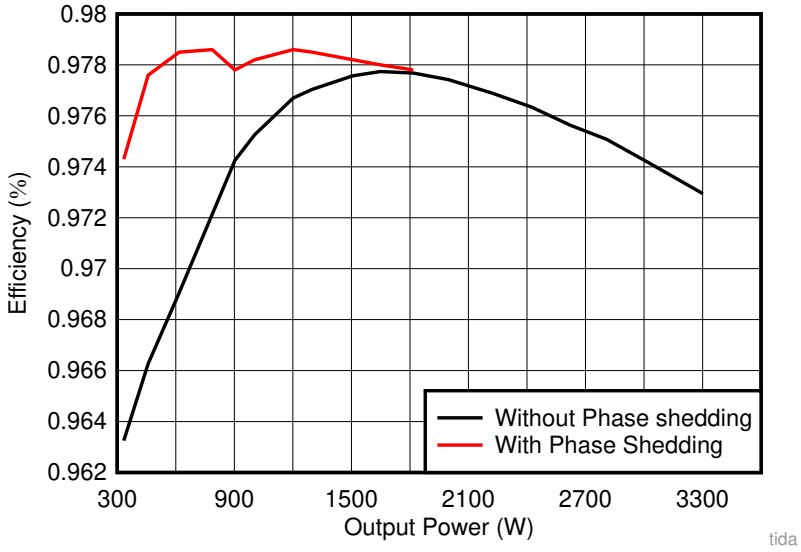


Figure 59. Efficiency Comparison at 120-V Input With and Without Phase Shedding

3.3.2 Test Results at 240 V_{rms} Input

3.3.2.1 Startup

The startup waveform with single AC phase input of 240-V AC, 400-V DC Bus output is shown in Figure 60. The PFC is loaded with 1.6 kW.

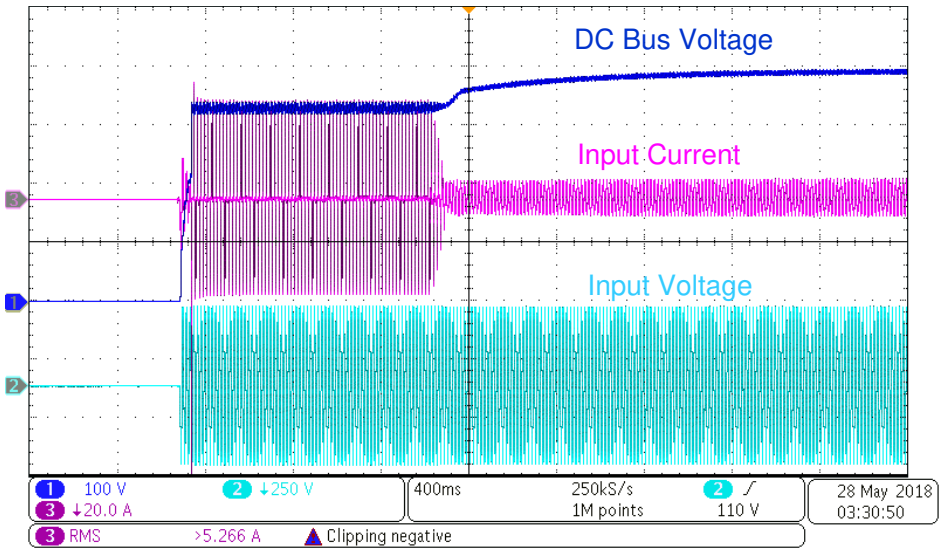


Figure 60. Startup at 240-V AC Input, 400-V DC Output and 1.6-kW Load

The startup waveform with 240-V AC, 400-V DC output, and with no load is shown in Figure 61.

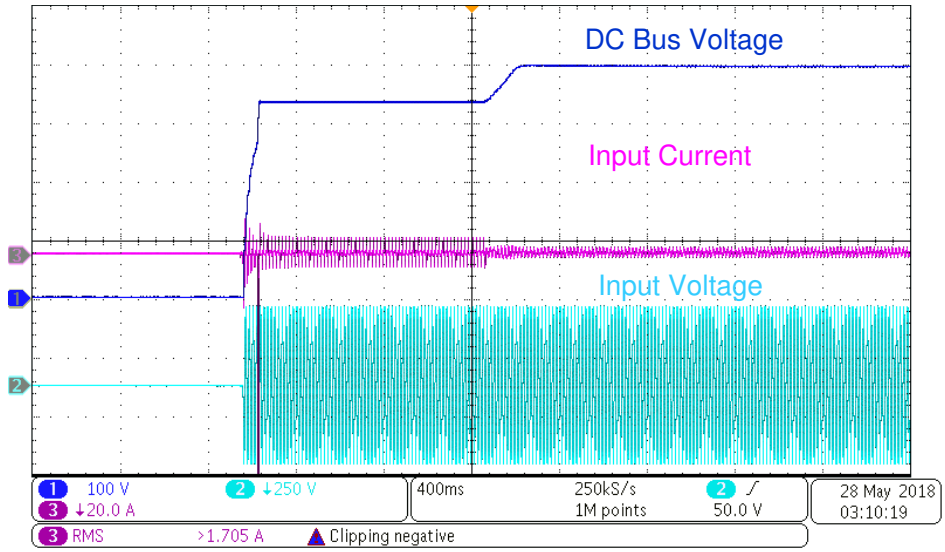


Figure 61. Startup at 240-V AC Input, 400-V DC Output and No Load

3.3.2.2 Steady State Condition

The steady state waveforms of TIDA-01604 at 240-V input with 2.6 kW load, 3.3 kW load, 4.8 kW load and 6.6 kW load are shown in Figure 62, Figure 63, Figure 64, and Figure 65 respectively.

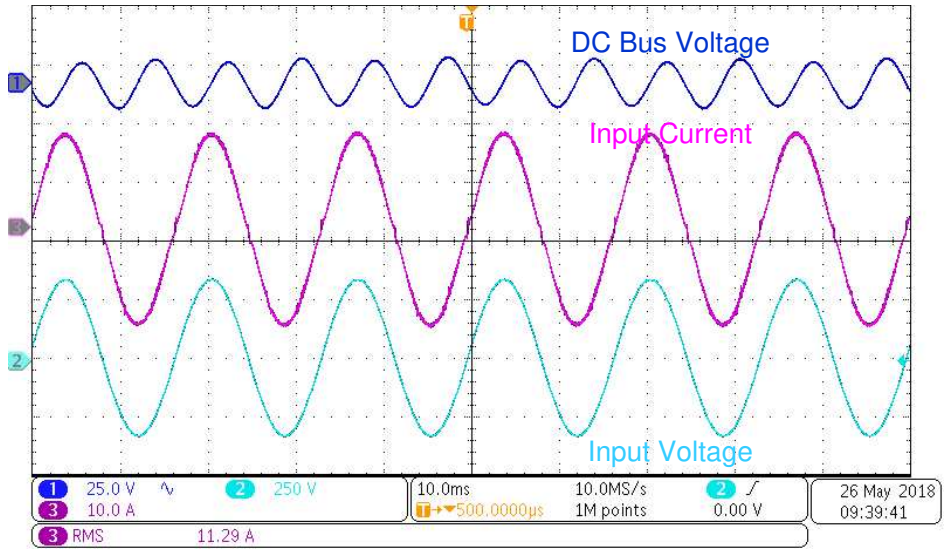


Figure 62. Steady State Waveforms at 240-V AC Input, 400-V DC Output and 2.6-kW Load

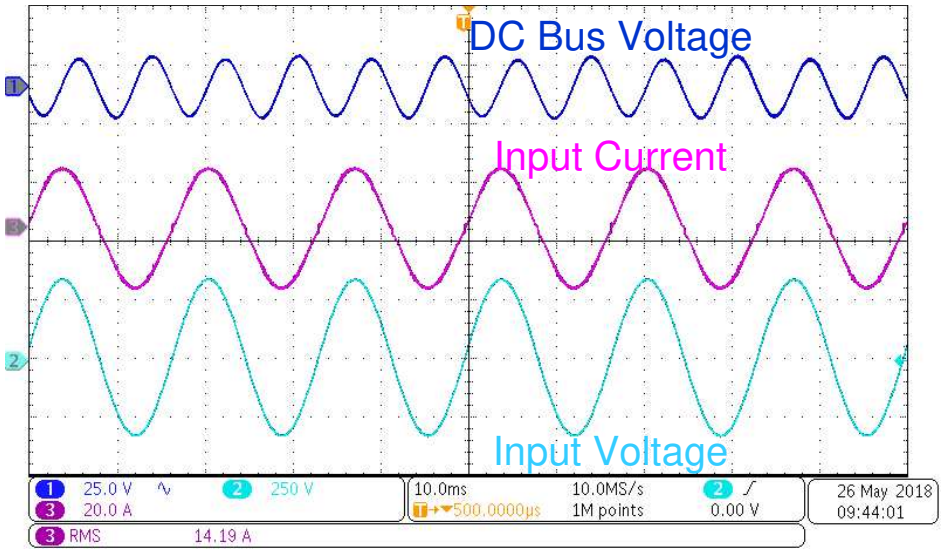


Figure 63. Steady State Waveforms at 240-V AC Input, 400-V DC Output and 3.3-kW Load

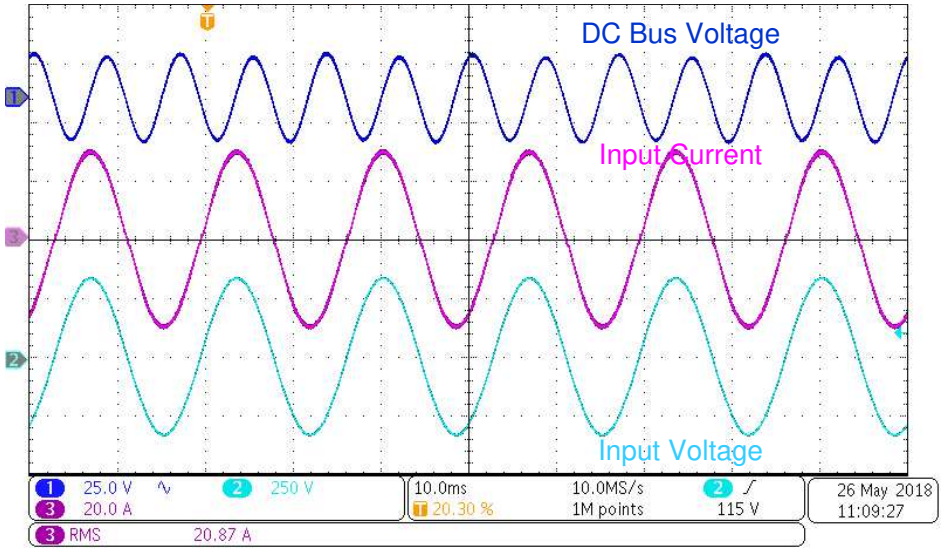


Figure 64. Steady State Waveforms at 240-V AC Input, 400-V DC Output and 4.8-kW Load

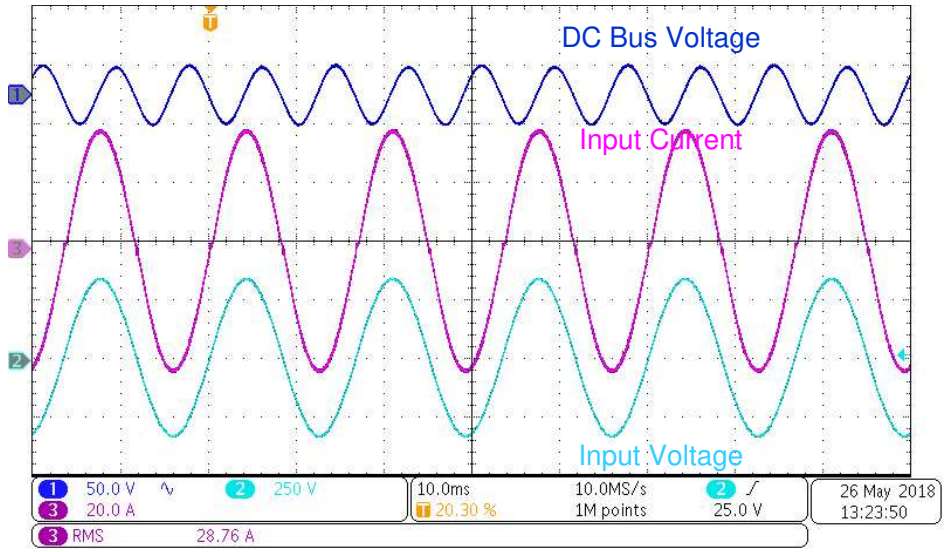


Figure 65. Steady State Waveforms at 240-V AC Input, 400-V DC Output and 6.6-kW Load

3.3.2.3 Detailed Results

Table 7 lists the detailed test results under varying load conditions with 240-V AC input and 400-V DC output. Phase shedding is disabled. The efficiency is 98.6% at a 6.6-kW full load. The peak efficiency (98.86%) is achieved at approximately 50% load.

Table 7. Detailed Test Results With 240-V AC V_{in}, 400 V_{out}, and Different Power Levels

V_{in} (RMS)	V_{out} (RMS)	P_{in} (W)	I_{out} (A)	P_{out} (W)	Efficiency (%)	THD (%)	PF	% of Load
240.135	399.883	678.4	1.667	666.53	98.25%	12.39%	0.98027	10%
240.1	399.891	911.72	2.24469	897.6	98.45%	7.30%	0.99166	14%
240.054	399.893	1218.2	3	1201.26	98.61%	4.06%	0.99654	18%
240.009	399.889	1527.16	3.769	1507.27	98.70%	3.28%	0.99802	23%
239.963	399.891	1838.54	4.54	1815.77	98.76%	3.12%	0.99859	28%
239.931	399.888	2046.12	5.05517	2021.48	98.80%	3.06%	0.99879	31%
239.87	399.938	2450.23	6.0549	2421.54	98.83%	2.91%	0.99904	37%
238.8	400.14	2653	6.55	2622	98.81%	2.79%	0.999	40%
239.783	399.984	3050.23	7.5389	3015.39	98.86%	2.62%	0.99922	46%
239.742	400.023	3334.45	8.2406	3296.7	98.86%	2.51%	0.99925	50%
239.695	400.042	3650.99	9.022	3609.11	98.85%	2.41%	0.9993	55%
239.64	400.113	4045.92	9.994	3998.65	98.83%	2.21%	0.99933	61%
239.581	400.142	4459.01	11.0116	4406.1	98.81%	2.10%	0.99936	67%
239.575	400.228	4850.39	11.9711	4791	98.78%	1.99%	0.99939	73%
239.514	400.309	5279.9	13.02	5213.2	98.74%	1.89%	0.99942	79%
239.8	400	5675	14	5602	98.71%	1.73%	0.999	85%
239.986	400.04	6087.7	15.01	6005.1	98.68%	1.70%	0.99966	91%
240.081	399.929	6694.9	16.5059	6601	98.60%	1.59%	0.99967	100%

3.3.2.4 Load Transient Test

Figure 66 shows the transient response when input is 240 V_{rms} and a load step change from 1.6 kW to 3.3 kW.

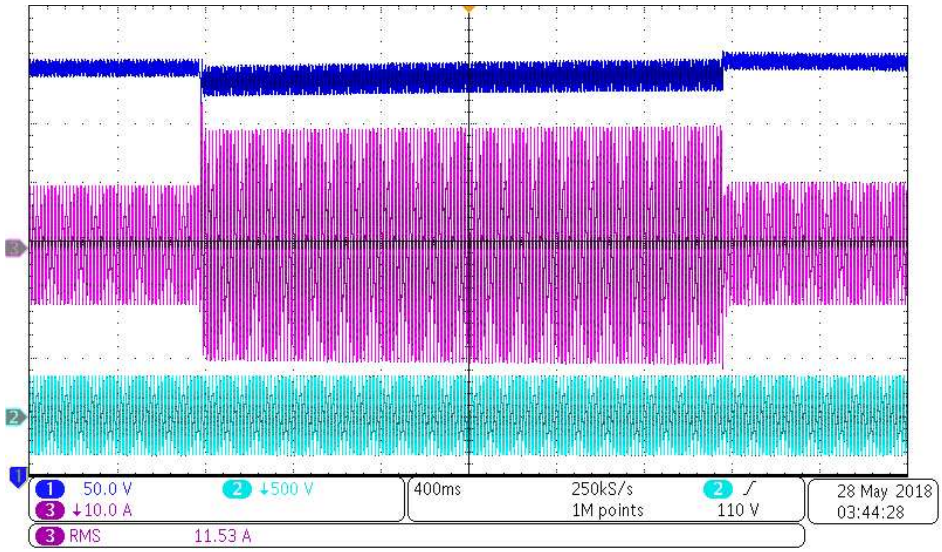


Figure 66. Load Transient Response From 1.6-kW to 3.3-kW Step With 240-V AC Input

Figure 67 shows the transient response when input is 240 V_{rms} and a load step change from 300 W to 3.3 kW.

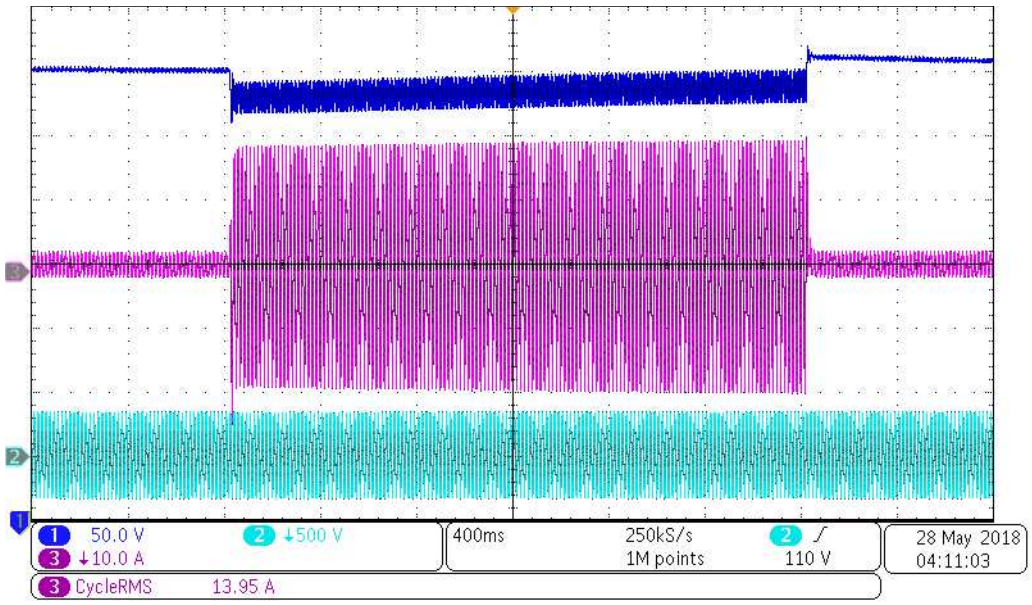


Figure 67. Load Transient Response From 300-W to 3.3-kW Step With 240-V AC Input

Figure 68 shows the transient response when input is 240 V_{rms} and a load step change from 3.3 kW to 5.5 kW.

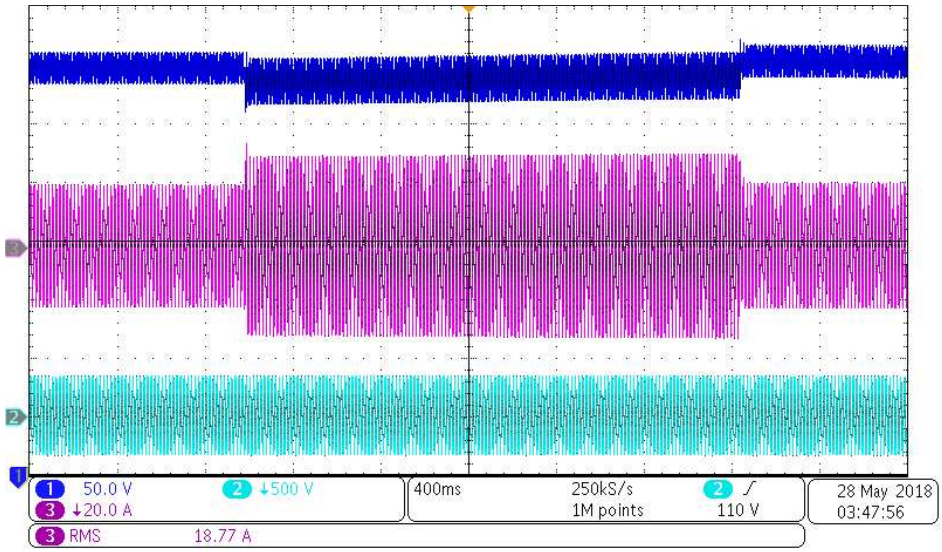


Figure 68. Load Transient Response From 3.3-kW to 5.5-kW Step With 240-V AC Input

3.3.2.5 Phase Shedding Test

Comparison of the efficiency curves with and without phase shedding at 240-V AC input is shown in Figure 69.

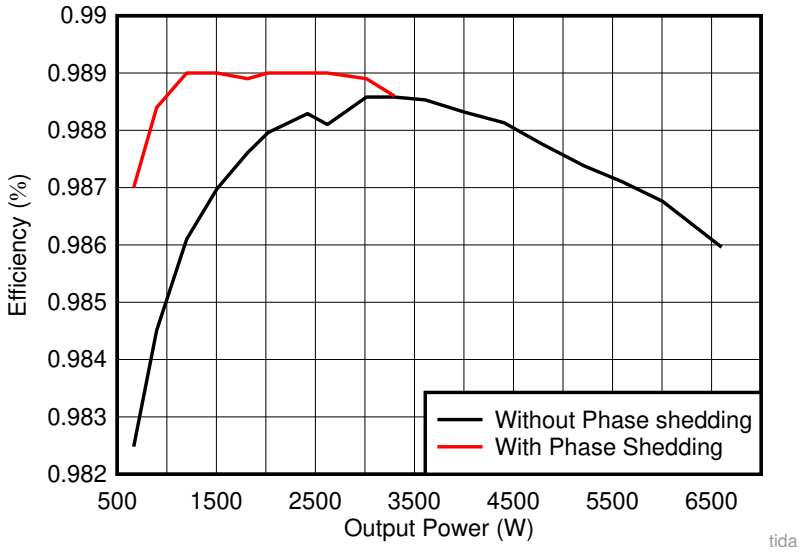


Figure 69. Efficiency Comparison at 240-V Input With and Without Phase Shedding

3.3.3 Result Comparison in Graphs

Figure 70 shows the efficiency comparison at varying load conditions with 120-V and 240-V AC inputs.

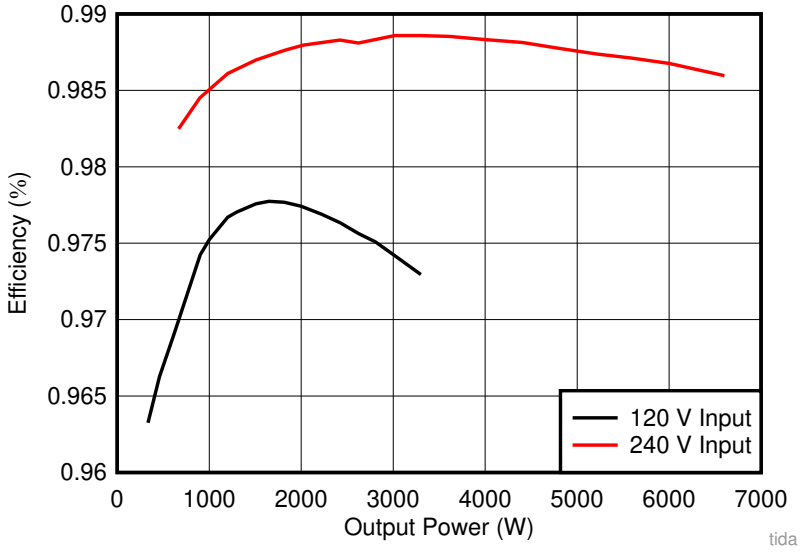


Figure 70. Efficiency Comparison at 120-V and 240-V Input With Varying Load Conditions

Figure 71 shows the power factor comparison at various load conditions with 120-V and 240-V AC inputs.

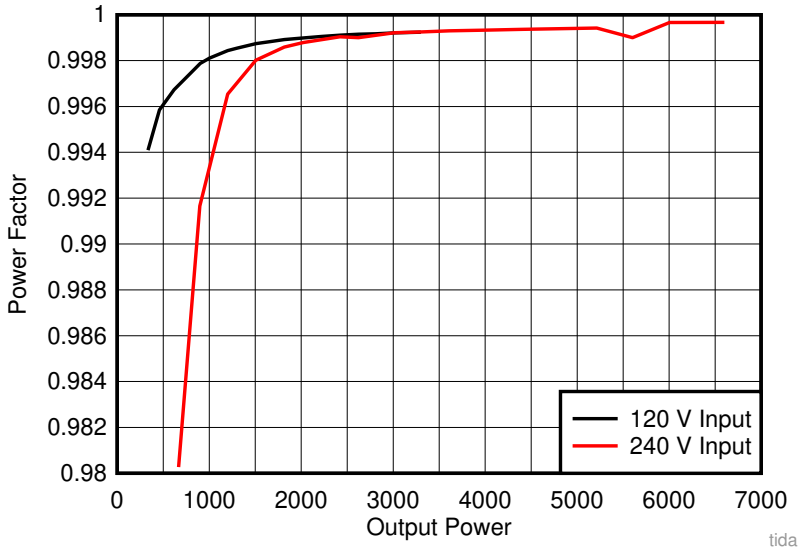


Figure 71. PF Comparison at 120-V and 240-V Input With Varying Load Conditions

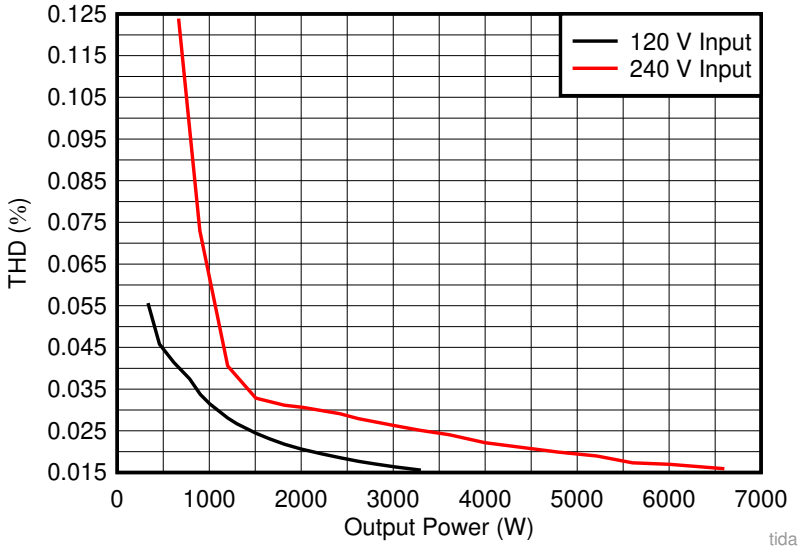


Figure 72. THD Comparison at 120-V and 240-V Input With Varying Load Conditions

3.3.4 Thermal Image

Figure 73 and Figure 74 show the thermal image of the design board running at 120-V input and under 3.3 kW load. The images are taken after the circuit is running at room temperature for 30 minutes.

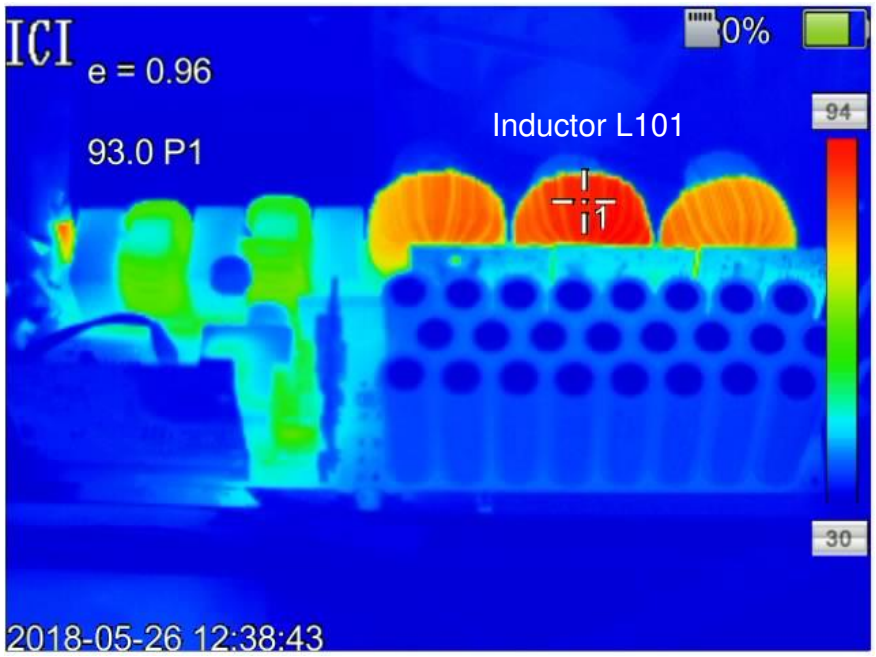


Figure 73. Thermal Image of the TIDA-01604 at 120-V AC Input With 3.3-kW Load (Focus on the Inductor)

Figure 74. Thermal Image of the TIDA-01604 at 120-V AC Input With 3.3-kW Load (Focus on the Hall Sensor)

Figure 75 shows the thermal image of the design board running at 240-V input and with 3.3 kW load. The image is taken after the circuit is running at room temperature for 30 minutes.

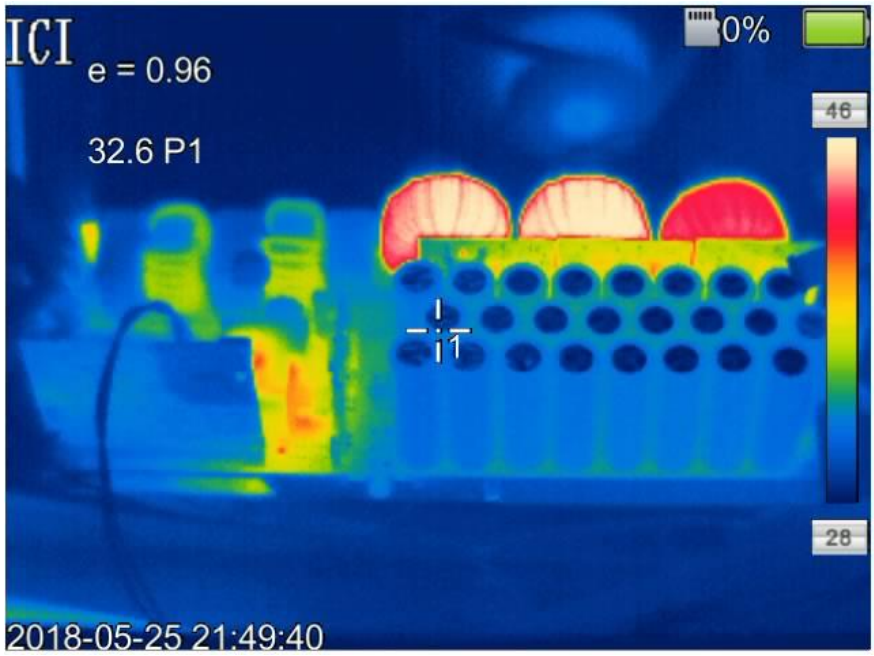


Figure 75. Thermal Image of the TIDA-01604 at 240-V AC Input With 3.3-kW Load

Figure 76 shows the thermal image of the design board running at 240-V input and with 6.6 kW load. The image is taken after the circuit is running at room temperature for 30 minutes.

Figure 76. Thermal Image of the TIDA-01604 at 240-V AC Input With 6.6-kW Load

4 Design Files

4.1 Schematics

To download the schematics, see the design files at TIDA-01604.

4.2 Bill of Materials

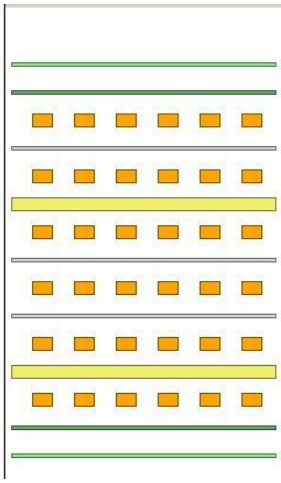
To download the bill of materials (BOM), see the design files at TIDA-01604.

4.3 PCB Layout Recommendations

4.3.1 Layout Prints

To download the layer plots, see the design files at TIDA-01604.

TIDA-01604 implements a six-layer PCB. Figure 77 shows the board material, copper thickness, and the dielectric distance between the layers.



Layer Name	Type	Material	Thickness (mm)	Dielectric Material	Dielectric Constant	Pullback (mm)	Orientation	Coverlay Expansion
Top Overlay	Overlay							
Top Solder	Solder Mask...	Surface Mat...	0.01016	Solder Resist	3.5			0
Top Layer	Signal	Copper	0.07112				Top	
Dielectric1	Dielectric	Prepreg	0.1778		4.2			
Signal Layer 1	Signal	Copper	0.07112				Not Allowed	
Dielectric 3	Dielectric	Core	0.3556	FR-4	4.2			
Signal Layer 2	Signal	Copper	0.07112				Not Allowed	
Dielectric 2	Dielectric	Prepreg	0.1778		4.2			
Signal Layer 3	Signal	Copper	0.07112				Not Allowed	
Dielectric 4	Dielectric	Prepreg	0.1778		4.2			
Signal Layer 4	Signal	Copper	0.07112				Not Allowed	
Dielectric 5	Dielectric	Core	0.3556	FR-4	4.2			
Bottom Layer	Signal	Copper	0.07112				Bottom	
Bottom Solder	Solder Mask...	Surface Mat...	0.01016	Solder Resist	3.5			0
Bottom Over...	Overlay							

Figure 77. Layer Stack of TIDA-01604

4.4 Altium Project

To download the Altium project files, see the design files at TIDA-01604.

4.5 Gerber Files

To download the Gerber files, see the design files at TIDA-01604.

4.6 Assembly Drawings

To download the assembly drawings, see the design files at TIDA-01604.

5 Related Documentation

1. Joel Turchi, J.T., Dhaval Dalal, D.D., Patrick Wang, P.T., and Laurent Lenck, L.L. (2014). *Power Factor Correction (PFC) Handbook: Choosing the Right Power Factor Controller Solution*. Revision 5, http://www.onsemi.com/pub/Collateral/HBD853-D.PDF
2. Texas Instruments, *Automotive, Dual-Channel SiC MOSFET Gate Driver Reference Design With Two-Level Turnoff Protection*
3. Texas Instruments, *Control challenges in a totem-pole PFC* Technical Brief

5.1 Trademarks

6 Terminology

ADC— Analog-to-digital converter

AEC— Automotive Electronics Council

AFE— Analog front end

BOM— Bill of materials

CCM— Continuous conduction mode

CM— Common mode

CMTI— Common-mode transient immunity

CPU— Central processing unit

DCM— Discontinuous conduction mode

DM— Differential mode

EMC— Electromagnetic compatibility

EMI— Electromagnetic interference

ESR— Equivalent series resistance

EV— Electric vehicle

HEV— Hybrid-electric vehicle

IGBT— Insulated-gate bipolar transistor

MOSFET— Metal-oxide-semiconductor-field-effect transistor

OBC— Onboard charger

PCB— Printed-circuit board

PFC— Power factor correction

PHEV— Plug-in hybrid-electric vehicle

PSR— Primary side regulation

RMS— Root mean square

UVLO— Undervoltage lockout

7 About the Author

XUN GONG is an Automotive Systems Engineer at Texas Instruments, where he is responsible for developing reference design solutions in Automotive HEV/EV Power Train. Xun brings to this role expertise in the field of IGBT and SiC (Silicon Carbide) isolated gate drivers, traction inverters, high voltage and high power DC-DC converters. Xun achieved his Ph.D. in Electrical Engineering from Delft University of Technology in Delft, Netherlands. Xun Gong won the 1st prize Award of the Academic Journal *IEEE Transactions on Power Electronics* in 2014.

GANGYAO WANG is a SiC System Architect with High Voltage Power Solutions Group at Texas Instruments, where he is responsible for defining high power gate drivers and developing references design solutions for all kinds of applications using SiC MOSFET. Before join TI in 2017, Gangyao has been worked on SiC power device characterization and application. Gangyao has received has Ph.D. in Electrical Engineering from North Carolina State University in 2013 and he has published more than 40 technical papers in international journals and conference proceedings.

Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from A Revision (August 2018) to B Revision **Page**

- Made additions and deletions to the Opening Project Inside CCS section including the *Code Composer Studio* version. 23
- Changed instructions for opening the reference design software. 23
- Changed step 5 of the *Solution Adapter Tool* changes. 24
- Changed Figure 19 to accommodate the PowerSuite update. 24
- Changed Figure 20 to accommodate the PowerSuite update. 25
- Made updates to the section following Figure 21, Project Structure Overview. 26
- Added **NOTE:** to the *Running Code on CLA* section. 45

Changes from Original (March 2018) to A Revision **Page**

- Changed design title from *98.5% Efficiency, 6.6-kW Totem-Pole PFC Reference Design for HEV/EV Onboard Charger* to *98.6% Efficiency, 6.6-kW Totem-Pole PFC Reference Design for HEV/EV Onboard Charger* 1
- Changed Description 1
- Changed peak efficiency from 98.46% to 98.60% in Features 1
- Added resource links to the UCC21520-Q1, TMS320F280049, and C2000WARE-DIGITALPOWER-SDK product folders 1
- Deleted resource links to the SN74LVC1G3157, TLV71333-Q1, and OPA2376-Q1 product folders 1
- Added Warnings to Section 1, *System Description* 2
- Changed Input specifications for power line harmonics in Table 2, *TIDA-01604 Key System Specifications* 6
- Changed Output specifications for peak efficiency in Table 2, *TIDA-01604 Key System Specifications* 6
- Changed device name from ASN6501-Q1 to SN6501-Q1 in Section 2.1, *Block Diagram* 7
- Added Figure 5, *Functional Block Diagram of UCC21520-Q1* 8
- Added Section 2.2.3, *SN6501-Q1* 8
- Added Section 2.2.4, *ISO7731-Q1* 8
- Added Section 2.2.5, *LMV762Q-Q1* 9
- Added Section 2.2.6, *TPS7B6950-Q1* 9
- Added Section 2.2.7, *TL431-Q1* 9
- Added Section 2.2.8, *TLV71333-Q1* 9
- Added Section 2.2.9, *OPA2376-Q1* 9
- Changed device name from TMS320F280049M to TMS320F280049 in Section 2.2.10, *C2000™ MCU F28004x* 9
- Added Section 2.3.1, *PWM* 9
- Added Section 2.3.2, *Current Loop Model* 10
- Changed Figure 7, *Current Loop Control Model* 11
- Added Section 2.3.3, *DC Bus Regulation Loop* 11

- Changed Figure 8, *DC Voltage Loop Control Model* 12
- Added Section 2.3.4, *Soft Start Around Zero-Crossing for Eliminate or Reduce Current Spike* 12
- Added Section 2.3.6, *Inductor Calculation* 13
- Deleted *PLECS® Simulation Circuit* image from Section 2.3.9, *Three-Phase-Interleaved, High-Frequency Bridge Legs* 14
- Added Section 2.3.10, *Auxiliary Power Supply Design* 15
- Added Figure 12 to Section 2.3.11, *Current and Voltage Sense* 18
- Added Equation 28 to Section 2.3.11, *Current and Voltage Sense* 18
- Added information regarding output voltage to Section 2.3.11, *Current and Voltage Sense* 18
- Changed Figure 13 caption from *Schematic of AC Hall Effect Sensor* to *Schematic of Current Sensing* 19
- Added information regarding RC filters to Section 2.3.11, *Current and Voltage Sense* 19
- Added information regarding the measurement setup diagram to Section 3.1, *Hardware* 22
- Added Section 3.1.1, *Control Card Settings* 22
- Added Section 3.2, *Software* 23
- Added Section 3.3.1, *Test Results at 120 Vrms Input* 50
- Added Section 3.3.2, *Test Results at 240 Vrms Input* 57
- Added Section 3.3.3, *Result Comparison in Graphs* 62
- Added Section 3.3.4, *Thermal Image* 65
- Changed Section 7, *About the Author* 69

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